

IGLOO PLUS Low Power Flash FPGAs

with Flash*Freeze Technology

Features and Benefits

Low Power

- 1.2 V to 1.5 V Core Voltage Support for Low Power
- Supports Single-Voltage System Operation
- 5 μW Power Consumption in Flash*Freeze Mode
- Low Power Active FPGA Operation
- Flash*Freeze Technology Enables Ult Consumption while Maintaining FPGA Content Ultra-Low Power
- Configurable Hold Previous State, Tristate, HIGH, or LOW State per I/Ŏ in Flash*Freeze Mode
- Easy Entry To / Exit From Ultra-Low Power Flash*Freeze Mode

Feature Rich

- 30 k to 125 k System Gates
- Up to 36 kbits of True Dual-Port SRAM
- Up to 212 User I/Os

Reprogrammable Flash Technology

- 130-nm, 7-Layer Metal, Flash-Based CMOS Process
- Instant On Level 0 Support
- Single-Chip Solution
- Retains Programmed Design When Powered Off
- 250 MHz (1.5 V systems) and 160 MHz (1.2 V systems) System Performance

In-System Programming (ISP) and Security

- ISP Using On-Chip 128-Bit Advanced Encryption Standard (AES) Decryption via JTAG (IEEE 1532–compliant) FlashLock® Designed to Secure FPGA Contents

High-Performance Routing Hierarchy

Segmented, Hierarchical Routing and Clock Structure

Advanced I/O

- 1.2 V, 1.5 V, 1.8 V, 2.5 V, and 3.3 V Mixed-Voltage Operation
- Bank-Selectable I/O Voltages-4 Banks per Chip on All IGLOO® PLUS Devices
- Single-Ended **LVCMOS** I/O Standards: LVTTL. 3.3 V / 2.5 V / 1.8 V / 1.5 V / 1.2 V
- Selectable Schmitt Trigger Inputs
 Wide Range Power Supply Voltage Support per JESD8-B,
 Allowing I/Os to Operate from 2.7 V to 3.6 V
- Wide Range Power Supply Voltage Support per JESD8-12, Allowing I/Os to Operate from 1.14 V to 1.575 V
- I/O Registers on Input, Output, and Enable Paths
- Hot-Swappable and Cold-Sparing I/Os
- Programmable Output Slew Rate and Drive Strength
- Weak Pull-Up/-Down
- IEEE 1149.1 (JTAG) Boundary Scan Test
- Pin-Compatible Small-Footprint Packages across the IGLOO PLUS Family

Clock Conditioning Circuit (CCC) and PLL[†]

- Six CCC Blocks, One with an Integrated PLL
- Configurable Phase Shift, Multiply/Divide, Delay Capabilities, and External Feedback
- Wide Input Frequency Range (1.5 MHz up to 250 MHz)

Embedded Memory

- 1 kbit of FlashROM User Nonvolatile Memory
- SRAMs and FIFOs with Variable-Aspect-Ratio 4,608-Bit RAM Blocks (×1, ×2, ×4, ×9, and ×18 organizations)
- True Dual-Port SRAM (except ×18)

IGLOO PLUS Devices	AGLP030	AGLP060	AGLP125
System Gates	30,000	60,000	125,000
Typical Equivalent Macrocells	256	512	1,024
VersaTiles (D-flip-flops)	792	1,584	3,120
Flash*Freeze Mode (typical, μW)	5	10	16
RAM Kbits (1,024 bits)	-	18	36
4,608-Bit Blocks	-	4	8
Secure (AES) ISP	-	Yes	Yes
FlashROM Kbits	1	1	1
Integrated PLL in CCCs ¹	-	1	1
VersaNet Globals ²	6	18	18
I/O Banks	4	4	4
Maximum User I/Os	120	157	212
Package Pins CS VQ	CS201, CS289 VQ128	CS201, CS289 VQ176	CS281, CS289

Notes:

- 1. AGLP060 in CS201 does not support the PLL.
- 2. Six chip (main) and twelve guadrant global networks are available for AGLP060 and AGLP125.

[†] The AGLP030 device does not support this feature.



I/Os Per Package ¹

IGLOO PLUS Devices	AGLP030	AGLP060	AGLP125	
Package		Single-Ended I/Os		
CS201	120	157	-	
CS281	-	-	212	
CS289	120	157	212	
VQ128	101	-	-	
VQ176	-	137	-	

Note: When the Flash*Freeze pin is used to directly enable Flash*Freeze mode and not used as a regular I/O, the number of single-ended user I/Os available is reduced by one.

Table 2 • IGLOO PLUS FPGAs Package Size Dimensions

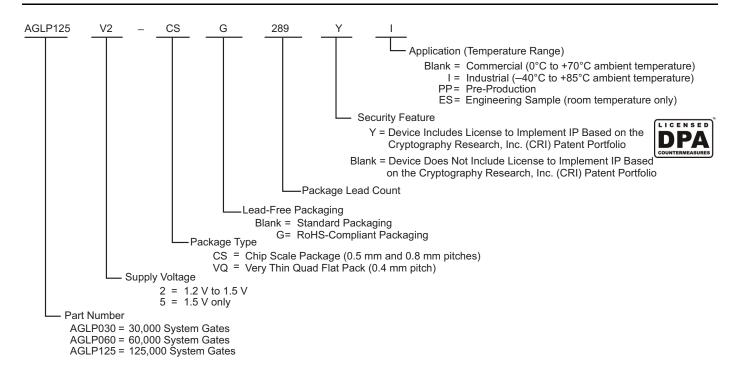
Package	CS201	CS281	CS289	VQ128	VQ176
Length × Width (mm/mm)	8 × 8	10 × 10	14 × 14	14 × 14	20 × 20
Nominal Area (mm2)	64	100	196	196	400
Pitch (mm)	0.5	0.5	0.8	0.4	0.4
Height (mm)	0.89	1.05	1.20	1.0	1.0

IGLOO PLUS Device Status

IGLOO PLUS Device	Status
AGLP030	Production
AGLP060	Production
AGLP125	Production

II Revision 16

IGLOO PLUS Ordering Information



Notes:

- 1. Marking information: IGLOO PLUS V2 devices do not have a V2 marking, but IGLOO PLUS V5 devices are marked accordingly.
- "G" indicates RoHS-compliant packages.

Revision 16 III



Temperature Grade Offerings

Package	AGLP030	AGLP060	AGLP125
CS201	C, I	C, I	-
CS281	-	_	C, I
CS289	C, I	C, I	C, I
VQ128	C, I	_	-
VQ176	_	C, I	-

Notes:

- C = Commercial temperature range: 0°C to 70°C ambient temperature.
 I = Industrial temperature range: -40°C to 85°C ambient temperature.

Contact your local Microsemi SoC Products Group representative for device availability:

http://www.microsemi.com/soc/company/contact/default.aspx.

Revision 16



Table of Contents

IGLOO PLUS Device Family Overview	
General Description	1-1
IGLOO PLUS DC and Switching Characteristics	
General Specifications	2-1
Calculating Power Dissipation	
User I/O Characteristics	
VersaTile Characteristics	
Global Resource Characteristics	
Clock Conditioning Circuits	
Embedded SRAM and FIFO Characteristics	2-64
Embedded FlashROM Characteristics	2-78
JTAG 1532 Characteristics	2-79
Pin Descriptions and Packaging	
Supply Pins	
User Pins	
JTAG Pins	
Special Function Pins	
Packaging	
Related Documents	
Package Pin Assignments	
VQ128	
VQ176	
CS201	
CS281	
CS289	4-16
Datasheet Information	
List of Changes	
Datasheet Categories	5-7
Safety Critical, Life Support, and High-Reliability Applications Policy	

Revision 16



1 – IGLOO PLUS Device Family Overview

General Description

The IGLOO PLUS family of flash FPGAs, based on a 130 nm flash process, offers the lowest power FPGA, a single-chip solution, small-footprint packages, reprogrammability, and an abundance of advanced features.

The Flash*Freeze technology used in IGLOO PLUS devices enables entering and exiting an ultra-low power mode that consumes as little as 5 μ W while retaining the design information, SRAM content, registers, and I/O states. Flash*Freeze technology simplifies power management through I/O and clock management with rapid recovery to operation mode.

The Low Power Active capability (static idle) allows for ultra-low power consumption while the IGLOO PLUS device is completely functional in the system. This allows the IGLOO PLUS device to control system power management based on external inputs (e.g., scanning for keyboard stimulus) while consuming minimal power.

Nonvolatile flash technology gives IGLOO PLUS devices the advantage of being a secure, low power, single-chip solution that is Instant On. IGLOO PLUS is reprogrammable and offers time-to-market benefits at an ASIC-level unit cost.

These features enable designers to create high-density systems using existing ASIC or FPGA design flows and tools.

IGLOO PLUS devices offer 1 kbit of on-chip, reprogrammable, nonvolatile FlashROM storage as well as clock conditioning circuitry based on an integrated phase-locked loop (PLL). IGLOO PLUS devices have up to 125 k system gates, supported with up to 36 kbits of true dual-port SRAM and up to 212 user I/Os. The AGLP030 devices have no PLL or RAM support.

Flash*Freeze Technology

The IGLOO PLUS device offers unique Flash*Freeze technology, allowing the device to enter and exit ultra-low power Flash*Freeze mode. IGLOO PLUS devices do not need additional components to turn off I/Os or clocks while retaining the design information, SRAM content, registers, and I/O states. Flash*Freeze technology is combined with in-system programmability, which enables users to quickly and easily upgrade and update their designs in the final stages of manufacturing or in the field. The ability of IGLOO PLUS V2 devices to support a wide range of core and I/O voltages (1.2 V to 1.5 V) allows further reduction in power consumption, thus achieving the lowest total system power.

During Flash*Freeze mode, each I/O can be set to the following configurations: hold previous state, tristate, or set as HIGH or LOW.

The availability of low power modes, combined with reprogrammability, a single-chip and single-voltage solution, and availability of small-footprint, high-pin-count packages, make IGLOO PLUS devices the best fit for portable electronics.

Flash Advantages

Low Power

IGLOO PLUS devices exhibit power characteristics similar to those of an ASIC, making them an ideal choice for power-sensitive applications. IGLOO PLUS devices have only a very limited power-on current surge and no high-current transition period, both of which occur on many FPGAs.

IGLOO PLUS devices also have low dynamic power consumption to further maximize power savings; power is even further reduced by the use of a 1.2 V core voltage.

Low dynamic power consumption, combined with low static power consumption and Flash*Freeze technology, gives the IGLOO PLUS device the lowest total system power offered by any FPGA.

Security

Nonvolatile, flash-based IGLOO PLUS devices do not require a boot PROM, so there is no vulnerable external bitstream that can be easily copied. IGLOO PLUS devices incorporate FlashLock, which provides a unique combination of reprogrammability and design security without external overhead, advantages that only an FPGA with nonvolatile flash programming can offer.

IGLOO PLUS devices (except AGLP030) utilize a 128-bit flash-based lock and a separate AES key to provide the highest level of security in the FPGA industry for programmed intellectual property and configuration data. In addition, all FlashROM data in IGLOO PLUS devices can be encrypted prior to loading, using the industry-leading AES-128 (FIPS192) bit block cipher encryption standard. AES was adopted by the National Institute of Standards and Technology (NIST) in 2000 and replaces the 1977 DES standard. IGLOO PLUS devices have a built-in AES decryption engine and a flash-based AES key that make them the most comprehensive programmable logic device security solution available today. IGLOO PLUS devices with AES-based security provide a high level of protection for secure, remote field updates over public networks such as the Internet, and ensure that valuable IP remains out of the hands of system overbuilders, system cloners, and IP thieves.

Security, built into the FPGA fabric, is an inherent component of the IGLOO PLUS family. The flash cells are located beneath seven metal layers, and many device design and layout techniques have been used to make invasive attacks extremely difficult. The IGLOO PLUS family, with FlashLock and AES security, is unique in being highly resistant to both invasive and noninvasive attacks. Your valuable IP is protected with industry-standard security, making remote ISP possible. An IGLOO PLUS device provides the best available security for programmable logic designs.

Single Chip

Flash-based FPGAs store their configuration information in on-chip flash cells. Once programmed, the configuration data is an inherent part of the FPGA structure, and no external configuration data needs to be loaded at system power-up (unlike SRAM-based FPGAs). Therefore, flash-based IGLOO PLUS FPGAs do not require system configuration components such as EEPROMs or microcontrollers to load device configuration data. This reduces bill-of-materials costs and PCB area, and increases security and system reliability.

The IGLOO PLUS devices can be operated with a 1.2 V or 1.5 V single-voltage supply for core and I/Os, eliminating the need for additional supplies while minimizing total power consumption.

Instant On

Flash-based IGLOO PLUS devices support Level 0 of the Instant On classification standard. This feature helps in system component initialization, execution of critical tasks before the processor wakes up, setup and configuration of memory blocks, clock generation, and bus activity management. The Instant On feature of flash-based IGLOO PLUS devices greatly simplifies total system design and reduces total system cost, often eliminating the need for CPLDs and clock generation PLLs. In addition, glitches and brownouts in system power will not corrupt the IGLOO PLUS device's flash configuration, and unlike SRAM-based FPGAs, the device will not have to be reloaded when system power is restored. This enables the reduction or complete removal of the configuration PROM, expensive voltage monitor, brownout detection, and clock generator devices from the PCB design. Flash-based IGLOO PLUS devices simplify total system design and reduce cost and design risk while increasing system reliability and improving system initialization time.

IGLOO PLUS flash FPGAs allow the user to quickly enter and exit Flash*Freeze mode. This is done almost instantly (within 1 µs), and the device retains configuration and data in registers and RAM. Unlike SRAM-based FPGAs, the device does not need to reload configuration and design state from external memory components; instead, it retains all necessary information to resume operation immediately.

Reduced Cost of Ownership

Advantages to the designer extend beyond low unit cost, performance, and ease of use. Unlike SRAM-based FPGAs, flash-based IGLOO PLUS devices allow all functionality to be Instant On; no external boot PROM is required. On-board security mechanisms prevent access to all the programming information and enable secure remote updates of the FPGA logic. Designers can perform secure remote in-system reprogramming to support future design iterations and field upgrades with confidence that valuable intellectual property cannot be compromised or copied. Secure ISP can be performed using the industry-standard AES algorithm.

1-2 Revision 16



The IGLOO PLUS family device architecture mitigates the need for ASIC migration at higher user volumes. This makes the IGLOO PLUS family a cost-effective ASIC replacement solution, especially for applications in the consumer, networking/communications, computing, and avionics markets.

Firm-Error Immunity

Firm errors occur most commonly when high-energy neutrons, generated in the upper atmosphere, strike a configuration cell of an SRAM FPGA. The energy of the collision can change the state of the configuration cell and thus change the logic, routing, or I/O behavior in an unpredictable way. These errors are impossible to prevent in SRAM FPGAs. The consequence of this type of error can be a complete system failure. Firm errors do not exist in the configuration memory of IGLOO PLUS flash-based FPGAs. Once it is programmed, the flash cell configuration element of IGLOO PLUS FPGAs cannot be altered by high-energy neutrons and is therefore immune to them. Recoverable (or soft) errors occur in the user data SRAM of all FPGA devices. These can easily be mitigated by using error detection and correction (EDAC) circuitry built into the FPGA fabric.

Advanced Flash Technology

The IGLOO PLUS family offers many benefits, including nonvolatility and reprogrammability, through an advanced flash-based, 130 nm LVCMOS process with seven layers of metal. Standard CMOS design techniques are used to implement logic and control functions. The combination of fine granularity, enhanced flexible routing resources, and abundant flash switches allows for very high logic utilization without compromising device routability or performance. Logic functions within the device are interconnected through a four-level routing hierarchy.

IGLOO PLUS family FPGAs utilize design and process techniques to minimize power consumption in all modes of operation.

Advanced Architecture

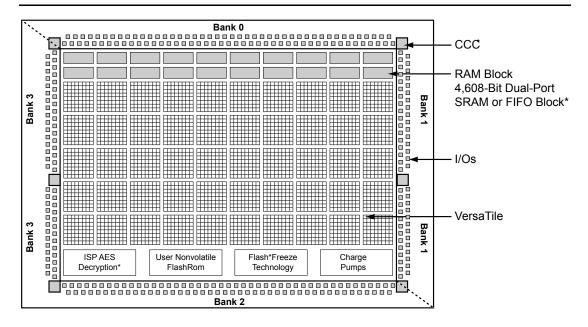
The proprietary IGLOO PLUS architecture provides granularity comparable to standard-cell ASICs. The IGLOO PLUS device consists of five distinct and programmable architectural features (Figure 1-1 on page 1-4):

- Flash*Freeze technology
- FPGA VersaTiles
- Dedicated FlashROM
- Dedicated SRAM/FIFO memory[†]
- Extensive CCCs and PLLs[†]
- · Advanced I/O structure

The FPGA core consists of a sea of VersaTiles. Each VersaTile can be configured as a three-input logic function, a D-flip-flop (with or without enable), or a latch by programming the appropriate flash switch interconnections. The versatility of the IGLOO PLUS core tile as either a three-input lookup table (LUT) equivalent or a D-flip-flop/latch with enable allows for efficient use of the FPGA fabric. The VersaTile capability is unique to the ProASIC[®] family of third-generation-architecture flash FPGAs. VersaTiles are connected with any of the four levels of routing hierarchy. Flash switches are distributed throughout the device to provide nonvolatile, reconfigurable interconnect programming. Maximum core utilization is possible for virtually any design.

[†] The AGLP030 device does not support PLL or SRAM.





Note: *Not supported by AGLP030 devices

Figure 1-1 • IGLOO PLUS Device Architecture Overview with Four I/O Banks (AGLP030, AGLP060, and AGLP125)

Flash*Freeze Technology

The IGLOO PLUS device has an ultra-low power static mode, called Flash*Freeze mode, which retains all SRAM and register information and can still quickly return to normal operation. Flash*Freeze technology enables the user to quickly (within 1 μ s) enter and exit Flash*Freeze mode by activating the Flash*Freeze pin while all power supplies are kept at their original values. In addition, I/Os and global I/Os can still be driven and can be toggling without impact on power consumption, clocks can still be driven or can be toggling without impact on power consumption, and the device retains all core registers, SRAM information, and I/O states. I/Os can be individually configured to either hold their previous state or be tristated during Flash*Freeze mode. Alternatively, they can be set to a certain state using weak pull-up or pull-down I/O attribute configuration. No power is consumed by the I/O banks, clocks, JTAG pins, or PLL, and the device consumes as little as 5 μ W in this mode.

Flash*Freeze technology allows the user to switch to Active mode on demand, thus simplifying the power management of the device.

The Flash*Freeze pin (active low) can be routed internally to the core to allow the user's logic to decide when it is safe to transition to this mode. Refer to Figure 1-2 for an illustration of entering/exiting Flash*Freeze mode. It is also possible to use the Flash*Freeze pin as a regular I/O if Flash*Freeze mode usage is not planned.

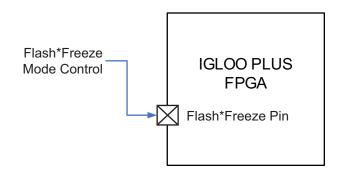


Figure 1-2 • IGLOO PLUS Flash*Freeze Mode

1-4 Revision 16



VersaTiles

The IGLOO PLUS core consists of VersaTiles, which have been enhanced beyond the ProASIC PLUS® core tiles. The IGLOO PLUS VersaTile supports the following:

- · All 3-input logic functions—LUT-3 equivalent
- · Latch with clear or set
- · D-flip-flop with clear or set
- · Enable D-flip-flop with clear or set

Refer to Figure 1-3 for VersaTile configurations.

LUT-3 Equivalent D-Flip-Flop with Clear or Set Data CLK CLR D-FF CLR CLR CLR CLR CLR CLR

Figure 1-3 • VersaTile Configurations

User Nonvolatile FlashROM

IGLOO PLUS devices have 1 kbit of on-chip, user-accessible, nonvolatile FlashROM. The FlashROM can be used in diverse system applications:

- · Internet protocol addressing (wireless or fixed)
- · System calibration settings
- Device serialization and/or inventory control
- Subscription-based business models (for example, set-top boxes)
- Secure key storage for secure communications algorithms
- Asset management/tracking
- · Date stamping
- · Version management

The FlashROM is written using the standard IGLOO PLUS IEEE 1532 JTAG programming interface. The core can be individually programmed (erased and written), and on-chip AES decryption can be used selectively to securely load data over public networks (except in AGLP030 devices), as in security keys stored in the FlashROM for a user design.

The FlashROM can be programmed via the JTAG programming interface, and its contents can be read back either through the JTAG programming interface or via direct FPGA core addressing. Note that the FlashROM can only be programmed from the JTAG interface and cannot be programmed from the internal logic array.

The FlashROM is programmed as 8 banks of 128 bits; however, reading is performed on a byte-by-byte basis using a synchronous interface. A 7-bit address from the FPGA core defines which of the 8 banks and which of the 16 bytes within that bank are being read. The three most significant bits (MSBs) of the FlashROM address determine the bank, and the four least significant bits (LSBs) of the FlashROM address define the byte.

The IGLOO PLUS development software solutions, Libero[®] System-on-Chip (SoC) and Designer, have extensive support for the FlashROM. One such feature is auto-generation of sequential programming files for applications requiring a unique serial number in each part. Another feature allows the inclusion of static data for system version control. Data for the FlashROM can be generated quickly and easily using Libero SoC and Designer software tools. Comprehensive programming file support is also included to allow for easy programming of large numbers of parts with differing FlashROM contents.

SRAM and FIFO

IGLOO PLUS devices (except AGLP030 devices) have embedded SRAM blocks along their north side. Each variable-aspect-ratio SRAM block is 4,608 bits in size. Available memory configurations are 256×18, 512×9, 1k×4, 2k×2, and 4k×1 bits. The individual blocks have independent read and write ports that can be configured with different bit widths on each port. For example, data can be sent through a 4-bit port and read as a single bitstream. The embedded SRAM blocks can be initialized via the device JTAG port (ROM emulation mode) using the UJTAG macro (except in AGLP030 devices).

In addition, every SRAM block has an embedded FIFO control unit. The control unit allows the SRAM block to be configured as a synchronous FIFO without using additional core VersaTiles. The FIFO width and depth are programmable. The FIFO also features programmable Almost Empty (AEMPTY) and Almost Full (AFULL) flags in addition to the normal Empty and Full flags. The embedded FIFO control unit contains the counters necessary for generation of the read and write address pointers. The embedded SRAM/FIFO blocks can be cascaded to create larger configurations.

PLL and CCC

IGLOO PLUS devices provide designers with very flexible clock conditioning circuit (CCC) capabilities. Each member of the IGLOO PLUS family contains six CCCs. One CCC (center west side) has a PLL. The AGLP030 device does not have a PLL or CCCs; it contains only inputs to six globals.

The six CCC blocks are located at the four corners and the centers of the east and west sides. One CCC (center west side) has a PLL.

The four corner CCCs and the east CCC allow simple clock delay operations as well as clock spine access.

The inputs of the six CCC blocks are accessible from the FPGA core or from one of several inputs located near the CCC that have dedicated connections to the CCC block.

The CCC block has these key features:

- Wide input frequency range (f_{IN CCC}) = 1.5 MHz up to 250 MHz
- Output frequency range (f_{OUT CCC}) = 0.75 MHz up to 250 MHz
- · 2 programmable delay types for clock skew minimization
- · Clock frequency synthesis (for PLL only)

Additional CCC specifications:

- Internal phase shift = 0°, 90°, 180°, and 270°. Output phase shift depends on the output divider configuration (for PLL only).
- Output duty cycle = 50% ± 1.5% or better (for PLL only)
- Low output jitter: worst case < 2.5% × clock period peak-to-peak period jitter when single global network used (for PLL only)
- Maximum acquisition time is 300 µs (for PLL only)
- Exceptional tolerance to input period jitter—allowable input jitter is up to 1.5 ns (for PLL only)
- Four precise phases; maximum misalignment between adjacent phases (for PLL only) is 40 ps × 250 MHz / f_{OUT CCC}

Global Clocking

IGLOO PLUS devices have extensive support for multiple clocking domains. In addition to the CCC and PLL support described above, there is a comprehensive global clock distribution network.

Each VersaTile input and output port has access to nine VersaNets: six chip (main) and three quadrant global networks. The VersaNets can be driven by the CCC or directly accessed from the core via multiplexers (MUXes). The VersaNets can be used to distribute low-skew clock signals or for rapid distribution of high-fanout nets.

I/Os with Advanced I/O Standards

The IGLOO PLUS family of FPGAs features a flexible I/O structure, supporting a range of voltages (1.2 V, 1.5 V, 1.8 V, 2.5 V, 3.0 V wide range, and 3.3 V). IGLOO PLUS FPGAs support many different I/O standards.

The I/Os are organized into four banks. All devices in IGLOO PLUS have four banks. The configuration of these banks determines the I/O standards supported.

1-6 Revision 16



Each I/O module contains several input, output, and output enable registers.

Hot-swap (also called hot-plug, or hot-insertion) is the operation of hot-insertion or hot-removal of a card in a powered-up system.

Cold-sparing (also called cold-swap) refers to the ability of a device to leave system data undisturbed when the system is powered up, while the component itself is powered down, or when power supplies are floating.

Wide Range I/O Support

IGLOO PLUS devices support JEDEC-defined wide range I/O operation. IGLOO PLUS devices support both the JESD8-B specification, covering 3 V and 3.3 V supplies, for an effective operating range of 2.7 V to 3.6 V, and JESD8-12 with its 1.2 V nominal, supporting an effective operating range of 1.14 V to 1.575 V.

Wider I/O range means designers can eliminate power supplies or power conditioning components from the board or move to less costly components with greater tolerances. Wide range eases I/O bank management and provides enhanced protection from system voltage spikes, while providing the flexibility to easily run custom voltage applications.

Specifying I/O States During Programming

You can modify the I/O states during programming in FlashPro. In FlashPro, this feature is supported for PDB files generated from Designer v8.5 or greater. See the *FlashPro User's Guide* for more information.

Note: PDB files generated from Designer v8.1 to Designer v8.4 (including all service packs) have limited display of Pin Numbers only.

- 1. Load a PDB from the FlashPro GUI. You must have a PDB loaded to modify the I/O states during programming.
- From the FlashPro GUI, click PDB Configuration. A FlashPoint Programming File Generator window appears.
- 3. Click the Specify I/O States During Programming button to display the Specify I/O States During Programming dialog box.
- 4. Sort the pins as desired by clicking any of the column headers to sort the entries by that header. Select the I/Os you wish to modify (Figure 1-4 on page 1-8).
- 5. Set the I/O Output State. You can set Basic I/O settings if you want to use the default I/O settings for your pins, or use Custom I/O settings to customize the settings for each pin. Basic I/O state settings:
 - 1 I/O is set to drive out logic High
 - 0 I/O is set to drive out logic Low

Last Known State – I/O is set to the last value that was driven out prior to entering the programming mode, and then held at that value during programming

Z -Tri-State: I/O is tristated

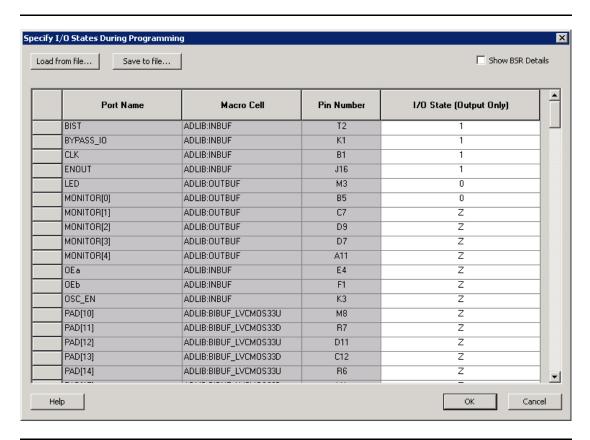


Figure 1-4 • I/O States During Programming Window

6. Click OK to return to the FlashPoint - Programming File Generator window.

Note: I/O States During programming are saved to the ADB and resulting programming files after completing programming file generation.

1-8 Revision 16



2 – IGLOO PLUS DC and Switching Characteristics

General Specifications

Operating Conditions

Stresses beyond those listed in Table 2-1 may cause permanent damage to the device.

Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Absolute Maximum Ratings are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions specified in Table 2-2 on page 2-2 is not implied.

Table 2-1 • Absolute Maximum Ratings

Symbol	Parameter	Limits	Units
VCC	DC core supply voltage	-0.3 to 1.65	V
VJTAG	JTAG DC voltage	-0.3 to 3.75	V
VPUMP	Programming voltage	-0.3 to 3.75	V
VCCPLL	Analog power supply (PLL)	-0.3 to 1.65	V
VCCI	DC I/O buffer supply voltage	-0.3 to 3.75	V
VI ¹	I/O input voltage	–0.3 V to 3.6 V	V
T _{STG} ²	Storage temperature	-65 to +150	°C
T_J^2	Junction temperature	+125	°C

Notes:

^{1.} The device should be operated within the limits specified by the datasheet. During transitions, the input signal may undershoot or overshoot according to the limits shown in Table 2-4 on page 2-3.

^{2.} For flash programming and retention maximum limits, refer to Table 2-3 on page 2-2, and for recommended operating limits, refer to Table 2-2 on page 2-2.



Table 2-2 • Recommended Operating Conditions 1,2

Symbol	Pa	rameter	Commercial	Industrial	Units
T _A	Ambient temperature	0 to +70	-40 to +85	°C	
T _J	Junction temperature ²		0 to + 85	-40 to +100	°C
VCC ³	1.5 V DC core supply voltage	⁴	1.425 to 1.575	1.425 to 1.575	V
	1.2 V-1.5 V wide range core	voltage ^{5,6}	1.14 to 1.575	1.14 to 1.575	V
VJTAG	JTAG DC voltage		1.4 to 3.6	1.4 to 3.6	V
VPUMP ⁷	Programming voltage	Programming mode	3.15 to 3.45	3.15 to 3.45	V
		Operation	0 to 3.6	0 to 3.6	V
VCCPLL ⁸	Analog power supply (PLL)	nalog power supply (PLL) 1.5 V DC core supply voltage ⁴		1.425 to 1.575	V
		1.2 V–1.5 V wide range core voltage ⁵	1.14 to 1.575	1.14 to 1.575	V
VCCI	1.2 V DC supply voltage ⁵		1.14 to 1.26	1.14 to 1.26	V
	1.2 V DC wide range supply	voltage ⁵	1.14 to 1.575	1.14 to 1.575	V
	1.5 V DC supply voltage		1.425 to 1.575	1.425 to 1.575	V
	1.8 V DC supply voltage	1.7 to 1.9	1.7 to 1.9	V	
	2.5 V DC supply voltage	2.3 to 2.7	2.3 to 2.7	V	
	3.3 V wide range DC supply	2.7 to 3.6	2.7 to 3.6	V	
	3.3 V DC supply voltage		3.0 to 3.6	3.0 to 3.6	V

- 1. All parameters representing voltages are measured with respect to GND unless otherwise specified.
- 2. To ensure targeted reliability standards are met across ambient and junction operating temperatures, Microsemi recommends that the user follow best design practices using Microsemi's timing and power simulation tools.
- 3. The ranges given here are for power supplies only. The recommended input voltage ranges specific to each I/O standard are given in Table 2-21 on page 2-19. VCCI should be at the same voltage within a given I/O bank.
- 4. For IGLOO® PLUS V5 devices
- 5. For IGLOO PLUS V2 devices only, operating at VCCI ≥ VCC.
- 6. All IGLOO PLUS devices (V5 and V2) must be programmed with the VCC core voltage at 1.5 V. Applications using V2 devices powered by a 1.2 V supply must switch the core supply to 1.5 V for in-system programming.
- 7. VPUMP can be left floating during operation (not programming mode).
- 8. VCCPLL pins should be tied to VCC pins. See the Pin Descriptions chapter of the IGLOO PLUS FPGA Fabric User's Guide for further information.
- 9. 3.3 V wide range is compliant to the JDEC8b specification and supports 3.0 V VCCI operation.

Table 2-3 • Flash Programming Limits – Retention, Storage, and Operating Temperature 1

Product Grade	Programming Cycles	Program Retention (biased/unbiased)	Maximum Storage Temperature T _{STG} (°C) ²	Maximum Operating Junction Temperature T _J (°C) ²
Commercial	500	20 years	110	100
Industrial	500	20 years	110	100

Notes:

- 1. This is a stress rating only; functional operation at any condition other than those indicated is not implied.
- 2. These limits apply for program/data retention only. Refer to Table 2-1 on page 2-1 and Table 2-2 for device operating conditions and absolute limits.

2-2 Revision 16

Table 2-4 • Overshoot and Undershoot Limits 1

vccı	Average VCCI–GND Overshoot or Undershoot Duration as a Percentage of Clock Cycle ²	Maximum Overshoot/ Undershoot ²
2.7 V or less	10%	1.4 V
	5%	1.49 V
3 V	10%	1.1 V
	5%	1.19 V
3.3 V	10%	0.79 V
	5%	0.88 V
3.6 V	10%	0.45 V
	5%	0.54 V

- 1. Based on reliability requirements at 85°C.
- 2. The duration is allowed at one out of six clock cycles. If the overshoot/undershoot occurs at one out of two cycles, the maximum overshoot/undershoot has to be reduced by 0.15 V.

I/O Power-Up and Supply Voltage Thresholds for Power-On Reset (Commercial and Industrial)

Sophisticated power-up management circuitry is designed into every IGLOO PLUS device. These circuits ensure easy transition from the powered-off state to the powered-up state of the device. The many different supplies can power up in any sequence with minimized current spikes or surges. In addition, the I/O will be in a known state through the power-up sequence. The basic principle is shown in Figure 2-1 on page 2-4.

There are five regions to consider during power-up.

IGLOO PLUS I/Os are activated only if ALL of the following three conditions are met:

- 1. VCC and VCCI are above the minimum specified trip points (Figure 2-1 and Figure 2-2 on page 2-5).
- 2. VCCI > VCC 0.75 V (typical)
- 3. Chip is in the operating mode.

VCCI Trip Point:

Ramping up (V5 devices): 0.6 V < trip_point_up < 1.2 V Ramping down (V5 devices): 0.5 V < trip_point_down < 1.1 V Ramping up (V2 devices): 0.75 V < trip_point_up < 1.05 V Ramping down (V2 devices): 0.65 V < trip_point_down < 0.95 V

VCC Trip Point:

Ramping up (V5 devices): 0.6 V < trip_point_up < 1.1 V
Ramping down (V5 devices): 0.5 V < trip_point_down < 1.0 V
Ramping up (V2 devices): 0.65 V < trip_point_up < 1.05 V
Ramping down (V2 devices): 0.55 V < trip_point_down < 0.95 V

VCC and VCCI ramp-up trip points are about 100 mV higher than ramp-down trip points. This specifically built-in hysteresis prevents undesirable power-up oscillations and current surges. Note the following:

- During programming, I/Os become tristated and weakly pulled up to VCCI.
- JTAG supply, PLL power supplies, and charge pump VPUMP supply have no influence on I/O behavior.

PLL Behavior at Brownout Condition

Microsemi recommends using monotonic power supplies or voltage regulators to ensure proper powerup behavior. Power ramp-up should be monotonic at least until VCC and VCCPLX exceed brownout activation levels (see Figure 2-1 and Figure 2-2 on page 2-5 for more details).

When PLL power supply voltage and/or VCC levels drop below the VCC brownout levels (0.75 V \pm 0.25 V for V5 devices, and 0.75 V \pm 0.2 V for V2 devices), the PLL output lock signal goes Low and/or the output clock is lost. Refer to the "Brownout Voltage" section in the "Power-Up/-Down Behavior of Low Power Flash Devices" chapter of the *IGLOO PLUS Device Family User's Guide* for information on clock and lock recovery.

Internal Power-Up Activation Sequence

- Core
- 2. Input buffers
- 3. Output buffers, after 200 ns delay from input buffer activation

To make sure the transition from input buffers to output buffers is clean, ensure that there is no path longer than 100 ns from input buffer to output buffer in your design.

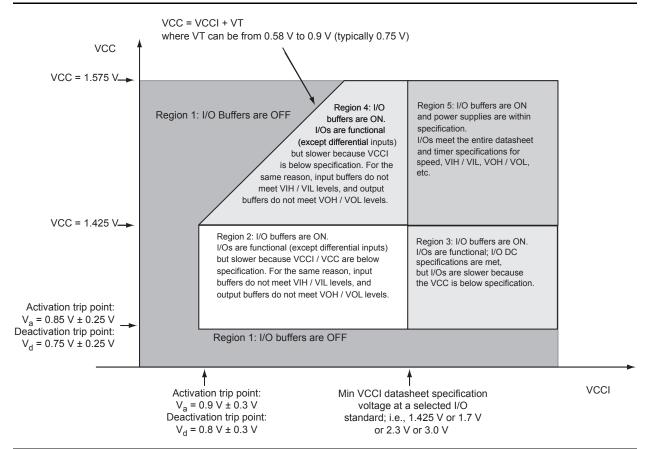


Figure 2-1 • V5 Devices - I/O State as a Function of VCCI and VCC Voltage Levels

2-4 Revision 16

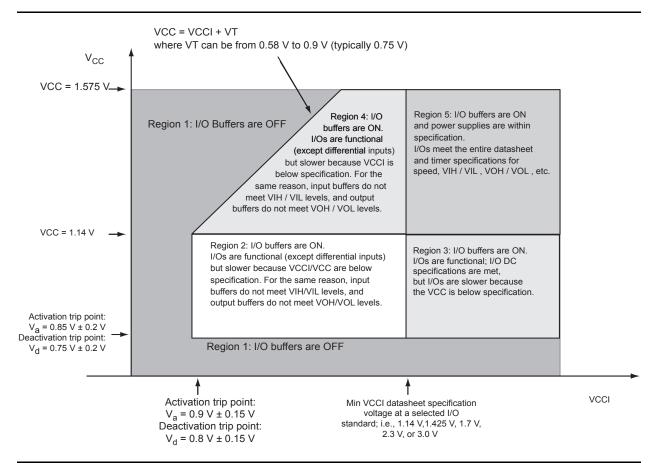


Figure 2-2 • V2 Devices – I/O State as a Function of VCCI and VCC Voltage Levels

Thermal Characteristics

Introduction

The temperature variable in the Microsemi Designer software refers to the junction temperature, not the ambient temperature. This is an important distinction because dynamic and static power consumption cause the chip junction temperature to be higher than the ambient temperature.

EQ 1 can be used to calculate junction temperature.

$$T_J$$
 = Junction Temperature = $\Delta T + T_A$

EQ 1

where:

 T_A = Ambient temperature

 ΔT = Temperature gradient between junction (silicon) and ambient ΔT = θ_{ia} * P

 θ_{ja} = Junction-to-ambient of the package. θ_{ja} numbers are located in Figure 2-5.

P = Power dissipation

Package Thermal Characteristics

The device junction-to-case thermal resistivity is θ_{jc} and the junction-to-ambient air thermal resistivity is θ_{ja} . The thermal characteristics for θ_{ja} are shown for two air flow rates. The maximum operating junction temperature is 100°C. EQ 2 shows a sample calculation of the maximum operating power dissipation allowed for a 484-pin FBGA package at commercial temperature and in still air.

Maximum Power Allowed =
$$\frac{\text{Max. junction temp. (°C)} - \text{Max. ambient temp. (°C)}}{\theta_{ja}(°\text{C/W})} = \frac{100°\text{C} - 70°\text{C}}{20.5°\text{C/W}} = 1.46~\text{W}$$

EQ 2

Table 2-5 • Package Thermal Resistivities

			θ_{ja}			
Package Type	Pin Count	θ _{jc}	Still Air	200 ft./ min.	500 ft./ min.	Units
Chip Scale Package (CSP)	CS201	TBD	TBD	TBD	TBD	C/W
	CS281	TBD	TBD	TBD	TBD	C/W
	CS289	TBD	TBD	TBD	TBD	C/W
Very Thin Quad Flat Package (VQFP)	VQ128	TBD	TBD	TBD	TBD	C/W
	VQ176	TBD	TBD	TBD	TBD	C/W

Temperature and Voltage Derating Factors

Table 2-6 • Temperature and Voltage Derating Factors for Timing Delays (normalized to T_J = 70°C, VCC = 1.425 V)
For IGLOO PLUS V2 or V5 devices, 1.5 V DC Core Supply Voltage

Array Voltage	Junction Temperature (°C)							
VCC (V)	-40°C	0°C	25°C	70°C	85°C	100°C		
1.425	0.934	0.953	0.971	1.000	1.007	1.013		
1.5	0.855	0.874	0.891	0.917	0.924	0.929		
1.575	0.799	0.816	0.832	0.857	0.864	0.868		

2-6 Revision 16

Table 2-7 • Temperature and Voltage Derating Factors for Timing Delays (normalized to T_J = 70°C, VCC = 1.14 V)
For IGLOO PLUS V2, 1.2 V DC Core Supply Voltage

Array Voltage VCC (V)	Junction Temperature (°C)							
	-40°C	0°C	25°C	70°C	85°C	100°C		
1.14	0.963	0.975	0.989	1.000	1.007	1.011		
1.2	0.853	0.865	.0877	0.893	0.893	0.897		
1.26	0.781	0.792	0.803	0.813	0.819	0.822		

Calculating Power Dissipation

Quiescent Supply Current

Quiescent supply current (I_{DD}) calculation depends on multiple factors, including operating voltages (VCC, VCCI, and VJTAG), operating temperature, system clock frequency, and power mode usage. Microsemi recommends using the Power Calculator and SmartPower software estimation tools to evaluate the projected static and active power based on the user design, power mode usage, operating voltage, and temperature.

Table 2-8 • Power Supply State per Mode

	Power Supply Configurations							
Modes/Power Supplies	VCC	VCCPLL	VCCI	VJTAG	VPUMP			
Flash*Freeze	On	On	On	On	On/off/floating			
Sleep	Off	Off	On	Off	Off			
Shutdown	Off	Off	Off	Off	Off			
No Flash*Freeze	On	On	On	On	On/off/floating			

Note: Off: Power Supply level = 0 V

Table 2-9 • Quiescent Supply Current (IDD) Characteristics, IGLOO PLUS Flash*Freeze Mode*

	Core Voltage	AGLP030	AGLP060	AGLP125	Units
Typical (25°C)	1.2 V	4	8	13	μΑ
	1.5 V	6	10	18	μΑ

Note: *IDD includes VCC, VPUMP, VCCI, VJTAG, and VCCPLL currents.

Table 2-10 • Quiescent Supply Current (IDD) Characteristics, IGLOO PLUS Sleep Mode*

ICCI Current	Core Voltage	AGLP030	AGLP060	AGLP125	Units
VCCI = 1.2 V (per bank) Typical (25°C)	1.2 V	1.7	1.7	1.7	μΑ
VCCI = 1.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	1.8	μΑ
VCCI = 1.8 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	1.9	μΑ
VCCI = 2.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	2.2	μΑ
VCCI = 3.3 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	2.5	μΑ

Note: *IDD = N_{BANKS} * ICCI

Table 2-11 • Quiescent Supply Current (IDD) Characteristics, IGLOO PLUS Shutdown Mode

	Core Voltage	AGLP030	AGLP060	AGLP125	Units
Typical (25°C)	1.2 V / 1.5 V	0	0	0	μΑ

Table 2-12 • Quiescent Supply Current (IDD), No IGLOO PLUS Flash*Freeze Mode 1

	Core Voltage	AGLP030	AGLP060	AGLP125	Units
ICCA Current ²		•	•		
Typical (25°C)	1.2 V	6	10	13	μΑ
	1.5 V	16	20	28	μA
ICCI or IJTAG Current					
VCCI / VJTAG = 1.2 V (per bank) Typical (25°C)	1.2 V	1.7	1.7	1.7	μΑ
VCCI / VJTAG = 1.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.8	1.8	1.8	μΑ
VCCI / VJTAG = 1.8 V (per bank) Typical (25°C)	1.2 V / 1.5 V	1.9	1.9	1.9	μA
VCCI / VJTAG = 2.5 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.2	2.2	2.2	μΑ
VCCI / VJTAG = 3.3 V (per bank) Typical (25°C)	1.2 V / 1.5 V	2.5	2.5	2.5	μΑ

2-8 Revision 16

^{1.} $IDD = N_{BANKS} * ICCI + ICCA$. JTAG counts as one bank when powered. 2. Includes VCC, VCCPLL, and VPUMP currents.



Power per I/O Pin

Table 2-13 • Summary of I/O Input Buffer Power (per pin) - Default I/O Software Settings

	VCCI (V)	Dynamic Power PAC9 (μW/MHz) ¹
Single-Ended		•
3.3 V LVTTL / 3.3 V LVCMOS	3.3	16.26
3.3 V LVTTL / 3.3 V LVCMOS – Schmitt Trigger	3.3	18.95
3.3 V LVCMOS Wide Range ²	3.3	16.26
3.3 V LVCMOS Wide Range ² – Schmitt Trigger	3.3	18.95
2.5 V LVCMOS	2.5	4.59
2.5 V LVCMOS – Schmitt Trigger	2.5	6.01
1.8 V LVCMOS	1.8	1.61
1.8 V LVCMOS – Schmitt Trigger	1.8	1.70
1.5 V LVCMOS (JESD8-11)	1.5	0.96
1.5 V LVCMOS (JESD8-11) – Schmitt Trigger	1.5	0.90
1.2 V LVCMOS ³	1.2	0.55
1.2 V LVCMOS ³ – Schmitt Trigger	1.2	0.47
1.2 V LVCMOS Wide Range ³	1.2	0.55
1.2 V LVCMOS Wide Range ³ – Schmitt Trigger	1.2	0.47

Notes:

- 1. PAC9 is the total dynamic power measured on VCCI.
- 2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
- 3. Applicable for IGLOO PLUS V2 devices only, operating at VCCI ≥ VCC.

Table 2-14 • Summary of I/O Output Buffer Power (per pin) - Default I/O Software Settings¹

	C _{LOAD} (pF)	VCCI (V)	Dynamic Power PAC10 (μW/MHz) ²
Single-Ended			
3.3 V LVTTL / 3.3 V LVCMOS	5	3.3	127.11
3.3 V LVCMOS Wide Range ³	5	3.3	127.11
2.5 V LVCMOS	5	2.5	70.71
1.8 V LVCMOS	5	1.8	35.57
1.5 V LVCMOS (JESD8-11)	5	1.5	24.30
1.2 V LVCMOS ⁴	5	1.2	15.22
1.2 V LVCMOS Wide Range ⁴	5	1.2	15.22

Notes:

- 1. Dynamic power consumption is given for standard load and software default drive strength and output slew.
- 2. PAC10 is the total dynamic power measured on VCCI.
- 3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
- 4. Applicable for IGLOO PLUS V2 devices only, operating at VCCI ≥ VCC.

Power Consumption of Various Internal Resources

Table 2-15 • Different Components Contributing to Dynamic Power Consumption in IGLOO PLUS Devices For IGLOO PLUS V2 or V5 Devices, 1.5 V Core Supply Voltage

		Device Specific Dynamic Pow (µW/MHz)			
Parameter	Definition	AGLP125	AGLP060	AGLP030	
PAC1	Clock contribution of a Global Rib	4.489	2.696	0.000 ¹	
PAC2	Clock contribution of a Global Spine	1.991	1.962	3.499	
PAC3	Clock contribution of a VersaTile row	1.510	1.523	1.537	
PAC4	Clock contribution of a VersaTile used as a sequential module	0.153	0.151	0.151	
PAC5	First contribution of a VersaTile used as a sequential module	0.029	0.029	0.029	
PAC6	Second contribution of a VersaTile used as a sequential module	0.323	0.323	0.323	
PAC7	Contribution of a VersaTile used as a combinatorial module	0.280	0.300	0.278	
PAC8	Average contribution of a routing net	1.097	1.081	1.130	
PAC9	Contribution of an I/O input pin (standard-dependent)	See Ta	ble 2-13 on p	page 2-9.	
PAC10	Contribution of an I/O output pin (standard-dependent)	See Table 2-14 on page 2-9.			
PAC11	Average contribution of a RAM block during a read operation	25.00			
PAC12	Average contribution of a RAM block during a write operation	30.00			
PAC13	Dynamic contribution for PLL		2.70		

Note: 1. There is no Center Global Rib present in AGLP030, and thus it starts directly at the spine resulting in $0\mu W/MHz$.

2-10 Revision 16

Table 2-16 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices For IGLOO PLUS V2 or V5 Devices, 1.5 V Core Supply Voltage

		Device-Specific Static Power (mW)				
Parameter	Definition	AGLP125	AGLP060	AGLP030		
PDC1	Array static power in Active mode	See Table 2-12 on page 2-8				
PDC2	Array static power in Static (Idle) mode	See Table 2-11 on page 2-8				
PDC3	Array static power in Flash*Freeze mode	See Table 2-9 on page 2-7				
PDC4	Static PLL contribution	1.84 ¹				
PDC5	Bank quiescent power (VCCI-dependent)	See Table 2-12 on page 2-8				

- 1. This is the minimum contribution of the PLL when operating at lowest frequency.
- 2. For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or the SmartPower tool in Libero SoC software.

Table 2-17 • Different Components Contributing to Dynamic Power Consumption in IGLOO PLUS Devices For IGLOO PLUS V2 Devices, 1.2 V Core Supply Voltage

		Device-Spo	mic Power				
Parameter	Definition	AGLP125	AGLP060	AGLP030			
PAC1	Clock contribution of a Global Rib	2.874	1.727	0.000 ¹			
PAC2	Clock contribution of a Global Spine	1.264	1.244	2.241			
PAC3	Clock contribution of a VersaTile row	0.963	0.975	0.981			
PAC4	Clock contribution of a VersaTile used as a sequential module	0.098	0.096	0.096			
PAC5	First contribution of a VersaTile used as a sequential module	0.018	0.018	0.018			
PAC6	Second contribution of a VersaTile used as a sequential module	0.203	0.203	0.203			
PAC7	Contribution of a VersaTile used as a combinatorial module	0.160	0.170	0.158			
PAC8	Average contribution of a routing net	0.679	0.686	0.748			
PAC9	Contribution of an I/O input pin (standard-dependent)	See Table 2-13 on page 2-9					
PAC10	Contribution of an I/O output pin (standard-dependent)	See Table 2-14 on page 2-9					
PAC11	Average contribution of a RAM block during a read operation	25.00					
PAC12	Average contribution of a RAM block during a write operation	30.00					
PAC13	Dynamic contribution for PLL		2.10				

Note: 1. There is no Center Global Rib present in AGLP030, and thus it starts directly at the spine resulting in 0μ W/MHz.

Table 2-18 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices For IGLOO PLUS V2 Devices, 1.2 V Core Supply Voltage

		Device-Sp	Device-Specific Static Power (mW)							
Parameter	Definition	Definition AGLP125 AGLP060								
PDC1	Array static power in Active mode	See T	See Table 2-12 on page 2-8							
PDC2	Array static power in Static (Idle) mode	See 7	See Table 2-11 on page 2-8							
PDC3	Array static power in Flash*Freeze mode	See	See Table 2-9 on page 2-7							
PDC4	Static PLL contribution		0.90 ¹							
PDC5	Bank quiescent power (VCCI-dependent)	x quiescent power (VCCI-dependent) See Table 2-12 on page 2-8								

- 1. This is the minimum contribution of the PLL when operating at lowest frequency.
- 2. For a different output load, drive strength, or slew rate, Microsemi recommends using the Microsemi power spreadsheet calculator or the SmartPower tool in Libero SoC software.

Power Calculation Methodology

This section describes a simplified method to estimate power consumption of an application. For more accurate and detailed power estimations, use the SmartPower tool in Libero SoC software.

The power calculation methodology described below uses the following variables:

- · The number of PLLs as well as the number and the frequency of each output clock generated
- The number of combinatorial and sequential cells used in the design
- · The internal clock frequencies
- · The number and the standard of I/O pins used in the design
- · The number of RAM blocks used in the design
- Toggle rates of I/O pins as well as VersaTiles—guidelines are provided in Table 2-19 on page 2-14.
- Enable rates of output buffers—guidelines are provided for typical applications in Table 2-20 on page 2-14.
- Read rate and write rate to the memory—guidelines are provided for typical applications in Table 2-20 on page 2-14. The calculation should be repeated for each clock domain defined in the design.

Methodology

Total Power Consumption—P_{TOTAL}

 $P_{TOTAL} = P_{STAT} + P_{DYN}$

P_{STAT} is the total static power consumption.

P_{DYN} is the total dynamic power consumption.

Total Static Power Consumption—P_{STAT}

P_{STAT} = (PDC1 or PDC2 or PDC3) + N_{BANKS} * PDC5

N_{BANKS} is the number of I/O banks powered in the design.

Total Dynamic Power Consumption—PDYN

PDYN = PCLOCK + PS-CELL + PC-CELL + PNET + PINPUTS + POUTPUTS + PMEMORY + PPLL

Global Clock Contribution—PCLOCK

 P_{CLOCK} = (PAC1 + N_{SPINE} *PAC2 + N_{ROW} *PAC3 + N_{S-CELL} * PAC4) * F_{CLK}

N_{SPINE} is the number of global spines used in the user design—guidelines are provided in the "Spine Architecture" section of the Global Resources chapter in the *IGLOO PLUS FPGA Fabric User's Guide*.

2-12 Revision 16

N_{ROW} is the number of VersaTile rows used in the design—guidelines are provided in the "Spine Architecture" section of the Global Resources chapter in the *IGLOO PLUS FPGA Fabric User's Guide*.

F_{CLK} is the global clock signal frequency.

N_{S-CFLL} is the number of VersaTiles used as sequential modules in the design.

PAC1, PAC2, PAC3, and PAC4 are device-dependent.

Sequential Cells Contribution—P_{S-CELL}

 $P_{S-CELL} = N_{S-CELL} * (PAC5 + \alpha_1 / 2 * PAC6) * F_{CLK}$

 $N_{S\text{-}CELL}$ is the number of VersaTiles used as sequential modules in the design. When a multi-tile sequential cell is used, it should be accounted for as 1.

 α_1 is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-19 on page 2-14.

F_{CLK} is the global clock signal frequency.

Combinatorial Cells Contribution—P_{C-CFL}

 $P_{C-CELL} = N_{C-CELL} * \alpha_1 / 2 * PAC7 * F_{CLK}$

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

 α_{1} is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-19 on page 2-14.

F_{CLK} is the global clock signal frequency.

Routing Net Contribution—PNFT

 P_{NET} = (N_{S-CELL} + N_{C-CELL}) * α_1 / 2 * PAC8 * F_{CLK}

 $N_{S\text{-}CELL}$ is the number of VersaTiles used as sequential modules in the design.

N_{C-CELL} is the number of VersaTiles used as combinatorial modules in the design.

 α_1 is the toggle rate of VersaTile outputs—guidelines are provided in Table 2-19 on page 2-14.

F_{CLK} is the global clock signal frequency.

I/O Input Buffer Contribution—PINPUTS

 $P_{INPUTS} = N_{INPUTS} * \alpha_2 / 2 * P_{AC9} * F_{CLK}$

N_{INPLITS} is the number of I/O input buffers used in the design.

 α_2 is the I/O buffer toggle rate—guidelines are provided in Table 2-19 on page 2-14.

F_{CLK} is the global clock signal frequency.

I/O Output Buffer Contribution—POUTPUTS

 $P_{OUTPUTS} = N_{OUTPUTS} * \alpha_2 / 2 * \beta_1 * PAC10 * F_{CLK}$

 $N_{OUTPUTS}$ is the number of I/O output buffers used in the design.

 α_2 is the I/O buffer toggle rate—guidelines are provided in Table 2-19 on page 2-14.

 β_1 is the I/O buffer enable rate—guidelines are provided in Table 2-20 on page 2-14.

F_{CLK} is the global clock signal frequency.

RAM Contribution—P_{MEMORY}

 $P_{MEMORY} = P_{AC11} * N_{BLOCKS} * F_{READ-CLOCK} * \beta_2 + PAC12 * N_{BLOCK} * F_{WRITE-CLOCK} * \beta_3$

N_{BLOCKS} is the number of RAM blocks used in the design.

F_{READ-CLOCK} is the memory read clock frequency.

 β_2 is the RAM enable rate for read operations.

 $F_{WRITE\text{-}CLOCK}$ is the memory write clock frequency.

 β_3 is the RAM enable rate for write operations—guidelines are provided in Table 2-20 on page 2-14.

PLL Contribution—PPLL

 P_{PLL} = PDC4 + PAC1₃ *F_{CLKOUT} F_{CLKOUT} is the output clock frequency.¹

Guidelines

Toggle Rate Definition

A toggle rate defines the frequency of a net or logic element relative to a clock. It is a percentage. If the toggle rate of a net is 100%, this means that this net switches at half the clock frequency. Below are some examples:

- The average toggle rate of a shift register is 100% because all flip-flop outputs toggle at half of the clock frequency.
- The average toggle rate of an 8-bit counter is 25%:

- Bit 0 (LSB) = 100%

- Bit 1 = 50%

- Bit 2 = 25%

- ...

- Bit 7 (MSB) = 0.78125%

– Average toggle rate = (100% + 50% + 25% + 12.5% + . . . + 0.78125%) / 8

Enable Rate Definition

Output enable rate is the average percentage of time during which tristate outputs are enabled. When nontristate output buffers are used, the enable rate should be 100%.

Table 2-19 • Toggle Rate Guidelines Recommended for Power Calculation

Component	Definition	Guideline
α_1	Toggle rate of VersaTile outputs	10%
α_2	I/O buffer toggle rate	10%

Table 2-20 • Enable Rate Guidelines Recommended for Power Calculation

Component	Definition	Guideline
β_1	I/O output buffer enable rate	100%
β_2	RAM enable rate for read operations	12.5%
β_3	RAM enable rate for write operations	12.5%

2-14 Revision 16

If a PLL is used to generate more than one output clock, include each output clock in the formula by adding its corresponding contribution (P_{AC13}* F_{CLKOUT} product) to the total PLL contribution.

User I/O Characteristics

Timing Model

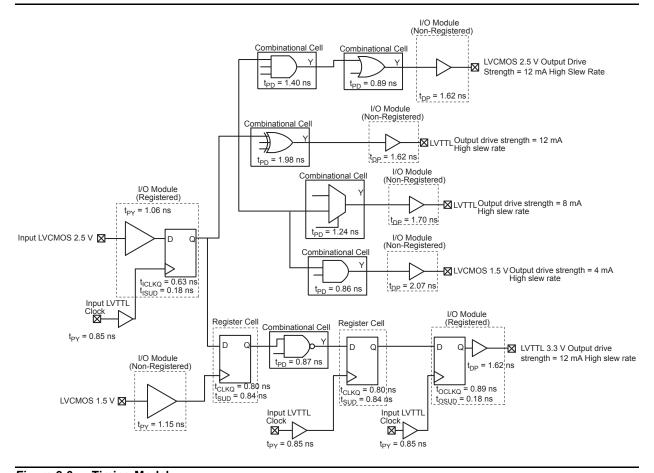


Figure 2-3 • Timing Model
Operating Conditions: STD Speed, Commercial Temperature Range (T_J = 70°C), Worst-Case
VCC = 1.425 V, for DC 1.5 V Core Voltage, Applicable to V2 and V5 Devices

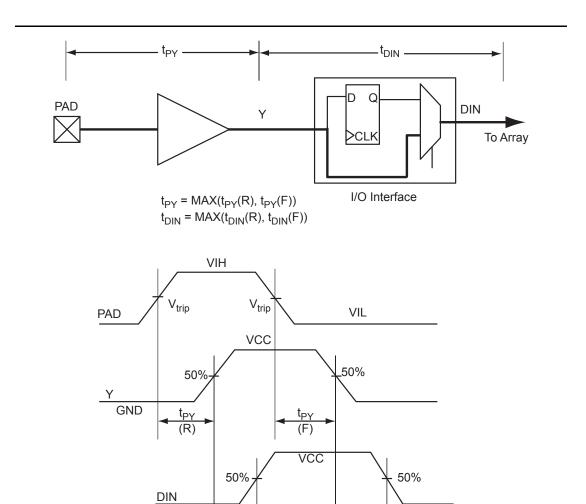


Figure 2-4 • Input Buffer Timing Model and Delays (example)

GND

t_{DIN} (R)

2-16 Revision 16

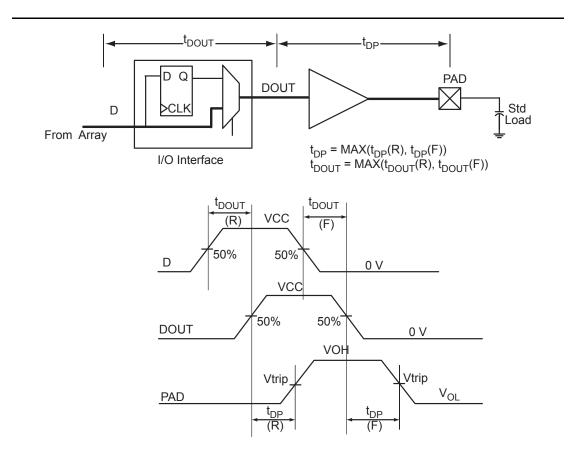


Figure 2-5 • Output Buffer Model and Delays (example)



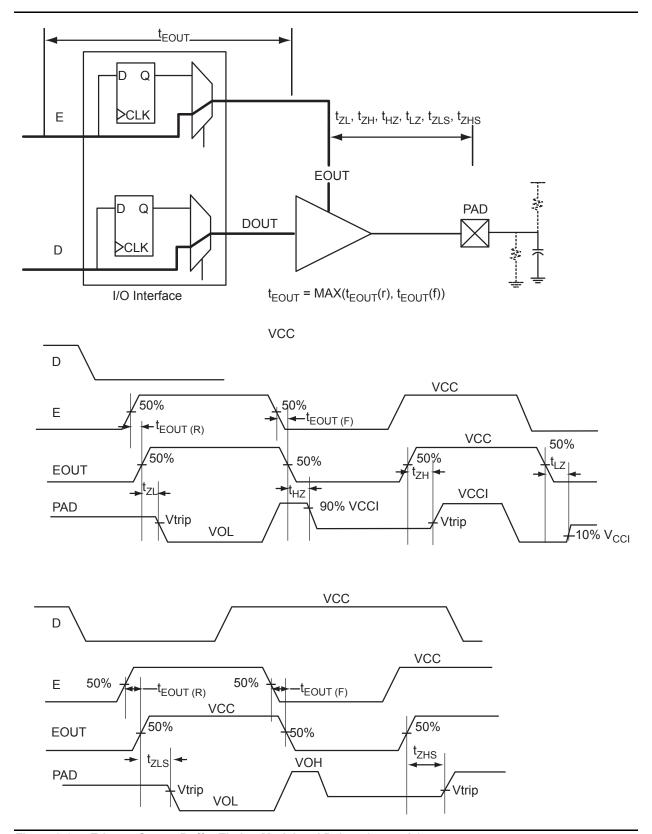


Figure 2-6 • Tristate Output Buffer Timing Model and Delays (example)

2-18 Revision 16



Overview of I/O Performance

Summary of I/O DC Input and Output Levels – Default I/O Software Settings

Table 2-21 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings

		Equiv.			VIL	VIH		VOL	VOH	IOL ¹	IOH ¹
I/O Standard	Drive Strength	Software Default Drive Strength Option ²	Slew		Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	-0.3	0.8	2	3.6	0.4	2.4	12	12
3.3 V LVCMOS Wide Range ³	100 μΑ	12 mA	High	-0.3	0.8	2	3.6	0.2	VDD 3 0.2	0.1	0.1
2.5 V LVCMOS	12 mA	12 mA	High	-0.3	0.7	1.7	3.6	0.7	1.7	12	12
1.8 V LVCMOS	8 mA	8 mA	High	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI - 0.45	8	8
1.5 V LVCMOS	4 mA	4 mA	High	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	4	4
1.2 V LVCMOS ⁴	2 mA	2 mA	High	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2
1.2 V LVCMOS Wide Range ^{4,5}	100 μΑ	2 mA	High	-0.3	0.3 * VCCI	0.7 * VCCI	3.6	0.1	VCCI - 0.1	0.1	0.1

Notes:

- 1. Currents are measured at 85°C junction temperature.
- 2. Note that 1.2 V LVCMOS and 3.3 V LVCMOS wide range are applicable to 100 μ A drive strength only. The configuration will not operate at the equivalent software default drive strength. These values are for normal ranges only.
- 3. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
- 4. Applicable to IGLOO PLUS V2 devices operating at VCC_I \geq VCC.
- 5. All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.

Table 2-22 • Summary of Maximum and Minimum DC Input Levels **Applicable to Commercial and Industrial Conditions**

	Com	mercial ¹	Industrial ²			
	IIL ³	IIH⁴	IIL ³	IIH ⁴		
DC I/O Standards	μΑ	μΑ	μΑ	μΑ		
3.3 V LVTTL / 3.3 V LVCMOS	10	10	15	15		
3.3 V LVCMOS Wide Range	10	10	15	15		
2.5 V LVCMOS	10	10	15	15		
1.8 V LVCMOS	10	10	15	15		
1.5 V LVCMOS	10	10	15	15		
1.2 V LVCMOS ⁵	10	10	15	15		
1.2 V LVCMOS Wide Range ⁵	10	10	15	15		

- Commercial range (0°C < T_A < 70°C)
 Industrial range (-40°C < T_A < 85°C)
- 3. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 4. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 5. Applicable to IGLOO PLUS V2 devices operating at VCCI 3 VCC.

2-20 Revision 16



Summary of I/O Timing Characteristics – Default I/O Software Settings

Table 2-23 • Summary of AC Measuring Points

Standard	Measuring Trip Point (Vtrip)
3.3 V LVTTL / 3.3 V LVCMOS	1.4 V
3.3 V LVCMOS Wide Range	1.4 V
2.5 V LVCMOS	1.2 V
1.8 V LVCMOS	0.90 V
1.5 V LVCMOS	0.75 V
1.2 V LVCMOS	0.60 V
1.2 V LVCMOS Wide Range	0.60 V

Table 2-24 • I/O AC Parameter Definitions

Parameter	Parameter Definition
t _{DP}	Data to Pad delay through the Output Buffer
t _{PY}	Pad to Data delay through the Input Buffer
t _{DOUT}	Data to Output Buffer delay through the I/O interface
t _{EOUT}	Enable to Output Buffer Tristate Control delay through the I/O interface
t _{DIN}	Input Buffer to Data delay through the I/O interface
t_{HZ}	Enable to Pad delay through the Output Buffer—High to Z
t _{ZH}	Enable to Pad delay through the Output Buffer—Z to High
t_{LZ}	Enable to Pad delay through the Output Buffer—Low to Z
t _{ZL}	Enable to Pad delay through the Output Buffer—Z to Low
t _{ZHS}	Enable to Pad delay through the Output Buffer with delayed enable—Z to High
t _{ZLS}	Enable to Pad delay through the Output Buffer with delayed enable—Z to Low

Table 2-25 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade,
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V

I/O Standard	Drive Strength	Equivalent Software Default Drive Strength Option ¹	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	[‡] воит	40,	[‡] DIN	t _P Y	t _{PYS}	t _E our	^t ZL	нг	^t LZ	tнz	Units
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	5 pF	1	0.97	1.76	0.18	0.85	1.15	0.66	1.80	1.39	2.20	2.64	ns
3.3 V LVCMOS Wide Range ²	100 μΑ	12 mA	High	5 pF	1	0.97	2.47	0.18	1.18	1.64	0.66	2.48	1.91	3.16	3.76	ns
2.5 V LVCMOS	12 mA	12 mA	High	5 pF	1	0.97	1.77	0.18	1.06	1.22	0.66	1.81	1.51	2.22	2.56	ns
1.8 V LVCMOS	8 mA	8 mA	High	5 pF	ı	0.97	2.00	0.18	1.00	1.43	0.66	2.04	1.76	2.29	2.55	ns
1.5 V LVCMOS	4 mA	4 mA	High	5 pF	ı	0.97	2.29	0.18	1.16	1.62	0.66	2.33	2.00	2.37	2.57	ns

- 1. Note that 3.3 V LVCMOS wide range is applicable to 100 μ A drive strength only. The configuration will not operate at the equivalent software default drive strength. These values are for normal ranges only.
- 2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2-22 Revision 16



Table 2-26 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade Commercial-Case Conditions: $T_J = 70^{\circ}$ C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V

I/O Standard	Drive Strength	Equivalent Software Default Drive Strength Option ¹	Slew Rate	Capacitive Load (pF)	External Resistor (Ω)	tроит	t _{DP}	[‡] DIN	t _{PY})	t _{РҮS}	teour	tzı	t _Z н	t _{LZ}	t _{HZ}	Units
3.3 V LVTTL / 3.3 V LVCMOS	12 mA	12 mA	High	5 pF	-	0.98	2.31	0.19	0.99	1.37	0.67	2.34	1.86	2.65	3.38	ns
3.3 V LVCMOS Wide Range ²	100 µA	12 mA	High	5 pF	-	0.98	3.21	0.19	1.32	1.92	0.67	3.21	2.52	3.73	4.73	ns
2.5 V LVCMOS	12 mA	12 mA	High	5 pF	_	0.98	2.29	0.19	1.19	1.40	0.67	2.32	1.94	2.65	3.27	ns
1.8 V LVCMOS	8 mA	8 mA	High	5 pF	_	0.98	2.45	0.19	1.12	1.61	0.67	2.48	2.16	2.71	3.16	ns
1.5 V LVCMOS	4 mA	4 mA	High	5 pF	-	0.98	2.71	0.19	1.26	1.80	0.67	2.75	2.39	2.78	3.15	ns
1.2 V LVCMOS	2 mA	2 mA	High	5 pF	-	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns
1.2 V LVCMOS Wide Range ³	100 µA	2 mA	High	5 pF	1	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is $\pm 100~\mu$ A. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. All LVCMOS 3.3 V software macros support LVCMOS 3.3 V wide range as specified in the JESD-8B specification.
- 3. All LVCMOS 1.2 V software macros support LVCMOS 1.2 V wide range as specified in the JESD8-12 specification.
- 4. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Detailed I/O DC Characteristics

Table 2-27 • Input Capacitance

Symbol	Definition	Conditions	Min.	Max.	Units
C _{IN}	Input capacitance	VIN = 0, f = 1.0 MHz		8	pF
C _{INCLK}	Input capacitance on the clock pin	VIN = 0, f = 1.0 MHz		8	pF

Table 2-28 • I/O Output Buffer Maximum Resistances 1

Standard	Drive Strength	R _{PULL-DOWN} (Ω) ²	R _{PULL} ; _{UP} (Ω) ³
3.3 V LVTTL / 3.3V LVCMOS	2 mA	100	300
	4 mA	100	300
	6 mA	50	150
	8 mA	50	150
	12 mA	25	75
	16 mA	25	75
3.3 V LVCMOS Wide Range	100 μΑ	Same as equivalent	software default drive
2.5 V LVCMOS	2 mA	100	200
	4 mA	100	200
	6 mA	50	100
	8 mA	50	100
	12 mA	25	50
1.8 V LVCMOS	2 mA	200	225
	4 mA	100	112
	6 mA	50	56
	8 mA	50	56
1.5 V LVCMOS	2 mA	200	224
	4 mA	100	112
1.2 V LVCMOS	2 mA	157.5	163.8
1.2 V LVCMOS Wide Range ⁴	100 μΑ	157.5	163.8

Notes:

2-24 Revision 16

^{1.} These maximum values are provided for informational reasons only. Minimum output buffer resistance values depend on VCC_I, drive strength selection, temperature, and process. For board design considerations and detailed output buffer resistances, use the corresponding IBIS model on the Microsemi SoC Products Group website at http://www.microsemi.com/soc/download/ibis/default.aspx.

^{2.} $R_{(PULL-DOWN-MAX)} = (VOLspec) / IOLspec$

^{3.} $R_{(PULL-UP-MAX)} = (VCCImax - VOHspec) / IOHspec$

^{4.} Applicable to IGLOO PLUS V2 devices operating at VCCI ≥ VCC.



Table 2-29 • I/O Weak Pull-Up/Pull-Down Resistances Minimum and Maximum Weak Pull-Up/Pull-Down Resistance Values

	R _{(WEAK I}	PULL-UP) ¹	$R_{(WEAK\;PULL-DOWN)}^2$ (\Omega)			
VCCI	Min.	Max.	Min.	Max.		
3.3 V	10 K	45 K	10 K	45 K		
3.3 V (wide range I/Os)	10 K	45 K	10 K	45 K		
2.5 V	11 K	55 K	12 K	74 K		
1.8 V	18 K	70 K	17 K	110 K		
1.5 V	19 K	90 K	19 K	140 K		
1.2 V	25 K	110 K	25 K	150 K		
1.2 V (wide range I/Os)	19 K	110 K	19 K	150 K		

Notes:

- 1. $R_{(WEAK\ PULL-UP-MAX)} = (VCCImax VOHspec) / I_{(WEAK\ PULL-UP-MIN)}$ 2. $R_{(WEAK\ PULLDOWN-MAX)} = (VOLspec) / I_{(WEAK\ PULLDOWN-MIN)}$

Table 2-30 • I/O Short Currents IOSH/IOSL

	Drive Strength	IOSL (mA)*	IOSH (mA)*
3.3 V LVTTL / 3.3 V LVCMOS	2 mA	27	25
	4 mA	27	25
	6 mA	54	51
	8 mA	54	51
	12 mA	109	103
	16 mA	109	103
3.3 V LVCMOS Wide Range	100 μΑ	Same as equivalent s	software default drive
2.5 V LVCMOS	2 mA	18	16
	4 mA	18	16
	6 mA	37	32
	8 mA	37	32
	12 mA	74	65
1.8 V LVCMOS	2 mA	11	9
	4 mA	22	17
	6 mA	44	35
	8 mA	44	35
1.5 V LVCMOS	2 mA	16	13
	4 mA	33	25
1.2 V LVCMOS	2 mA	26	20
1.2 V LVCMOS Wide Range	100 μΑ	26	20

Note: $*T_J = 100$ °C

The length of time an I/O can withstand IOSH/IOSL events depends on the junction temperature. The reliability data below is based on a 3.3 V, 12 mA I/O setting, which is the worst case for this type of analysis.

For example, at 100°C, the short current condition would have to be sustained for more than six months to cause a reliability concern. The I/O design does not contain any short circuit protection, but such protection would only be needed in extremely prolonged stress conditions.

Table 2-31 • Duration of Short Circuit Event before Failure

Temperature	Time before Failure
-40°C	> 20 years
0°C	> 20 years
25°C	> 20 years
70°C	5 years
85°C	2 years
100°C	6 months

Table 2-32 • Schmitt Trigger Input Hysteresis
Hysteresis Voltage Value (Typ.) for Schmitt Mode Input Buffers

Input Buffer Configuration	Hysteresis Value (typ.)
3.3 V LVTTL/LVCMOS (Schmitt trigger mode)	240 mV
2.5 V LVCMOS (Schmitt trigger mode)	140 mV
1.8 V LVCMOS (Schmitt trigger mode)	80 mV
1.5 V LVCMOS (Schmitt trigger mode)	60 mV
1.2 V LVCMOS (Schmitt trigger mode)	40 mV

Table 2-33 • I/O Input Rise Time, Fall Time, and Related I/O Reliability

Input Buffer	Input Rise/Fall Time (min.)	Input Rise/Fall Time (max.)	Reliability
LVTTL/LVCMOS (Schmitt trigger disabled)	No requirement	10 ns *	20 years (100°C)
LVTTL/LVCMOS (Schmitt trigger enabled)	No requirement	No requirement, but input noise voltage cannot exceed Schmitt hysteresis.	20 years (100°C)

Note: *The maximum input rise/fall time is related to the noise induced into the input buffer trace. If the noise is low, then the rise time and fall time of input buffers can be increased beyond the maximum value. The longer the rise/fall times, the more susceptible the input signal is to the board noise. Microsemi recommends signal integrity evaluation/characterization of the system to ensure that there is no excessive noise coupling into input signals.

2-26 Revision 16

Single-Ended I/O Characteristics

3.3 V LVTTL / 3.3 V LVCMOS

Low-Voltage Transistor–Transistor Logic (LVTTL) is a general-purpose standard (EIA/JESD) for 3.3 V applications. It uses an LVTTL input buffer and push-pull output buffer.

Table 2-34 • Minimum and Maximum DC Input and Output Levels

3.3 V LVTTL / 3.3 V LVCMOS	٧	TL.	٧	IH	VOL	VOH	IOL	ЮН	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μ Α ⁴	μ Α ⁴
2 mA	-0.3	0.8	2	3.6	0.4	2.4	2	2	25	27	10	10
4 mA	-0.3	0.8	2	3.6	0.4	2.4	4	4	25	27	10	10
6 mA	-0.3	0.8	2	3.6	0.4	2.4	6	6	51	54	10	10
8 mA	-0.3	0.8	2	3.6	0.4	2.4	8	8	51	54	10	10
12 mA	-0.3	0.8	2	3.6	0.4	2.4	12	12	103	109	10	10
16 mA	-0.3	0.8	2	3.6	0.4	2.4	16	16	103	109	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

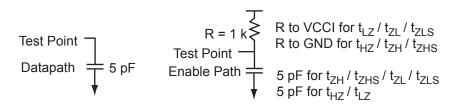


Figure 2-7 • AC Loading

Table 2-35 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	3.3	1.4	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-36 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.97	3.94	0.18	0.85	1.15	0.66	4.02	3.46	1.82	1.87	ns
6 mA	STD	0.97	3.20	0.18	0.85	1.15	0.66	3.27	2.94	2.04	2.27	ns
8 mA	STD	0.97	3.20	0.18	0.85	1.15	0.66	3.27	2.94	2.04	2.27	ns
12 mA	STD	0.97	2.72	0.18	0.85	1.15	0.66	2.78	2.57	2.20	2.53	ns
16 mA	STD	0.97	2.72	0.18	0.85	1.15	0.66	2.78	2.57	2.20	2.53	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-37 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.97	2.36	0.18	0.85	1.15	0.66	2.41	1.90	1.82	1.98	ns
6 mA	STD	0.97	1.96	0.18	0.85	1.15	0.66	2.01	1.56	2.04	2.38	ns
8 mA	STD	0.97	1.96	0.18	0.85	1.15	0.66	2.01	1.56	2.04	2.38	ns
12 mA	STD	0.97	1.76	0.18	0.85	1.15	0.66	1.80	1.39	2.20	2.64	ns
16 mA	STD	0.97	1.76	0.18	0.85	1.15	0.66	1.80	1.39	2.20	2.64	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

Applies to 1.2 V DC Core Voltage

Table 2-38 • 3.3 V LVTTL / 3.3 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage Commercial-Case Conditions: $T_J = 70^{\circ}$ C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t_{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.98	4.56	0.19	0.99	1.37	0.67	4.63	3.98	2.26	2.57	ns
6 mA	STD	0.98	3.80	0.19	0.99	1.37	0.67	3.96	3.45	2.49	2.98	ns
8 mA	STD	0.98	3.80	0.19	0.99	137	0.67	3.86	3.45	2.49	2.98	ns
12 mA	STD	0.98	3.31	0.19	0.99	1.37	0.67	3.36	3.07	2.65	3.25	ns
16 mA	STD	0.98	3.31	0.19	0.99	1.37	0.67	3.36	3.07	2.65	3.25	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-39 • 3.3 V LVTTL / 3.3 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.98	2.92	0.19	0.99	1.37	0.67	2.97	2.38	2.25	2.70	ns
6 mA	STD	0.98	2.52	0.19	0.99	1.37	0.67	2.56	2.03	2.49	3.11	ns
8 mA	STD	0.98	2.52	0.19	0.99	1.37	0.67	2.56	2.03	2.49	3.11	ns
12 mA	STD	0.98	2.31	0.19	0.99	1.37	0.67	2.34	1.86	2.65	3.38	ns
16 mA	STD	0.98	2.31	0.19	0.99	1.37	0.67	2.34	1.86	2.65	3.38	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray

2-28 Revision 16

3.3 V LVCMOS Wide Range

Table 2-40 • Minimum and Maximum DC Input and Output Levels

3.3 V LVCMOS Wide Range	Equivalent Software Default Drive Strength Option ¹	v	'IL	v	IH	VOL	VOH	IOL	ЮН	IOSL	IOSH	IIL ²	IIH ³
Drive Strength		Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	μΑ	μΑ	Max. μΑ ⁴	Max. μΑ ⁴	μ Α ⁵	μ Α ⁵
100 μΑ	2 mA	-0.3	8.0	2	3.6	0.2	VDD – 0.2	100	100	25	27	10	10
100 μΑ	4 mA	-0.3	8.0	2	3.6	0.4	VDD – 0.2	100	100	25	27	10	10
100 μΑ	6 mA	-0.3	8.0	2	3.6	0.4	VDD – 0.2	100	100	51	54	10	10
100 μΑ	8 mA	-0.3	8.0	2	3.6	0.4	VDD – 0.2	100	100	51	54	10	10
100 μΑ	12 mA	-0.3	8.0	2	3.6	0.4	VDD – 0.2	100	100	103	109	10	10
100 μΑ	16 mA	-0.3	0.8	2	3.6	0.4	VDD – 0.2	100	100	103	109	10	10

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 3. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < V CCI. Input current is larger when operating outside recommended ranges.
- 4. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 5. Currents are measured at 85°C junction temperature.
- 6. Software default selection highlighted in gray.

Table 2-41 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	3.3	1.4	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-42 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
100 μΑ	4 mA	STD	0.97	5.85	0.18	1.18	1.64	0.66	5.86	5.05	2.57	2.57	ns
100 μΑ	6 mA	STD	0.97	4.70	0.18	1.18	1.64	0.66	4.72	4.27	2.92	3.19	ns
100 μΑ	8 mA	STD	0.97	4.70	0.18	1.18	1.64	0.66	4.72	4.27	2.92	3.19	ns
100 μΑ	12 mA	STD	0.97	3.96	0.18	1.18	1.64	0.66	3.98	3.70	3.16	3.59	ns
100 μΑ	16 mA	STD	0.97	3.96	0.18	1.18	1.64	0.66	3.98	3.70	3.16	3.59	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-43 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
100 μΑ	4 mA	STD	0.97	3.39	0.18	1.18	1.64	0.66	3.41	2.69	2.57	2.73	ns
100 μΑ	6 mA	STD	0.97	2.79	0.18	1.18	1.64	0.66	2.80	2.17	2.92	3.36	ns
100 μΑ	8 mA	STD	0.97	2.79	0.18	1.18	1.64	0.66	2.80	2.17	2.92	3.36	ns
100 μΑ	12 mA	STD	0.97	2.47	0.18	1.18	1.64	0.66	2.48	1.91	3.16	3.76	ns
100 μΑ	16 mA	STD	0.97	2.47	0.18	1.18	1.64	0.66	2.48	1.91	3.16	3.76	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 3. Software default selection highlighted in gray.

Applies to 1.2 V DC Core Voltage

2-30 Revision 16

Table 2-44 • 3.3 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_{.J} = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
100 μΑ	4 mA	STD	0.98	6.68	0.19	1.32	1.92	0.67	6.68	5.74	3.13	3.47	ns
100 μΑ	6 mA	STD	0.98	5.51	0.19	1.32	1.92	0.67	5.51	4.94	3.48	4.11	ns
100 μΑ	8 mA	STD	0.98	5.51	0.19	1.32	1.92	0.67	5.51	4.94	3.48	4.11	ns
100 μΑ	12 mA	STD	0.98	4.75	0.19	1.32	1.92	0.67	4.75	4.36	3.73	4.52	ns
100 μΑ	16 mA	STD	0.98	4.75	0.19	1.32	1.92	0.67	4.75	4.36	3.73	4.52	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-45 • 3.3 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.7 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
100 μΑ	4 mA	STD	0.98	4.16	0.19	1.32	1.92	0.67	4.16	3.32	3.12	3.66	ns
100 μΑ	6 mA	STD	0.98	3.54	0.19	1.32	1.92	0.67	3.54	2.79	3.48	4.31	ns
100 μΑ	8 mA	STD	0.98	3.54	0.19	1.32	1.92	0.67	3.54	2.79	3.48	4.31	ns
100 μΑ	12 mA	STD	0.98	3.21	0.19	1.32	1.92	0.67	3.21	2.52	3.73	4.73	ns
100 μΑ	16 mA	STD	0.98	3.21	0.19	1.32	1.92	0.67	3.21	2.52	3.73	4.73	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 3.3 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 3. Software default selection highlighted in gray.

2.5 V LVCMOS

Low-Voltage CMOS for 2.5 V is an extension of the LVCMOS standard (JESD8-5) used for generalpurpose 2.5 V applications.

Table 2-46 • Minimum and Maximum DC Input and Output Levels

2.5 V LVCMOS	٧	TL.	V	IH	VOL	VOH	IOL	ЮН	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ³	Max. mA ³	μ Α ⁴	μ Α ⁴
2 mA	-0.3	0.7	1.7	3.6	0.7	1.7	2	2	16	18	10	10
4 mA	-0.3	0.7	1.7	3.6	0.7	1.7	4	4	16	18	10	10
6 mA	-0.3	0.7	1.7	3.6	0.7	1.7	6	6	32	37	10	10
8 mA	-0.3	0.7	1.7	3.6	0.7	1.7	8	8	32	37	10	10
12 mA	-0.3	0.7	1.7	3.6	0.7	1.7	12	12	65	74	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

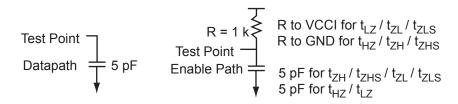


Figure 2-8 • AC Loading

Table 2-47 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	2.5	1.2	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

2-32 Revision 16



Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-48 • 2.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.97	4.44	0.18	1.06	1.22	0.66	4.53	4.15	1.80	1.70	ns
6 mA	STD	0.97	3.61	0.18	1.06	1.22	0.66	3.69	3.50	2.05	2.18	ns
8 mA	STD	0.97	3.61	0.18	1.06	1.22	0.66	3.69	3.50	2.05	2.18	ns
12 mA	STD	0.97	3.07	0.18	1.06	1.22	0.66	3.14	3.03	2.22	2.48	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-49 • 2.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 2.3 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.97	2.41	0.18	1.06	1.22	0.66	2.47	2.22	1.79	1.77	ns
6 mA	STD	0.97	1.99	0.18	1.06	1.22	0.66	2.04	1.75	2.04	2.25	ns
8 mA	STD	0.97	1.99	0.18	1.06	1.22	0.66	2.04	1.75	2.04	2.25	ns
12 mA	STD	0.97	1.77	0.18	1.06	1.22	0.66	1.81	1.51	2.22	2.56	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

Applies to 1.2 V DC Core Voltage

Table 2-50 • 2.5 LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCC_I = 2.3 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
4 mA	STD	0.98	5.04	0.19	1.19	1.40	0.67	5.12	4.65	2.22	2.36	ns
6 mA	STD	0.98	4.19	0.19	1.19	1.40	0.67	4.25	3.98	2.48	2.85	ns
8 mA	STD	0.98	4.19	0.19	1.19	1.40	0.67	4.25	3.98	2.48	2.85	ns
12 mA	STD	0.98	3.63	0.19	1.19	1.40	0.67	3.69	3.50	2.66	3.16	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-51 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 2.3 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t_{LZ}	t _{HZ}	Units
4 mA	STD	0.98	2.96	0.19	1.19	1.40	0.67	3.00	2.67	2.22	2.46	ns
6 mA	STD	0.98	2.52	0.19	1.19	1.40	0.67	2.56	2.18	2.47	2.95	ns
8 mA	STD	0.98	2.52	0.19	1.19	1.40	0.67	2.56	2.18	2.47	2.95	ns
12 mA	STD	0.98	2.29	0.19	1.19	1.40	0.67	2.32	1.94	2.65	3.27	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

1.8 V LVCMOS

Low-voltage CMOS for 1.8 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.8 V applications. It uses a 1.8 V input buffer and a push-pull output buffer.

Table 2-52 • Minimum and Maximum DC Input and Output Levels

1.8 V LVCMOS		VIL	VIH		VOL	VOH	IOL	ЮН	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA	Max., mA ³	Max., mA ³	μ Α ⁴	μ Α ⁴
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI - 0.45	2	2	9	11	10	10
4 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI - 0.45	4	4	17	22	10	10
6 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI-0.45	6	6	35	44	10	10
8 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.45	VCCI-0.45	8	8	35	44	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

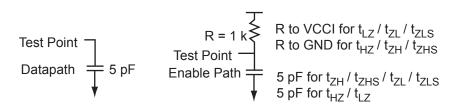


Figure 2-9 • AC Loading

Table 2-53 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	1.8	0.9	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

2-34 Revision 16



Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-54 • 1.8 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t_{PYS}	t _{EOUT}	t_{ZL}	t_{ZH}	t_{LZ}	t_{HZ}	Units
2 mA	STD	0.97	5.89	0.18	1.00	1.43	0.66	6.01	5.43	1.78	1.30	ns
4 mA	STD	0.97	4.82	0.18	1.00	1.43	0.66	4.92	4.56	2.08	2.08	ns
6 mA	STD	0.97	4.13	0.18	1.00	1.43	0.66	4.21	3.96	2.30	2.46	ns
8 mA	STD	0.97	4.13	0.18	1.00	1.43	0.66	4.21	3.96	2.30	2.46	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-55 • 1.8 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_{.J} = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.7 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.97	2.82	0.18	1.00	1.43	0.66	2.88	2.78	1.78	1.35	ns
4 mA	STD	0.97	2.30	0.18	1.00	1.43	0.66	2.35	2.11	2.08	2.15	ns
6 mA	STD	0.97	2.00	0.18	1.00	1.43	0.66	2.04	1.76	2.29	2.55	ns
8 mA	STD	0.97	2.00	0.18	1.00	1.43	0.66	2.04	1.76	2.29	2.55	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

Applies to 1.2 V DC Core Voltage

Table 2-56 • 1.8 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	6.43	0.19	1.12	1.61	0.67	6.54	5.93	2.19	1.88	ns
4 mA	STD	0.98	5.33	0.19	1.12	1.61	0.67	5.41	5.03	2.50	2.68	ns
6 mA	STD	0.98	4.61	0.19	1.12	1.61	0.67	4.69	4.41	2.72	3.07	ns
8 mA	STD	0.98	4.61	0.19	1.12	1.61	0.67	4.69	4.41	2.72	3.07	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-57 • 1.8 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.7 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	3.30	0.19	1.12	1.61	0.67	3.34	3.21	2.19	1.93	ns
4 mA	STD	0.98	2.76	0.19	1.12	1.61	0.67	2.79	2.51	2.50	2.76	ns
6 mA	STD	0.98	2.45	0.19	1.12	1.61	0.67	2.48	2.16	2.71	3.16	ns
8 mA	STD	0.98	2.45	0.19	1.12	1.61	0.67	2.48	2.16	2.71	3.16	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

1.5 V LVCMOS (JESD8-11)

Low-Voltage CMOS for 1.5 V is an extension of the LVCMOS standard (JESD8-5) used for general-purpose 1.5 V applications. It uses a 1.5 V input buffer and a push-pull output buffer.

Table 2-58 • Minimum and Maximum DC Input and Output Levels

1.5 V LVCMOS		VIL	VIH		VOL	VOH	IOL	ЮН	IOSL	IOSH	IIL ¹	IIH ²
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mΑ	mA	Max. mA ³	Max. mA ³	μ Α ⁴	μ Α ⁴
2 mA	-0.3	0.35 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2	13	16	10	10
4 mA	-0.3	0.35 * VCCI	0.7 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	4	4	25	33	10	10

Notes:

- 1. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 2. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 3. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 4. Currents are measured at 85°C junction temperature.
- 5. Software default selection highlighted in gray.

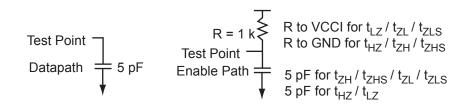


Figure 2-10 • AC Loading

Table 2-59 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	1.5	0.75	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

2-36 Revision 16

Timing Characteristics

Applies to 1.5 V DC Core Voltage

Table 2-60 • 1.5 V LVCMOS Low Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.97	6.07	0.18	1.16	1.62	0.66	6.19	5.53	2.13	2.02	ns
4 mA	STD	0.97	5.24	0.18	1.16	1.62	0.66	5.34	4.81	2.37	2.47	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-61 • 1.5 V LVCMOS High Slew – Applies to 1.5 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 1.4 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.97	2.65	0.18	1.16	1.62	0.66	2.71	2.43	2.13	2.11	ns
4 mA	STD	0.97	2.29	0.18	1.16	1.62	0.66	2.33	2.00	2.37	2.57	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

Applies to 1.2 V DC Core Voltage

Table 2-62 • 1.5 V LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	6.57	0.19	1.26	1.80	0.67	6.68	6.01	2.54	2.59	ns
4 mA	STD	0.98	5.72	0.19	1.26	1.80	0.67	5.81	5.27	2.79	3.05	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-63 • 1.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.4 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	3.08	0.19	1.26	1.80	0.67	3.13	2.82	2.53	2.68	ns
4 mA	STD	0.98	2.71	0.19	1.26	1.80	0.67	2.75	2.39	2.78	3.15	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.



1.2 V LVCMOS (JESD8-12A)

Low-Voltage CMOS for 1.2 V complies with the LVCMOS standard JESD8-12A for general purpose 1.2 V applications. It uses a 1.2 V input buffer and a push-pull output buffer.

Table 2-64 • Minimum and Maximum DC Input and Output Levels

1.2 V LVCMOS ¹		VIL	VIH		VOL	VOH	IOL	ЮН	IOSL	IOSH	IIL ²	IIH ³
Drive Strength	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ⁴	Max. mA ⁴	μ Α ⁵	μ Α ⁵
2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2	20	26	10	10

Notes:

- 1. Applicable to IGLOO nano V2 devices operating at VCCI ≥ VCC.
- 2. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 3. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 4. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 5. Currents are measured at 85°C junction temperature.
- 6. Software default selection highlighted in gray.

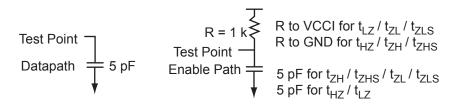


Figure 2-11 • AC Loading

Table 2-65 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	1.2	0.6	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

Timing Characteristics

Applies to 1.2 V DC Core Voltage

Table 2-66 • 1.2 V LVCMOS Low Slew

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	8.27	0.19	1.57	2.34	0.67	7.94	6.77	3.00	3.11	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-67 • 1.2 V LVCMOS High Slew

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V

Drive Strength	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
2 mA	STD	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns

Notes:

- 1. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 2. Software default selection highlighted in gray.

2-38 Revision 16



1.2 V LVCMOS Wide Range

Table 2-68 • Minimum and Maximum DC Input and Output Levels

1.2 V LVCMOS Range ¹	Wide		VIL	VIH		VOL	VOH	IOL	ЮН	IOSL	юзн	IIL ³	IIH ⁴
Drive Strength	Equivalent Software Default Drive Strength Option ²	Min. V	Max. V	Min. V	Max. V	Max. V	Min. V	mA	mA	Max. mA ⁵	Max mA ⁵	μ Α ⁶	μ Α ⁶
100 μΑ	2 mA	-0.3	0.35 * VCCI	0.65 * VCCI	3.6	0.25 * VCCI	0.75 * VCCI	2	2	20	26	10	10

Notes:

- 1. Applicable to V2 devices only.
- 2. The minimum drive strength for any LVCMOS 1.2 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 3. IIL is the input leakage current per I/O pin over recommended operation conditions where -0.3 V < VIN < VIL.
- 4. IIH is the input leakage current per I/O pin over recommended operating conditions VIH < VIN < VCCI. Input current is larger when operating outside recommended ranges.
- 5. Currents are measured at high temperature (100°C junction temperature) and maximum voltage.
- 6. Currents are measured at 85°C junction temperature.
- 7. Software default selection highlighted in gray.

Table 2-69 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	C _{LOAD} (pF)
0	1.2	0.6	5

Note: *Measuring point = Vtrip. See Table 2-23 on page 2-21 for a complete table of trip points.

Timing Characteristics

Applies to 1.2 V DC Core Voltage

Table 2-70 • 1.2 V LVCMOS Wide Range Low Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
100 μΑ	2 mA	STD	0.98	8.27	0.19	1.57	2.34	0.67	7.94	6.77	3.00	3.11	ns

Notes:

- 1. The minimum drive strength for any LVCMOS 1.2 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-71 • 1.2 V LVCMOS Wide Range High Slew – Applies to 1.2 V DC Core Voltage

Commercial-Case Conditions: T_{.I} = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 1.14 V

Drive Strength	Equivalent Software Default Drive Strength Option ¹	Speed Grade	t _{DOUT}	t _{DP}	t _{DIN}	t _{PY}	t _{PYS}	t _{EOUT}	t _{ZL}	t _{ZH}	t _{LZ}	t _{HZ}	Units
100 μΑ	2 mA	STD	0.98	3.38	0.19	1.57	2.34	0.67	3.26	2.78	2.99	3.24	ns

Notes:

- The minimum drive strength for any LVCMOS 1.2 V software configuration when run in wide range is ±100 μA. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.
- 3. Software default selection highlighted in gray.

2-40 Revision 16



I/O Register Specifications

Fully Registered I/O Buffers with Asynchronous Preset

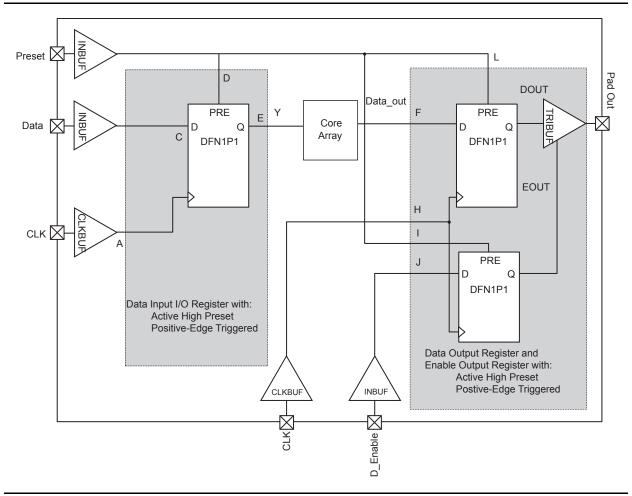


Figure 2-12 • Timing Model of Registered I/O Buffers with Asynchronous Preset

Table 2-72 • Parameter Definition and Measuring Nodes

Parameter Name	Parameter Definition	Measuring Nodes (from, to)*
t _{OCLKQ}	Clock-to-Q of the Output Data Register	H, DOUT
tosup	Data Setup Time for the Output Data Register	F, H
t _{OHD}	Data Hold Time for the Output Data Register	F, H
t _{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	L, DOUT
t _{OREMPRE}	Asynchronous Preset Removal Time for the Output Data Register	L, H
t _{ORECPRE}	Asynchronous Preset Recovery Time for the Output Data Register	L, H
t _{OECLKQ}	Clock-to-Q of the Output Enable Register	H, EOUT
t _{OESUD}	Data Setup Time for the Output Enable Register	J, H
t _{OEHD}	Data Hold Time for the Output Enable Register	J, H
t _{OEPRE2Q}	Asynchronous Preset-to-Q of the Output Enable Register	I, EOUT
t _{OEREMPRE}	Asynchronous Preset Removal Time for the Output Enable Register	I, H
t _{OERECPRE}	Asynchronous Preset Recovery Time for the Output Enable Register	I, H
t _{ICLKQ}	Clock-to-Q of the Input Data Register	A, E
t _{ISUD}	Data Setup Time for the Input Data Register	C, A
t _{IHD}	Data Hold Time for the Input Data Register	C, A
t _{IPRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	D, E
t _{IREMPRE}	Asynchronous Preset Removal Time for the Input Data Register	D, A
t _{IRECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	D, A

Note: *See Figure 2-12 on page 2-41 for more information.

2-42 Revision 16

Fully Registered I/O Buffers with Asynchronous Clear

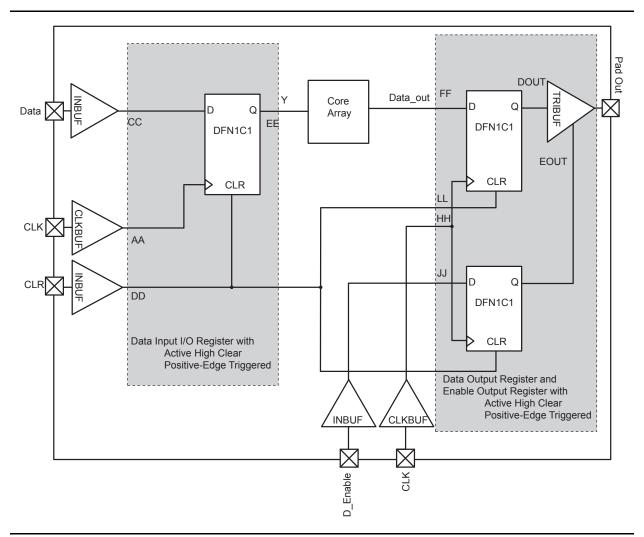


Figure 2-13 • Timing Model of the Registered I/O Buffers with Asynchronous Clear

Table 2-73 • Parameter Definition and Measuring Nodes

Parameter Name	Parameter Definition	Measuring Nodes (from, to)*
t _{OCLKQ}	Clock-to-Q of the Output Data Register	HH, DOUT
tosud	Data Setup Time for the Output Data Register	FF, HH
t _{OHD}	Data Hold Time for the Output Data Register	FF, HH
t _{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	LL, DOUT
t _{OREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	LL, HH
t _{ORECCLR}	Asynchronous Clear Recovery Time for the Output Data Register	LL, HH
t _{OECLKQ}	Clock-to-Q of the Output Enable Register	HH, EOUT
t _{OESUD}	Data Setup Time for the Output Enable Register	JJ, HH
t _{OEHD}	Data Hold Time for the Output Enable Register	JJ, HH
t _{OECLR2Q}	Asynchronous Clear-to-Q of the Output Enable Register	II, EOUT
t _{OEREMCLR}	Asynchronous Clear Removal Time for the Output Enable Register	II, HH
toerecclr	Asynchronous Clear Recovery Time for the Output Enable Register	II, HH
t _{ICLKQ}	Clock-to-Q of the Input Data Register	AA, EE
t _{ISUD}	Data Setup Time for the Input Data Register	CC, AA
t _{IHD}	Data Hold Time for the Input Data Register	CC, AA
t _{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	DD, EE
t _{IREMCLR}	Asynchronous Clear Removal Time for the Input Data Register	DD, AA
t _{IRECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	DD, AA

Note: *See Figure 2-13 on page 2-43 for more information.

2-44 Revision 16

Input Register

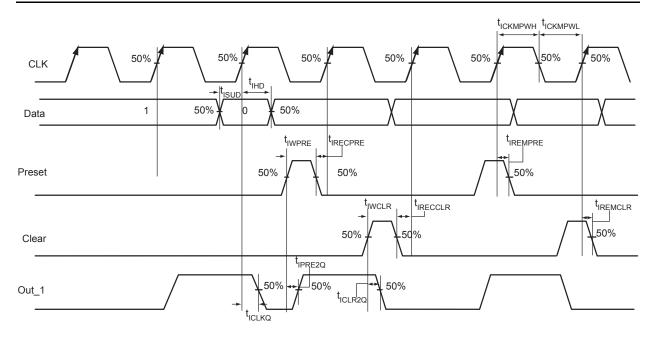


Figure 2-14 • Input Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-74 • Input Data Register Propagation Delays

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{ICLKQ}	Clock-to-Q of the Input Data Register	0.41	ns
t _{ISUD}	Data Setup Time for the Input Data Register	0.32	ns
t _{IHD}	Data Hold Time for the Input Data Register	0.00	ns
t _{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	0.57	ns
t _{IPRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	0.57	ns
t _{IREMCLR}	Asynchronous Clear Removal Time for the Input Data Register	0.00	ns
t _{IRECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	0.24	ns
t _{IREMPRE}	Asynchronous Preset Removal Time for the Input Data Register	0.00	ns
t _{IRECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	0.24	ns
t _{IWCLR}	Asynchronous Clear Minimum Pulse Width for the Input Data Register	0.19	ns
t _{IWPRE}	Asynchronous Preset Minimum Pulse Width for the Input Data Register	0.19	ns
t _{ICKMPWH}	Clock Minimum Pulse Width High for the Input Data Register	0.31	ns
t _{ICKMPWL}	Clock Minimum Pulse Width Low for the Input Data Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-75 • Input Data Register Propagation Delays Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{ICLKQ}	Clock-to-Q of the Input Data Register	0.66	ns
t _{ISUD}	Data Setup Time for the Input Data Register	0.43	ns
t _{IHD}	Data Hold Time for the Input Data Register	0.00	ns
t _{ICLR2Q}	Asynchronous Clear-to-Q of the Input Data Register	0.86	ns
t _{IPRE2Q}	Asynchronous Preset-to-Q of the Input Data Register	0.86	ns
t _{IREMCLR}	Asynchronous Clear Removal Time for the Input Data Register	0.00	ns
t _{IRECCLR}	Asynchronous Clear Recovery Time for the Input Data Register	0.24	ns
t _{IREMPRE}	Asynchronous Preset Removal Time for the Input Data Register	0.00	ns
t _{IRECPRE}	Asynchronous Preset Recovery Time for the Input Data Register	0.24	ns
t _{IWCLR}	Asynchronous Clear Minimum Pulse Width for the Input Data Register	0.19	ns
t _{IWPRE}	Asynchronous Preset Minimum Pulse Width for the Input Data Register	0.19	ns
t _{ICKMPWH}	Clock Minimum Pulse Width High for the Input Data Register	0.31	ns
t _{ICKMPWL}	Clock Minimum Pulse Width Low for the Input Data Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

2-46 Revision 16

Output Register

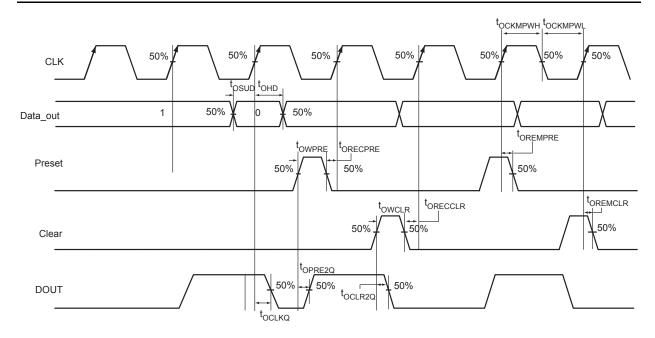


Figure 2-15 • Output Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-76 • Output Data Register Propagation Delays
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{OCLKQ}	Clock-to-Q of the Output Data Register	0.66	ns
tosup	Data Setup Time for the Output Data Register	0.33	ns
t _{OHD}	Data Hold Time for the Output Data Register	0.00	ns
t _{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	0.82	ns
t _{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	0.88	ns
t _{OREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	0.00	ns
torecclr	Asynchronous Clear Recovery Time for the Output Data Register	0.24	ns
t _{OREMPRE}	Asynchronous Preset Removal Time for the Output Data Register	0.00	ns
t _{ORECPRE}	Asynchronous Preset Recovery Time for the Output Data Register	0.24	ns
towclr	Asynchronous Clear Minimum Pulse Width for the Output Data Register	0.19	ns
t _{OWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Data Register	0.19	ns
tockmpwh	Clock Minimum Pulse Width High for the Output Data Register	0.31	ns
tockmpwl	Clock Minimum Pulse Width Low for the Output Data Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-77 • Output Data Register Propagation Delays
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{OCLKQ}	Clock-to-Q of the Output Data Register	1.03	ns
tosud	Data Setup Time for the Output Data Register	0.52	ns
t _{OHD}	Data Hold Time for the Output Data Register	0.00	ns
t _{OCLR2Q}	Asynchronous Clear-to-Q of the Output Data Register	1.22	ns
t _{OPRE2Q}	Asynchronous Preset-to-Q of the Output Data Register	1.31	ns
t _{OREMCLR}	Asynchronous Clear Removal Time for the Output Data Register	0.00	ns
torecclr	Asynchronous Clear Recovery Time for the Output Data Register	0.24	ns
t _{OREMPRE}	Asynchronous Preset Removal Time for the Output Data Register	0.00	ns
torecpre	Asynchronous Preset Recovery Time for the Output Data Register	0.24	ns
towclr	Asynchronous Clear Minimum Pulse Width for the Output Data Register	0.19	ns
t _{OWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Data Register	0.19	ns
tockmpwh	Clock Minimum Pulse Width High for the Output Data Register	0.31	ns
tockmpwl	Clock Minimum Pulse Width Low for the Output Data Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

2-48 Revision 16

Output Enable Register

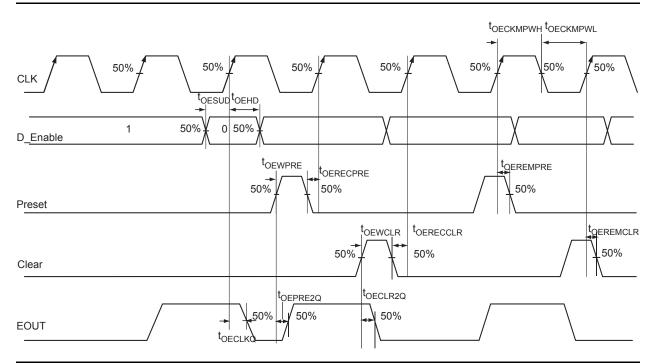


Figure 2-16 • Output Enable Register Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-78 • Output Enable Register Propagation Delays

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V

toesud Data Setup Time for the Output Enable Register 0.33 toehd Data Hold Time for the Output Enable Register 0.00 toeclr2Q Asynchronous Clear-to-Q of the Output Enable Register 0.84 toepre2Q Asynchronous Preset-to-Q of the Output Enable Register 0.91 toeremclr Asynchronous Clear Removal Time for the Output Enable Register 0.00 toeremclr Asynchronous Clear Removal Time for the Output Enable Register 0.00 toereclr Asynchronous Clear Recovery Time for the Output Enable Register 0.24 toerempre Asynchronous Preset Removal Time for the Output Enable Register 0.00 toerecpre Asynchronous Preset Recovery Time for the Output Enable Register 0.24 toerecpre Asynchronous Preset Recovery Time for the Output Enable Register 0.24 toewclr Asynchronous Preset Recovery Time for the Output Enable Register 0.19 toewclr Asynchronous Preset Minimum Pulse Width for the Output Enable Register 0.19	rameter	Description	Std.	Units
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toeclas described asynchronous Clear-to-Q of the Output Enable Register 0.84 toepresquare Asynchronous Preset-to-Q of the Output Enable Register 0.91 toered Asynchronous Clear Removal Time for the Output Enable Register 0.00 toered Asynchronous Clear Recovery Time for the Output Enable Register 0.24 toered Asynchronous Preset Removal Time for the Output Enable Register 0.00 toered Asynchronous Preset Recovery Time for the Output Enable Register 0.00 toered Asynchronous Preset Recovery Time for the Output Enable Register 0.24 toewclr Asynchronous Clear Minimum Pulse Width for the Output Enable Register 0.19 toewpre Asynchronous Preset Minimum Pulse Width for the Output Enable Register 0.19	SUD	Data Setup Time for the Output Enable Register	0.33	ns
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tober tober 2 degree tobe 2 degree tober 2 degree t	CLR2Q	Asynchronous Clear-to-Q of the Output Enable Register	0.84	ns
toereccle Asynchronous Clear Recovery Time for the Output Enable Register 0.24 toered Asynchronous Preset Removal Time for the Output Enable Register 0.00 toered Asynchronous Preset Recovery Time for the Output Enable Register 0.24 toewclr Asynchronous Clear Minimum Pulse Width for the Output Enable Register 0.19 toewcr Asynchronous Preset Minimum Pulse Width for the Output Enable Register 0.19	PRE2Q	Asynchronous Preset-to-Q of the Output Enable Register	0.91	ns
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toereche Asynchronous Preset Recovery Time for the Output Enable Register 0.24 toewclr Asynchronous Clear Minimum Pulse Width for the Output Enable Register 0.19 toewpre Asynchronous Preset Minimum Pulse Width for the Output Enable Register 0.19	RECCLR	Asynchronous Clear Recovery Time for the Output Enable Register	0.24	ns
t _{OEWCLR} Asynchronous Clear Minimum Pulse Width for the Output Enable Register 0.19 t _{OEWPRE} Asynchronous Preset Minimum Pulse Width for the Output Enable Register 0.19	REMPRE	Asynchronous Preset Removal Time for the Output Enable Register	0.00	ns
t _{OEWPRE} Asynchronous Preset Minimum Pulse Width for the Output Enable Register 0.19	RECPRE '	Asynchronous Preset Recovery Time for the Output Enable Register	0.24	ns
OLWINE 7	WCLR	Asynchronous Clear Minimum Pulse Width for the Output Enable Register	0.19	ns
0 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	WPRE	Asynchronous Preset Minimum Pulse Width for the Output Enable Register	0.19	ns
Toeckmpwh Clock Minimum Pulse Width High for the Output Enable Register 0.31	CKMPWH	Clock Minimum Pulse Width High for the Output Enable Register	0.31	ns
t _{OECKMPWL} Clock Minimum Pulse Width Low for the Output Enable Register 0.28	CKMPWL	Clock Minimum Pulse Width Low for the Output Enable Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-79 • Output Enable Register Propagation Delays
Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{OECLKQ}	Clock-to-Q of the Output Enable Register	1.06	ns
t _{OESUD}	Data Setup Time for the Output Enable Register	0.52	ns
t _{OEHD}	Data Hold Time for the Output Enable Register	0.00	ns
t _{OECLR2Q}	Asynchronous Clear-to-Q of the Output Enable Register	1.25	ns
t _{OEPRE2Q}	Asynchronous Preset-to-Q of the Output Enable Register	1.36	ns
t _{OEREMCLR}	Asynchronous Clear Removal Time for the Output Enable Register	0.00	ns
toerecclr	Asynchronous Clear Recovery Time for the Output Enable Register	0.24	ns
t _{OEREMPRE}	Asynchronous Preset Removal Time for the Output Enable Register	0.00	ns
t _{OERECPRE}	Asynchronous Preset Recovery Time for the Output Enable Register	0.24	ns
t _{OEWCLR}	Asynchronous Clear Minimum Pulse Width for the Output Enable Register	0.19	ns
t _{OEWPRE}	Asynchronous Preset Minimum Pulse Width for the Output Enable Register	0.19	ns
t _{OECKMPWH}	Clock Minimum Pulse Width High for the Output Enable Register	0.31	ns
t _{OECKMPWL}	Clock Minimum Pulse Width Low for the Output Enable Register	0.28	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

2-50 Revision 16

VersaTile Characteristics

VersaTile Specifications as a Combinatorial Module

The IGLOO PLUS library offers all combinations of LUT-3 combinatorial functions. In this section, timing characteristics are presented for a sample of the library. For more details, refer to the *Fusion, IGLOO/e, and ProASIC3/ E Macro Library Guide*.

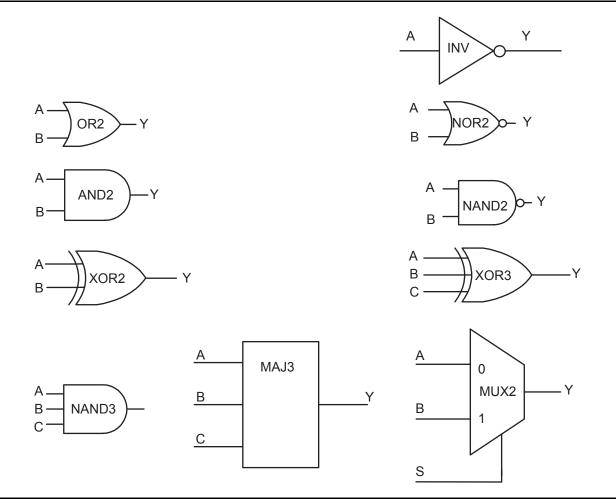


Figure 2-17 • Sample of Combinatorial Cells



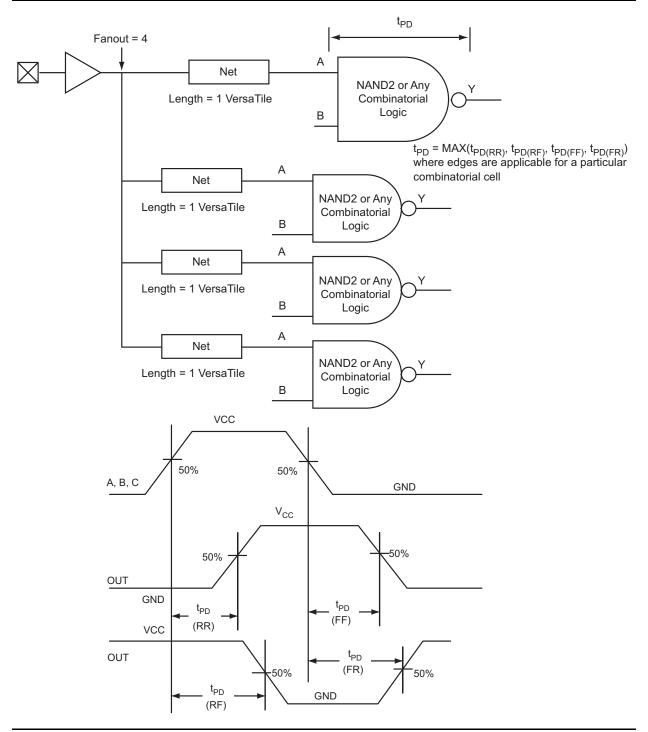


Figure 2-18 • Timing Model and Waveforms

2-52 Revision 16



Timing Characteristics

1.5 V DC Core Voltage

Table 2-80 • Combinatorial Cell Propagation Delays Commercial-Case Conditions: $T_J = 70^{\circ}$ C, Worst-Case VCC = 1.425 V

Combinatorial Cell	Equation	Parameter	Std.	Units
INV	Y = !A	t _{PD}	0.72	ns
AND2	Y = A · B	t _{PD}	0.86	ns
NAND2	Y = !(A · B)	t _{PD}	1.00	ns
OR2	Y = A + B	t _{PD}	1.26	ns
NOR2	Y = !(A + B)	t _{PD}	1.16	ns
XOR2	Y = A ⊕ B	t _{PD}	1.46	ns
MAJ3	Y = MAJ(A, B, C)	t _{PD}	1.47	ns
XOR3	Y = A ⊕ B ⊕ C	t _{PD}	2.12	ns
MUX2	Y = A !S + B S	t _{PD}	1.24	ns
AND3	$Y = A \cdot B \cdot C$	t _{PD}	1.40	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-81 • Combinatorial Cell Propagation Delays

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V

Combinatorial Cell	Equation	Parameter	Std.	Units
INV	Y = !A	t _{PD}	1.26	ns
AND2	Y = A · B	t _{PD}	1.46	ns
NAND2	Y = !(A · B)	t _{PD}	1.78	ns
OR2	Y = A + B	t _{PD}	2.47	ns
NOR2	Y = !(A + B)	t _{PD}	2.17	ns
XOR2	Y = A ⊕ B	t _{PD}	2.62	ns
MAJ3	Y = MAJ(A, B, C)	t _{PD}	2.66	ns
XOR3	Y = A ⊕ B ⊕ C	t _{PD}	3.77	ns
MUX2	Y = A !S + B S	t _{PD}	2.20	ns
AND3	$Y = A \cdot B \cdot C$	t _{PD}	2.49	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

VersaTile Specifications as a Sequential Module

The IGLOO PLUS library offers a wide variety of sequential cells, including flip-flops and latches. Each has a data input and optional enable, clear, or preset. In this section, timing characteristics are presented for a representative sample from the library. For more details, refer to the *Fusion, IGLOO/e, and ProASIC3/E Macro Library Guide*.

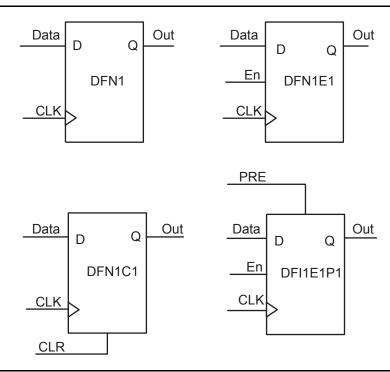


Figure 2-19 • Sample of Sequential Cells

2-54 Revision 16

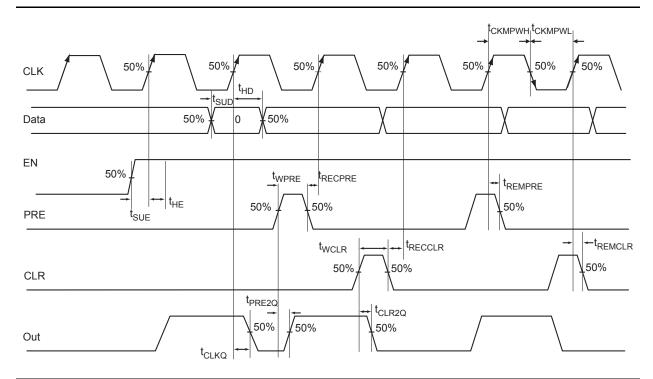


Figure 2-20 • Timing Model and Waveforms

Timing Characteristics 1.5 V DC Core Voltage

Table 2-82 • Register Delays Commercial-Case Conditions: $T_J = 70$ °C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{CLKQ}	Clock-to-Q of the Core Register	0.89	ns
t _{SUD}	Data Setup Time for the Core Register	0.81	ns
t _{HD}	Data Hold Time for the Core Register	0.00	ns
t _{SUE}	Enable Setup Time for the Core Register	0.73	ns
t _{HE}	Enable Hold Time for the Core Register	0.00	ns
t _{CLR2Q}	Asynchronous Clear-to-Q of the Core Register	0.60	ns
t _{PRE2Q}	Asynchronous Preset-to-Q of the Core Register	0.62	ns
t _{REMCLR}	Asynchronous Clear Removal Time for the Core Register	0.00	ns
t _{RECCLR}	Asynchronous Clear Recovery Time for the Core Register	0.24	ns
t _{REMPRE}	Asynchronous Preset Removal Time for the Core Register	0.00	ns
t _{RECPRE}	Asynchronous Preset Recovery Time for the Core Register	0.23	ns
t _{WCLR}	Asynchronous Clear Minimum Pulse Width for the Core Register	0.30	ns
t _{WPRE}	Asynchronous Preset Minimum Pulse Width for the Core Register	0.30	ns
t _{CKMPWH}	Clock Minimum Pulse Width High for the Core Register	0.56	ns
t _{CKMPWL}	Clock Minimum Pulse Width Low for the Core Register	0.56	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-83 • Register Delays

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{CLKQ}	Clock-to-Q of the Core Register	1.61	ns
t _{SUD}	Data Setup Time for the Core Register	1.17	ns
t _{HD}	Data Hold Time for the Core Register	0.00	ns
t _{SUE}	Enable Setup Time for the Core Register	1.29	ns
t _{HE}	Enable Hold Time for the Core Register	0.00	ns
t _{CLR2Q}	Asynchronous Clear-to-Q of the Core Register	0.87	ns
t _{PRE2Q}	Asynchronous Preset-to-Q of the Core Register	0.89	ns
t _{REMCLR}	Asynchronous Clear Removal Time for the Core Register	0.00	ns
t _{RECCLR}	Asynchronous Clear Recovery Time for the Core Register	0.24	ns
t _{REMPRE}	Asynchronous Preset Removal Time for the Core Register	0.00	ns
t _{RECPRE}	Asynchronous Preset Recovery Time for the Core Register	0.24	ns
t _{WCLR}	Asynchronous Clear Minimum Pulse Width for the Core Register	0.46	ns
t _{WPRE}	Asynchronous Preset Minimum Pulse Width for the Core Register	0.46	ns
t _{CKMPWH}	Clock Minimum Pulse Width High for the Core Register	0.95	ns
t _{CKMPWL}	Clock Minimum Pulse Width Low for the Core Register	0.95	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

2-56 Revision 16

Global Resource Characteristics

AGLP125 Clock Tree Topology

Clock delays are device-specific. Figure 2-21 is an example of a global tree used for clock routing. The global tree presented in Figure 2-21 is driven by a CCC located on the west side of the AGLP125 device. It is used to drive all D-flip-flops in the device.

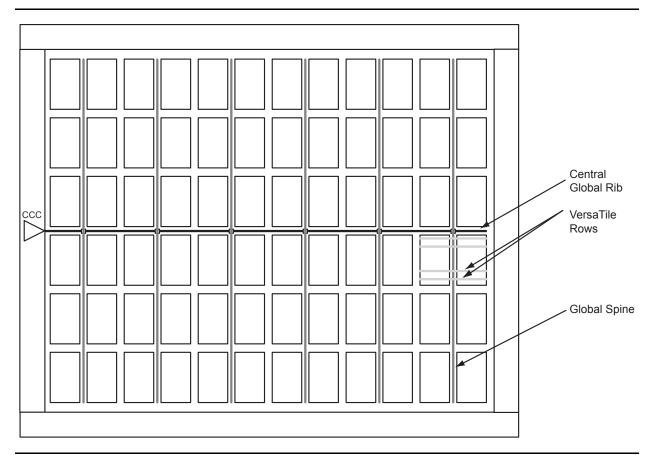


Figure 2-21 • Example of Global Tree Use in an AGLP125 Device for Clock Routing

Global Tree Timing Characteristics

Global clock delays include the central rib delay, the spine delay, and the row delay. Delays do not include I/O input buffer clock delays, as these are I/O standard–dependent, and the clock may be driven and conditioned internally by the CCC module. For more details on clock conditioning capabilities, refer to the "Clock Conditioning Circuits" section on page 2-61. Table 2-84 to Table 2-89 on page 2-60 present minimum and maximum global clock delays within each device. Minimum and maximum delays are measured with minimum and maximum loading.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-84 • AGLP030 Global Resource

Commercial-Case Conditions: T_{.I} = 70°C, VCC = 1.425 V

		S	Std.	
Parameter	Description	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock	1.21	1.42	ns
t _{RCKH}	Input High Delay for Global Clock	1.23	1.49	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock	1.18		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock	1.15		ns
t _{RCKSW}	Maximum Skew for Global Clock		0.27	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

Table 2-85 • AGLP060 Global Resource Commercial-Case Conditions: T_{.I} = 70°C, VCC = 1.425 V

		Std.		
Parameter	Description	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock	1.32	1.62	ns
t _{RCKH}	Input High Delay for Global Clock	1.34	1.72	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock	1.18		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock	1.15		ns
t _{RCKSW}	Maximum Skew for Global Clock		0.38	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2-58 Revision 16



Table 2-86 • AGLP125 Global Resource Commercial-Case Conditions: T_J = 70°C, VCC = 1.425 V

			Std.		
Parameter	Description	Mir	1. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock	1.3	36	1.71	ns
t _{RCKH}	Input High Delay for Global Clock	1.3	39	1.82	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock	1.	18		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock	1.	15		ns
t _{RCKSW}	Maximum Skew for Global Clock			0.43	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-87 • AGLP030 Global Resource

Commercial-Case Conditions: T_J = 70°C, VCC = 1.14 V

			Std.		
Parameter	Description	-	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock		1.80	2.09	ns
t _{RCKH}	Input High Delay for Global Clock		1.88	2.27	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock		1.40		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock		1.65		ns
t _{RCKSW}	Maximum Skew for Global Clock			0.39	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-88 • AGLP060 Global Resource Commercial-Case Conditions: $T_J = 70^{\circ}C$, VCC = 1.14 V

			Std.		
Parameter	Description	•	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock		2.02	2.43	ns
t _{RCKH}	Input High Delay for Global Clock		2.09	2.65	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock		1.40		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock		1.65		ns
t _{RCKSW}	Maximum Skew for Global Clock			0.56	ns

Notes:

- 1. Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Table 2-89 • AGLP125 Global Resource
Commercial-Case Conditions: T_J = 70°C, VCC = 1.14 V

		Std.		
Parameter	Description	Min. ¹	Max. ²	Units
t _{RCKL}	Input Low Delay for Global Clock	2.08	2.54	ns
t _{RCKH}	Input High Delay for Global Clock	2.15	2.77	ns
t _{RCKMPWH}	Minimum Pulse Width High for Global Clock	1.40		ns
t _{RCKMPWL}	Minimum Pulse Width Low for Global Clock	1.65		ns
t _{RCKSW}	Maximum Skew for Global Clock		0.62	ns

Notes:

- Value reflects minimum load. The delay is measured from the CCC output to the clock pin of a sequential element, located in a lightly loaded row (single element is connected to the global net).
- 2. Value reflects maximum load. The delay is measured on the clock pin of the farthest sequential element, located in a fully loaded row (all available flip-flops are connected to the global net in the row).
- 3. For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

2-60 Revision 16



Clock Conditioning Circuits

CCC Electrical Specifications

Timing Characteristics

Table 2-90 • IGLOO PLUS CCC/PLL Specification For IGLOO PLUS V2 or V5 devices, 1.5 V DC Core Supply Voltage

Parameter	Min.	Тур.	Max.	Units	
Clock Conditioning Circuitry Input Frequency f _{IN_CCC}	1.5		250	MHz	
Clock Conditioning Circuitry Output Frequency f _{OUT_CCC}	0.75		250	MHz	
Delay Increments in Programmable Delay Blocks ^{1, 2}		360 ³		ps	
Number of Programmable Values in Each Programmable Delay Block			32		
Serial Clock (SCLK) for Dynamic PLL ^{4,5}			100	MHz	
Input Cycle-to-Cycle Jitter (peak magnitude)			1	ns	
Acquisition Time					
LockControl = 0			300	μs	
LockControl = 1			6.0	ms	
Tracking Jitter ⁶					
LockControl = 0			2.5	ns	
LockControl = 1			1.5	ns	
Output Duty Cycle	48.5		51.5	%	
Delay Range in Block: Programmable Delay 1 ^{1, 2}	1.25		15.65	ns	
Delay Range in Block: Programmable Delay 2 ^{1, 2}	0.469		15.65	ns	
Delay Range in Block: Fixed Delay ^{1, 2}		3.5		ns	
VCO Output Peak-to-Peak Period Jitter F _{CCC_OUT} ⁷	Maximu	m Peak-to-	o-Peak Period Jitter ^{7,8,9}		
	SSO ≤ 2	SSO ≤ 4	SSO ≤ 8	SSO ≤ 16	
0.75 MHz to 50 MHz	0.50%	0.60%	0.80%	1.20%	
50 MHz to 250 MHz	2.50%	4.00%	6.00%	12.00%	

Notes:

- 1. This delay is a function of voltage and temperature. See Table 2-6 on page 2-6 and Table 2-7 on page 2-7 for deratings.
- 2. $T_{.I} = 25^{\circ}C$, VCC = 1.5 V
- 3. When the CCC/PLL core is generated by Microsemi core generator software, not all delay values of the specified delay increments are available. Refer to the Libero SoC Online Help associated with the core for more information.
- 4. Maximum value obtained for a STD speed grade device in Worst Case Commercial Conditions. For specific junction temperature and voltage supply, refer to Table 2-6 on page 2-6 and Table 2-7 on page 2-7 for derating values.
- 5. The AGLP030 device does not support a PLL.
- 6. Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to the PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by the period jitter parameter.
- 7. VCO output jitter is calculated as a percentage of the VCO frequency. The jitter (in ps) can be calculated by multiplying the VCO period by the per cent jitter. The VCO jitter (in ps) applies to CCC_OUT regardless of the output divider settings. For example, if the jitter on VCO is 300 ps, the jitter on CCC_OUT is also 300 ps, regardless of the output divider settings.
- 8. Measurements done with LVTTL 3.3 V 8 mA I/O drive strength and high slew rate, VCC/VCCPLL = 1.425 V, VCCI = 3.3 V, VQ/PQ/TQ type of packages, 20 pF load.
- 9. SSO are outputs that are synchronous to a single clock domain and have clock-to-out times that are within ±200 ps of each other. Switching I/Os are placed outside of the PLL bank. Refer to the "Simultaneously Switching Outputs (SSOs) and Printed Circuit Board Layout" section in the IGLOO PLUS FPGA Fabric User's Guide.

Table 2-91 • IGLOO PLUS CCC/PLL Specification
For IGLOO PLUS V2 Devices, 1.2 V DC Core Supply Voltage

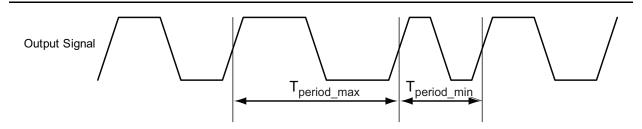
Parameter	Min.	Тур.	Max.	Units	
Clock Conditioning Circuitry Input Frequency f _{IN_CCC}	1.5		160	MHz	
Clock Conditioning Circuitry Output Frequency f _{OUT_CCC}	0.75		160	MHz	
Delay Increments in Programmable Delay Blocks ^{1, 2}		580 ³		ps	
Number of Programmable Values in Each Programmable Delay Block			32		
Serial Clock (SCLK) for Dynamic PLL ^{4,5}			60	MHz	
Input Cycle-to-Cycle Jitter (peak magnitude)			.25	ns	
Acquisition Time					
LockControl = 0			300	μs	
LockControl = 1			6.0	ms	
Tracking Jitter ⁶					
LockControl = 0			4	ns	
LockControl = 1			3	ns	
Output Duty Cycle	48.5		51.5	%	
Delay Range in Block: Programmable Delay 1 ^{1, 2}	2.3		20.86	ns	
Delay Range in Block: Programmable Delay 2 ^{1, 2}	0.863		20.86	ns	
Delay Range in Block: Fixed Delay ^{1, 2}		5.7		ns	
VCO Output Peak-to-Peak Period Jitter F _{CCC_OUT} ⁷	Maximu	ım Peak-to-F	Peak-to-Peak Period Jitter ^{7,8,9}		
	SSO ≤ 2	SSO ≤ 4	SSO ≤ 8	SSO ≤ 16	
0.75 MHz to 50 MHz	0.50%	1.20%	2.00%	3.00%	
50 MHz to 160 MHz	2.50%	5.00%	7.00%	15.00%	

Notes:

- 1. This delay is a function of voltage and temperature. See Table 2-6 on page 2-6 and Table 2-7 on page 2-7 for deratings.
- 2. $T_{.J} = 25^{\circ}C$, VCC = 1.2 V
- 3. When the CCC/PLL core is generated by Microsemi core generator software, not all delay values of the specified delay increments are available. Refer to the online help associated with the core for more information.
- 4. Maximum value obtained for a STD speed grade device in Worst Case Commercial Conditions. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 and Table 2-7 on page 2-7 for derating values.
- 5. The AGLP030 device does not support PLL.
- 6. Tracking jitter is defined as the variation in clock edge position of PLL outputs with reference to PLL input clock edge. Tracking jitter does not measure the variation in PLL output period, which is covered by period jitter parameter.
- 7. VCO output jitter is calculated as a percentage of the VCO frequency. The jitter (in ps) can be calculated by multiplying the VCO period by the per cent jitter. The VCO jitter (in ps) applies to CCC_OUT regardless of the output divider settings. For example, if the jitter on VCO is 300 ps, the jitter on CCC_OUT is also 300 ps, regardless of the output divider settings.
- 8. Measurements are done with LVTTL 3.3 V, 8 mA, I/O drive strength and high slew rate. VCC/VCCPLL = 1.14 V, VCCI = 3.3 V, VQ/PQ/TQ type of packages, 20 pF load.
- 9. SSO are outputs that are synchronous to a single clock domain, and have their clock-to-out times within ±200 ps of each other. Switching I/Os are placed outside of the PLL bank. Refer to the "Simultaneously Switching Outputs (SSOs) and Printed Circuit Board Layout" section in the IGLOO PLUS FPGA Fabric User's Guide

2-62 Revision 16





Note: Peak-to-peak jitter measurements are defined by $T_{peak-to-peak} = T_{period_max} - T_{period_min}$

Figure 2-22 • Peak-to-Peak Jitter Definition

Embedded SRAM and FIFO Characteristics

SRAM

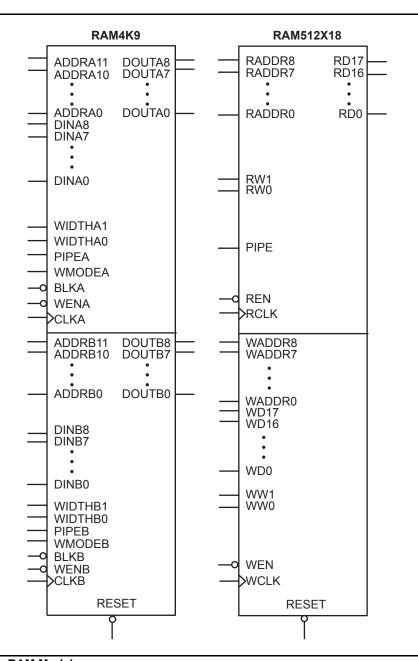


Figure 2-23 • RAM Models

2-64 Revision 16

Timing Waveforms

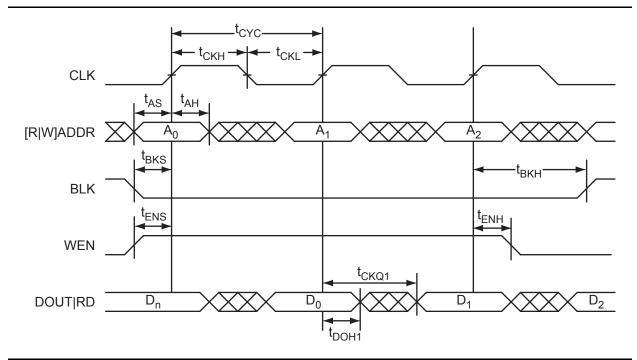


Figure 2-24 • RAM Read for Pass-Through Output. Applicable to Both RAM4K9 and RAM512x18.

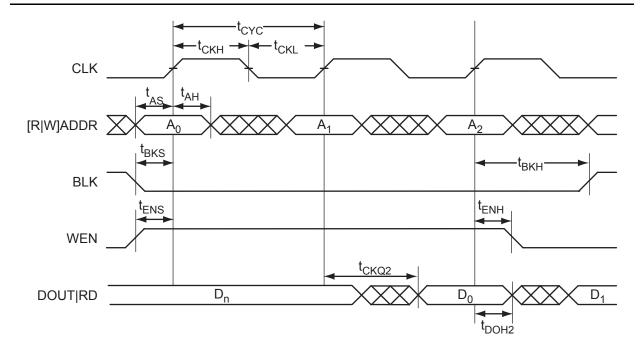


Figure 2-25 • RAM Read for Pipelined Output. Applicable to Both RAM4K9 and RAM512x18.

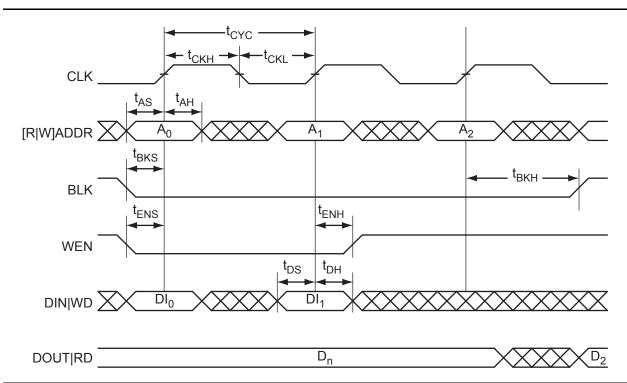


Figure 2-26 • RAM Write, Output Retained. Applicable to Both RAM4K9 and RAM512x18.

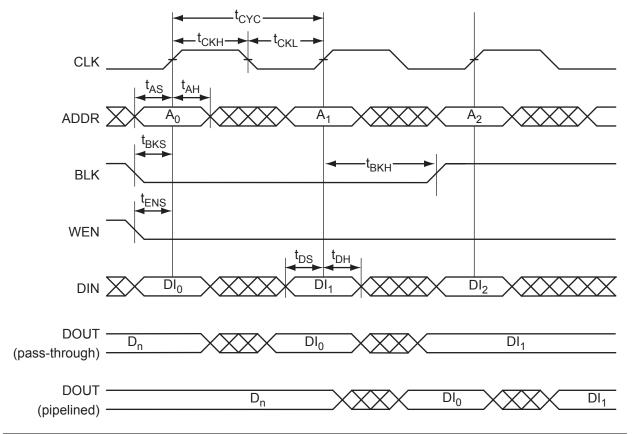


Figure 2-27 • RAM Write, Output as Write Data (WMODE = 1). Applicable to RAM4K9 only.

2-66 Revision 16

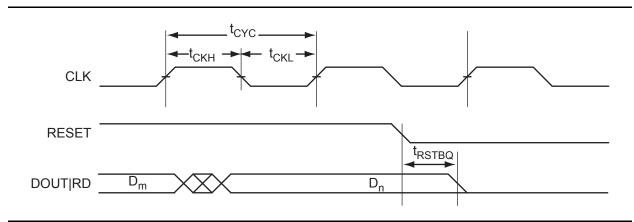


Figure 2-28 • RAM Reset

Timing Characteristics 1.5 V DC Core Voltage

Table 2-92 • RAM4K9

Commercial-Case Conditions: $T_J = 70^{\circ}C$, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{AS}	Address setup time	0.69	ns
t _{AH}	Address hold time	0.13	ns
t _{ENS}	REN, WEN setup time	0.68	ns
t _{ENH}	REN, WEN hold time	0.13	ns
t _{BKS}	BLK setup time	1.37	ns
t _{BKH}	BLK hold time	0.13	ns
t _{DS}	Input data (DIN) setup time	0.59	ns
t _{DH}	Input data (DIN) hold time	0.30	ns
t _{CKQ1}	Clock High to new data valid on DOUT (output retained, WMODE = 0)	2.94	ns
	Clock High to new data valid on DOUT (flow-through, WMODE = 1)	2.55	ns
t _{CKQ2}	Clock High to new data valid on DOUT (pipelined)	1.51	ns
t _{C2CWWL} 1	Address collision clk-to-clk delay for reliable write after write on same address – applicable to closing edge	0.29	ns
t _{C2CRWH} 1	Address collision clk-to-clk delay for reliable read access after write on same address – applicable to opening edge	0.24	ns
t _{C2CWRH} 1	Address collision clk-to-clk delay for reliable write access after read on same address – applicable to opening edge	0.40	ns
t _{RSTBQ}	RESET Low to data out Low on DOUT (flow-through)	1.72	ns
	RESET Low to data out Low on DOUT (pipelined)	1.72	ns
t _{REMRSTB}	RESET removal	0.51	ns
t _{RECRSTB}	RESET recovery	2.68	ns
t _{MPWRSTB}	RESET minimum pulse width	0.68	ns
t _{CYC}	Clock cycle time	6.24	ns
F _{MAX}	Maximum frequency	160	MHz

Notes:

- For more information, refer to the application note Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2-68 Revision 16



Table 2-93 • RAM512X18 Commercial-Case Conditions: $T_J = 70$ °C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{AS}	Address setup time	0.69	ns
t _{AH}	Address hold time	0.13	ns
t _{ENS}	REN, WEN setup time	0.61	ns
t _{ENH}	REN, WEN hold time	0.07	ns
t _{DS}	Input data (WD) setup time	0.59	ns
t _{DH}	Input data (WD) hold time	0.30	ns
t _{CKQ1}	Clock High to new data valid on RD (output retained)	3.51	ns
t _{CKQ2}	Clock High to new data valid on RD (pipelined)	1.43	ns
t _{C2CRWH} ¹	Address collision clk-to-clk delay for reliable read access after write on same address – applicable to opening edge	0.21	ns
t _{C2CWRH} 1	Address collision clk-to-clk delay for reliable write access after read on same address – applicable to opening edge	0.25	ns
t _{RSTBQ}	RESET Low to data out Low on RD (flow-through)	1.72	ns
	RESET Low to data out Low on RD (pipelined)	1.72	ns
t _{REMRSTB}	RESET removal	0.51	ns
t _{RECRSTB}	RESET recovery	2.68	ns
t _{MPWRSTB}	RESET minimum pulse width	0.68	ns
t _{CYC}	Clock cycle time	6.24	ns
F _{MAX}	Maximum frequency	160	MHz

Notes:

- 1. For more information, refer to the application note Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-94 • RAM4K9

Commercial-Case Conditions: $T_J = 70^{\circ}C$, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{AS}	Address setup time	1.28	ns
t _{AH}	Address hold time	0.25	ns
t _{ENS}	REN, WEN setup time	1.25	ns
t _{ENH}	REN, WEN hold time	0.25	ns
t _{BKS}	BLK setup time	2.54	ns
t _{BKH}	BLK hold time	0.25	ns
t _{DS}	Input data (DIN) setup time	1.10	ns
t _{DH}	Input data (DIN) hold time	0.55	ns
t _{CKQ1}	Clock High to new data valid on DOUT (output retained, WMODE = 0)	5.51	ns
	Clock High to new data valid on DOUT (flow-through, WMODE = 1)	4.77	ns
t _{CKQ2}	Clock High to new data valid on DOUT (pipelined)	2.82	ns
t _{C2CWWL} 1	Address collision clk-to-clk delay for reliable write after write on same address – applicable to closing edge	0.30	ns
t _{C2CRWH} 1	Address collision clk-to-clk delay for reliable read access after write on same address – applicable to opening edge	0.32	ns
t _{C2CWRH} 1	Address collision clk-to-clk delay for reliable write access after read on same address – applicable to opening edge	0.44	ns
t _{RSTBQ}	RESET Low to data out Low on DOUT (flow-through)	3.21	ns
	RESET Low to data out Low on DOUT (pipelined)	3.21	ns
t _{REMRSTB}	RESET removal	0.93	ns
t _{RECRSTB}	RESET recovery	4.94	ns
t _{MPWRSTB}	RESET minimum pulse width	1.18	ns
t _{CYC}	Clock cycle time	10.90	ns
F _{MAX}	Maximum frequency	92	MHz

Notes.

2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2-70 Revision 16

^{1.} For more information, refer to the application note Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.



Table 2-95 • RAM512X18 Commercial-Case Conditions: $T_J = 70^{\circ}\text{C}$, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{AS}	Address setup time	1.28	ns
t _{AH}	Address hold time	0.25	ns
t _{ENS}	REN, WEN setup time	1.13	ns
t _{ENH}	REN, WEN hold time	0.13	ns
t _{DS}	Input data (WD) setup time	1.10	ns
t _{DH}	Input data (WD) hold time	0.55	ns
t _{CKQ1}	Clock High to new data valid on RD (output retained)	6.56	ns
t _{CKQ2}	Clock High to new data valid on RD (pipelined)	2.67	ns
t _{C2CRWH} 1	Address collision clk-to-clk delay for reliable read access after write on same address – applicable to opening edge	0.29	ns
t _{C2CWRH} 1	Address collision clk-to-clk delay for reliable write access after read on same address – applicable to opening edge	0.36	ns
t _{RSTBQ}	RESET Low to data out Low on RD (flow through)	3.21	ns
	RESET Low to data out Low on RD (pipelined)	3.21	ns
t _{REMRSTB}	RESET removal	0.93	ns
t _{RECRSTB}	RESET recovery	4.94	ns
t _{MPWRSTB}	RESET minimum pulse width	1.18	ns
t _{CYC}	Clock cycle time	10.90	ns
F _{MAX}	Maximum frequency	92	MHz

Notes:

- 1. For more information, refer to the application note Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs.
- 2. For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

FIFO

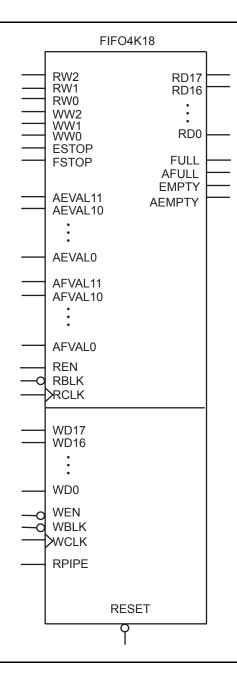


Figure 2-29 • FIFO Model

2-72 Revision 16

Timing Waveforms

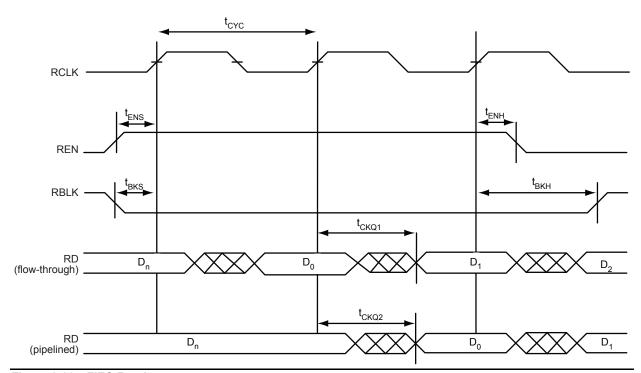


Figure 2-30 • FIFO Read

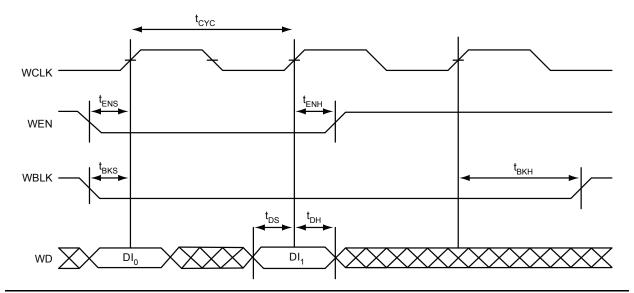


Figure 2-31 • FIFO Write



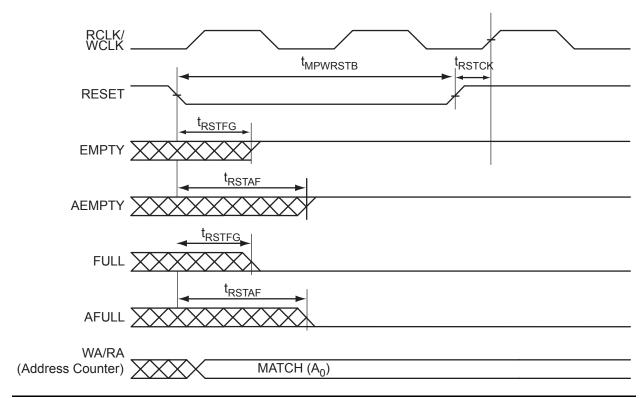


Figure 2-32 • FIFO Reset

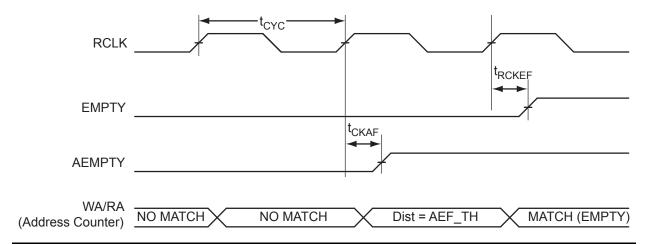


Figure 2-33 • FIFO EMPTY Flag and AEMPTY Flag Assertion

2-74 Revision 16

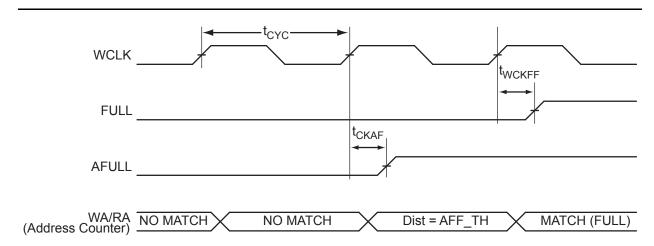


Figure 2-34 • FIFO FULL Flag and AFULL Flag Assertion

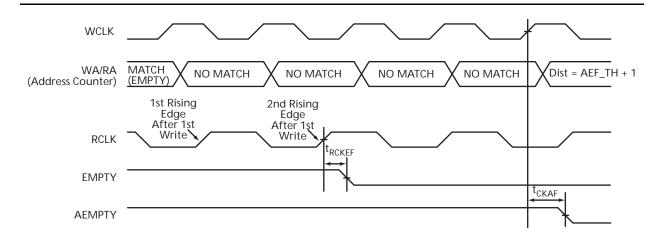


Figure 2-35 • FIFO EMPTY Flag and AEMPTY Flag Deassertion

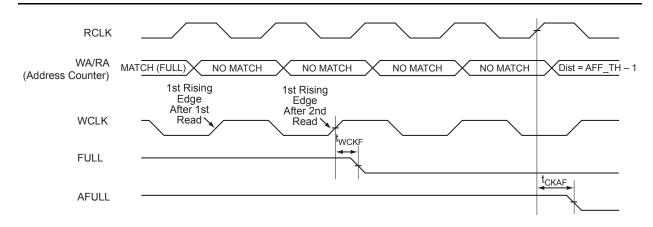


Figure 2-36 • FIFO FULL Flag and AFULL Flag Deassertion

Timing Characteristics 1.5 V DC Core Voltage

Table 2-96 • FIFO

Worst Commercial-Case Conditions: T_J = 70°C, VCC = 1.425 V

Parameter	Description	Std.	Units
t _{ENS}	REN, WEN Setup Time	1.66	ns
t _{ENH}	REN, WEN Hold Time	0.13	ns
t _{BKS}	BLK Setup Time	0.30	ns
t _{BKH}	BLK Hold Time	0.00	ns
t _{DS}	Input Data (WD) Setup Time	0.63	ns
t _{DH}	Input Data (WD) Hold Time	0.20	ns
t _{CKQ1}	Clock High to New Data Valid on RD (flow-through)	2.77	ns
t _{CKQ2}	Clock High to New Data Valid on RD (pipelined)	1.50	ns
t _{RCKEF}	RCLK High to Empty Flag Valid	2.94	ns
t _{WCKFF}	WCLK High to Full Flag Valid	2.79	ns
t _{CKAF}	Clock High to Almost Empty/Full Flag Valid	10.71	ns
t _{RSTFG}	RESET Low to Empty/Full Flag Valid	2.90	ns
t _{RSTAF}	RESET Low to Almost Empty/Full Flag Valid	10.60	ns
t _{RSTBQ}	RESET Low to Data Out Low on RD (flow-through)	1.68	ns
	RESET Low to Data Out Low on RD (pipelined)	1.68	ns
t _{REMRSTB}	RESET Removal	0.51	ns
t _{RECRSTB}	RESET Recovery	2.68	ns
t _{MPWRSTB}	RESET Minimum Pulse Width	0.68	ns
t _{CYC}	Clock Cycle Time	6.24	ns
F _{MAX}	Maximum Frequency for FIFO	160	MHz

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2-76 Revision 16



1.2 V DC Core Voltage

Table 2-97 • FIFO

Worst Commercial-Case Conditions: T_J = 70°C, VCC = 1.14 V

Parameter	Description	Std.	Units
t _{ENS}	REN, WEN Setup Time	3.44	ns
t _{ENH}	REN, WEN Hold Time	0.26	ns
t _{BKS}	BLK Setup Time	0.30	ns
t _{BKH}	BLK Hold Time	0.00	ns
t _{DS}	Input Data (WD) Setup Time	1.30	ns
t _{DH}	Input Data (WD) Hold Time	0.41	ns
t _{CKQ1}	Clock High to New Data Valid on RD (flow-through)	5.67	ns
t _{CKQ2}	Clock High to New Data Valid on RD (pipelined)	3.02	ns
t _{RCKEF}	RCLK High to Empty Flag Valid	6.02	ns
t _{WCKFF}	WCLK High to Full Flag Valid	5.71	ns
t _{CKAF}	Clock High to Almost Empty/Full Flag Valid	22.17	ns
t _{RSTFG}	RESET Low to Empty/Full Flag Valid	5.93	ns
t _{RSTAF}	RESET Low to Almost Empty/Full Flag Valid	21.94	ns
t _{RSTBQ}	RESET Low to Data Out Low on RD (flow-through)	3.41	ns
	RESET Low to Data Out Low on RD (pipelined)	3.41	ns
t _{REMRSTB}	RESET Removal	1.02	ns
t _{RECRSTB}	RESET Recovery	5.48	ns
t _{MPWRSTB}	RESET Minimum Pulse Width	1.18	ns
t _{CYC}	Clock Cycle Time	10.90	ns
F _{MAX}	Maximum Frequency for FIFO	92	MHz

Note: For specific junction temperature and voltage supply levels, refer to Table 2-7 on page 2-7 for derating values.

Embedded FlashROM Characteristics

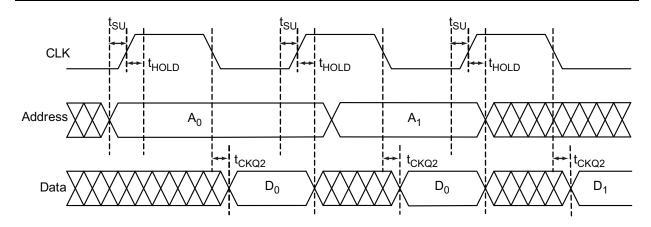


Figure 2-37 • Timing Diagram

Timing Characteristics

1.5 V DC Core Voltage

Table 2-98 • Embedded FlashROM Access Time Worst Commercial-Case Conditions: $T_J = 70$ °C, VCC = 1.425 V

Parameter	Description	Std.	Units
t _{SU}	Address Setup Time	0.57	ns
t _{HOLD}	Address Hold Time	0.00	ns
t _{CK2Q}	Clock to Out	17.58	ns
F _{MAX}	Maximum Clock Frequency	15	MHz

1.2 V DC Core Voltage

Table 2-99 • Embedded FlashROM Access Time Worst Commercial-Case Conditions: $T_J = 70^{\circ}C$, VCC = 1.14 V

Parameter	Description	Std.	Units
t _{SU}	Address Setup Time	0.59	ns
t _{HOLD}	Address Hold Time	0.00	ns
t _{CK2Q}	Clock to Out	30.94	ns
F _{MAX}	Maximum Clock Frequency	10	MHz

2-78 Revision 16

JTAG 1532 Characteristics

JTAG timing delays do not include JTAG I/Os. To obtain complete JTAG timing, add I/O buffer delays to the corresponding standard selected; refer to the I/O timing characteristics in the "User I/O Characteristics" section on page 2-15 for more details.

Timing Characteristics

1.5 V DC Core Voltage

Table 2-100 • JTAG 1532

Commercial-Case Conditions: T_J = 70°C, Worst-Case VCC = 1.425 V

Parameter	Description	Std.	Units
t _{DISU}	Test Data Input Setup Time	1.00	ns
t _{DIHD}	Test Data Input Hold Time	2.00	ns
t _{TMSSU}	Test Mode Select Setup Time	1.00	ns
t _{TMDHD}	Test Mode Select Hold Time	2.00	ns
t _{TCK2Q}	Clock to Q (data out)	8.00	ns
t _{RSTB2Q}	Reset to Q (data out)	25.00	ns
F _{TCKMAX}	TCK Maximum Frequency	15	MHz
t _{TRSTREM}	ResetB Removal Time	0.58	ns
t _{TRSTREC}	ResetB Recovery Time	0.00	ns
t _{TRSTMPW}	ResetB Minimum Pulse	TBD	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

1.2 V DC Core Voltage

Table 2-101 • JTAG 1532

Commercial-Case Conditions: $T_J = 70$ °C, Worst-Case VCC = 1.14 V

Parameter	Description	Std.	Units
t _{DISU}	Test Data Input Setup Time	1.50	ns
t _{DIHD}	Test Data Input Hold Time	3.00	ns
t _{TMSSU}	Test Mode Select Setup Time	1.50	ns
t _{TMDHD}	Test Mode Select Hold Time	3.00	ns
t _{TCK2Q}	Clock to Q (data out)	11.00	ns
t _{RSTB2Q}	Reset to Q (data out)	30.00	ns
F _{TCKMAX}	TCK Maximum Frequency	9.00	MHz
t _{TRSTREM}	ResetB Removal Time	1.18	ns
t _{TRSTREC}	ResetB Recovery Time	0.00	ns
t _{TRSTMPW}	ResetB Minimum Pulse	TBD	ns

Note: For specific junction temperature and voltage supply levels, refer to Table 2-6 on page 2-6 for derating values.

2-80 Revision 16



3 - Pin Descriptions and Packaging

Supply Pins

GND Ground

Ground supply voltage to the core, I/O outputs, and I/O logic.

GNDQ Ground (quiet)

Quiet ground supply voltage to input buffers of I/O banks. Within the package, the GNDQ plane is decoupled from the simultaneous switching noise originated from the output buffer ground domain. This minimizes the noise transfer within the package and improves input signal integrity. GNDQ must always be connected to GND on the board.

VCC Core Supply Voltage

Supply voltage to the FPGA core, nominally 1.5 V for IGLOO PLUS V5 devices, and 1.2 V or 1.5 V for IGLOO PLUS V2 devices. VCC is required for powering the JTAG state machine in addition to VJTAG. Even when a device is in bypass mode in a JTAG chain of interconnected devices, both VCC and VJTAG must remain powered to allow JTAG signals to pass through the device.

For IGLOO PLUS V2 devices, VCC can be switched dynamically from 1.2 V to 1.5 V or vice versa. This allows in-system programming (ISP) when VCC is at 1.5 V and the benefit of low power operation when VCC is at 1.2 V.

VCCIBx I/O Supply Voltage

Supply voltage to the bank's I/O output buffers and I/O logic. Bx is the I/O bank number. There are four I/O banks on low power flash devices plus a dedicated VJTAG bank. Each bank can have a separate VCCI connection. All I/Os in a bank will run off the same VCCIBx supply. VCCI can be 1.2 V, 1.5 V, 1.8 V, 2.5 V, or 3.3 V, nominal voltage. Unused I/O banks should have their corresponding VCCI pins tied to GND.

VMVx I/O Supply Voltage (quiet)

Quiet supply voltage to the input buffers of each I/O bank. *x* is the bank number. Within the package, the VMV plane biases the input stage of the I/Os in the I/O banks. This minimizes the noise transfer within the package and improves input signal integrity. Each bank must have at least one VMV connection, and no VMV should be left unconnected. All I/Os in a bank run off the same VMVx supply. VMV is used to provide a quiet supply voltage to the input buffers of each I/O bank. VMVx can be 1.2 V, 1.5 V, 1.8 V, 2.5 V, or 3.3 V, nominal voltage. Unused I/O banks should have their corresponding VMV pins tied to GND. VMV and VCCI should be at the same voltage within a given I/O bank. Used VMV pins must be connected to the corresponding VCCI pins of the same bank (i.e., VMV0 to VCCIB0, VMV1 to VCCIB1, etc.).

VCCPLA/B/C/D/E/F PLL Supply Voltage

Supply voltage to analog PLL, nominally 1.5 V or 1.2 V, depending on the device.

- · 1.5 V for IGLOO PLUS V5 devices
- 1.2 V or 1.5 V for IGLOO PLUS V2 devices

When the PLLs are not used, the Microsemi Designer place-and-route tool automatically disables the unused PLLs to lower power consumption. The user should tie unused VCCPLx and VCOMPLx pins to ground. Microsemi recommends tying VCCPLx to VCC and using proper filtering circuits to decouple VCC noise from the PLLs. Refer to the PLL Power Supply Decoupling section of the "Clock Conditioning Circuits in Low Power Flash Devices and Mixed signal FPGAs " chapter of the IGLOO PLUS FPGA Fabric User's Guide for a complete board solution for the PLL analog power supply and ground.

There is one VCCPLF pin on IGLOO PLUS devices.



Pin Descriptions and Packaging

VCOMPLA/B/C/D/E/F PLL Ground

Ground to analog PLL power supplies. When the PLLs are not used, the Designer place-and-route tool automatically disables the unused PLLs to lower power consumption. The user should tie unused VCCPLx and VCOMPLx pins to ground.

There is one VCOMPLF pin on IGLOO PLUS devices.

VJTAG

JTAG Supply Voltage

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND. It should be noted that VCC is required to be powered for JTAG operation; VJTAG alone is insufficient. If a device is in a JTAG chain of interconnected boards, the board containing the device can be powered down, provided both VJTAG and VCC to the part remain powered; otherwise, JTAG signals will not be able to transition the device, even in bypass mode.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

VPIIMP

Programming Supply Voltage

IGLOO PLUS devices support single-voltage ISP of the configuration flash and FlashROM. For programming, VPUMP should be 3.3 V nominal. During normal device operation, VPUMP can be left floating or can be tied (pulled up) to any voltage between 0 V and the VPUMP maximum. Programming power supply voltage (VPUMP) range is listed in the datasheet.

When the VPUMP pin is tied to ground, it will shut off the charge pump circuitry, resulting in no sources of oscillation from the charge pump circuitry.

For proper programming, $0.01~\mu F$ and $0.33~\mu F$ capacitors (both rated at 16 V) are to be connected in parallel across VPUMP and GND, and positioned as close to the FPGA pins as possible.

Microsemi recommends that VPUMP and VJTAG power supplies be kept separate with independent filtering capacitors rather than supplying them from a common rail.

User Pins

I/O

User Input/Output

The I/O pin functions as an input, output, tristate, or bidirectional buffer. Input and output signal levels are compatible with the I/O standard selected.

During programming, I/Os become tristated and weakly pulled up to VCCI. With VCCI, VMV, and VCC supplies continuously powered up, when the device transitions from programming to operating mode, the I/Os are instantly configured to the desired user configuration.

Unused I/Os are configured as follows:

- Output buffer is disabled (with tristate value of high impedance)
- · Input buffer is disabled (with tristate value of high impedance)
- · Weak pull-up is programmed

GL

Globals

GL I/Os have access to certain clock conditioning circuitry (and the PLL) and/or have direct access to the global network (spines). Additionally, the global I/Os can be used as regular I/Os, since they have identical capabilities. Unused GL pins are configured as inputs with pull-up resistors.

See more detailed descriptions of global I/O connectivity in the "Clock Conditioning Circuits in Low Power Flash Devices and Mixed Signal FPGAs" chapter of the IGLOO PLUS FPGA Fabric User's Guide. All inputs labeled GC/GF are direct inputs into the quadrant clocks. For example, if GAA0 is used for an input, GAA1 and GAA2 are no longer available for input to the quadrant globals. All inputs labeled GC/GF are direct inputs into the chip-level globals, and the rest are connected to the quadrant globals. The inputs to the global network are multiplexed, and only one input can be used as a global input.

Refer to the I/O Structure chapter of the IGLOO PLUS FPGA Fabric User's Guide for an explanation of the naming of global pins.

3-2 Revision 16

FF Flash*Freeze Mode Activation Pin

The FF pin is a dedicated input pin used to enter and exit Flash*Freeze mode. The FF pin is active low, has the same characteristics as a single-ended I/O, and must meet the maximum rise and fall times. When Flash*Freeze mode is not used in the design, the FF pin is available as a regular I/O.

When Flash*Freeze mode is used, the FF pin must not be left floating to avoid accidentally entering Flash*Freeze mode. While in Flash*Freeze mode, the Flash*Freeze pin should be constantly asserted.

The Flash*Freeze pin can be used with any single-ended I/O standard supported by the I/O bank in which the pin is located, and input signal levels compatible with the I/O standard selected. The FF pin should be treated as a sensitive asynchronous signal. When defining pin placement and board layout, simultaneously switching outputs (SSOs) and their effects on sensitive asynchronous pins must be considered.

Unused FF or I/O pins are tristated with weak pull-up. This default configuration applies to both Flash*Freeze mode and normal operation mode. No user intervention is required.

Table 3-1 shows the Flash*Freeze pin location on the available packages for IGLOO and ProASIC3L devices. The Flash*Freeze pin location is independent of device (except for a PQ208 package), allowing migration to larger or smaller IGLOO devices while maintaining the same pin location on the board. Refer to the "Flash*Freeze Technology and Low Power Modes" chapter of the *IGLOO PLUS Device Family User's Guide* for more information on I/O states during Flash*Freeze mode.

Table 3-1 • Flash*Freeze Pin Location in IGLOO PLUS Devices

Package	Flash*Freeze Pin
CS281	W2
CS201	R4
CS289	U1
VQ128	34
VQ176	47

Pin Descriptions and Packaging

JTAG Pins

Low power flash devices have a separate bank for the dedicated JTAG pins. The JTAG pins can be run at any voltage from 1.5 V to 3.3 V (nominal). VCC must also be powered for the JTAG state machine to operate, even if the device is in bypass mode; VJTAG alone is insufficient. Both VJTAG and VCC to the part must be supplied to allow JTAG signals to transition the device. Isolating the JTAG power supply in a separate I/O bank gives greater flexibility in supply selection and simplifies power supply and PCB design. If the JTAG interface is neither used nor planned for use, the VJTAG pin together with the TRST pin could be tied to GND.

TCK Test Clock

Test clock input for JTAG boundary scan, ISP, and UJTAG. The TCK pin does not have an internal pull-up/-down resistor. If JTAG is not used, Microsemi recommends tying off TCK to GND through a resistor placed close to the FPGA pin. This prevents JTAG operation in case TMS enters an undesired state.

Note that to operate at all VJTAG voltages, 500 Ω to 1 k Ω will satisfy the requirements. Refer to Table 3-2 for more information.

Table 3-2 • Recommended Tie-Off Values for the TCK and TRST Pins

VJTAG	Tie-Off Resistance
VJTAG at 3.3 V	200 Ω to 1 kΩ
VJTAG at 2.5 V	200 Ω to 1 kΩ
VJTAG at 1.8 V	500 Ω to 1 k Ω
VJTAG at 1.5 V	500 Ω to 1 kΩ

Notes:

- 1. Equivalent parallel resistance if more than one device is on the JTAG chain
- 2. The TCK pin can be pulled up/down.
- 3. The TRST pin is pulled down.

TDI Test Data Input

Serial input for JTAG boundary scan, ISP, and UJTAG usage. There is an internal weak pull-up resistor on the TDI pin.

TDO Test Data Output

Serial output for JTAG boundary scan, ISP, and UJTAG usage.

TMS Test Mode Select

The TMS pin controls the use of the IEEE 1532 boundary scan pins (TCK, TDI, TDO, TRST). There is an internal weak pull-up resistor on the TMS pin.

TRST Boundary Scan Reset Pin

The TRST pin functions as an active-low input to asynchronously initialize (or reset) the boundary scan circuitry. There is an internal weak pull-up resistor on the TRST pin. If JTAG is not used, an external pull-down resistor could be included to ensure the test access port (TAP) is held in reset mode. The resistor values must be chosen from Table 3-2 and must satisfy the parallel resistance value requirement. The values in Table 3-2 correspond to the resistor recommended when a single device is used, and the equivalent parallel resistor when multiple devices are connected via a JTAG chain.

In critical applications, an upset in the JTAG circuit could allow entrance to an undesired JTAG state. In such cases, Microsemi recommends tying off TRST to GND through a resistor placed close to the FPGA pin.

Note that to operate at all VJTAG voltages, 500 Ω to 1 k Ω will satisfy the requirements.

3-4 Revision 16



Special Function Pins

NC No Connect

This pin is not connected to circuitry within the device. These pins can be driven to any voltage or can be left floating with no effect on the operation of the device.

DC Do Not Connect

This pin should not be connected to any signals on the PCB. These pins should be left unconnected.

Packaging

Semiconductor technology is constantly shrinking in size while growing in capability and functional integration. To enable next-generation silicon technologies, semiconductor packages have also evolved to provide improved performance and flexibility.

Microsemi consistently delivers packages that provide the necessary mechanical and environmental protection to ensure consistent reliability and performance. Microsemi IC packaging technology efficiently supports high-density FPGAs with large-pin-count Ball Grid Arrays (BGAs), but is also flexible enough to accommodate stringent form factor requirements for Chip Scale Packaging (CSP). In addition, Microsemi offers a variety of packages designed to meet your most demanding application and economic requirements for today's embedded and mobile systems.

Related Documents

IGLOO PLUS Device Family User's Guide

http://www.microsemi.com/soc/documents/IGLOOPLUS_UG.pdf

The following documents provide packaging information and device selection for low power flash devices.

Product Catalog

http://www.microsemi.com/soc/documents/ProdCat PIB.pdf

Lists devices currently recommended for new designs and the packages available for each member of the family. Use this document or the datasheet tables to determine the best package for your design, and which package drawing to use.

Package Mechanical Drawings

http://www.microsemi.com/soc/documents/PckgMechDrwngs.pdf

This document contains the package mechanical drawings for all packages currently or previously supplied by Microsemi. Use the bookmarks to navigate to the package mechanical drawings.

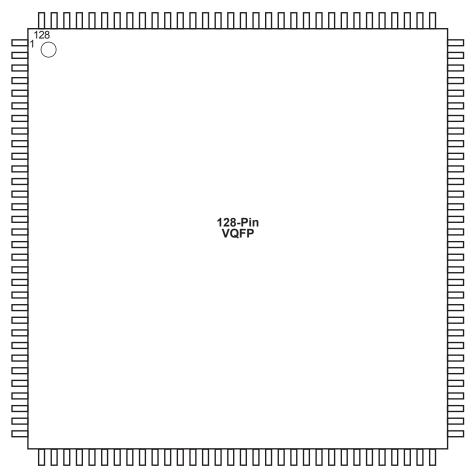
Additional packaging materials are available at

http://www.microsemi.com/soc/products/solutions/package/docs.aspx.



4 - Package Pin Assignments

VQ128



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

Pin information is in the "Pin Descriptions" chapter of the IGLOO PLUS FPGA Fabric User's Guide.



VQ128		VQ128		V	VQ128	
Pin Number	AGLP030 Function	Pin Number	AGLP030 Function	Pin Number	AGLP030 Function	
1	IO119RSB3	36	IO88RSB2	71	IO57RSB1	
2	IO118RSB3	37	IO86RSB2	72	VCCIB1	
3	IO117RSB3	38	IO84RSB2	73	GND	
4	IO115RSB3	39	IO83RSB2	74	IO55RSB1	
5	IO116RSB3	40	GND	75	IO54RSB1	
6	IO113RSB3	41	VCCIB2	76	IO53RSB1	
7	IO114RSB3	42	IO82RSB2	77	IO52RSB1	
8	GND	43	IO81RSB2	78	IO51RSB1	
9	VCCIB3	44	IO79RSB2	79	IO50RSB1	
10	IO112RSB3	45	IO78RSB2	80	IO49RSB1	
11	IO111RSB3	46	IO77RSB2	81	VCC	
12	IO110RSB3	47	IO75RSB2	82	GDB0/IO48RSB1	
13	IO109RSB3	48	IO74RSB2	83	GDA0/IO47RSB1	
14	GEC0/IO108RSB3	49	VCC	84	GDC0/IO46RSB1	
15	GEA0/IO107RSB3	50	IO73RSB2	85	IO45RSB1	
16	GEB0/IO106RSB3	51	IO72RSB2	86	IO44RSB1	
17	VCC	52	IO70RSB2	87	IO43RSB1	
18	IO104RSB3	53	IO69RSB2	88	IO42RSB1	
19	IO103RSB3	54	IO68RSB2	89	VCCIB1	
20	IO102RSB3	55	IO66RSB2	90	GND	
21	IO101RSB3	56	IO65RSB2	91	IO40RSB1	
22	IO100RSB3	57	GND	92	IO41RSB1	
23	IO99RSB3	58	VCCIB2	93	IO39RSB1	
24	GND	59	IO63RSB2	94	IO38RSB1	
25	VCCIB3	60	IO61RSB2	95	IO37RSB1	
26	IO97RSB3	61	IO59RSB2	96	IO36RSB1	
27	IO98RSB3	62	TCK	97	IO35RSB0	
28	IO95RSB3	63	TDI	98	IO34RSB0	
29	IO96RSB3	64	TMS	99	IO33RSB0	
30	IO94RSB3	65	VPUMP	100	IO32RSB0	
31	IO93RSB3	66	TDO	101	IO30RSB0	
32	IO92RSB3	67	TRST	102	IO28RSB0	
33	IO91RSB2	68	IO58RSB1	103	IO27RSB0	
34	FF/IO90RSB2	69	VJTAG	104	VCCIB0	
35	IO89RSB2	70	IO56RSB1	105	GND	

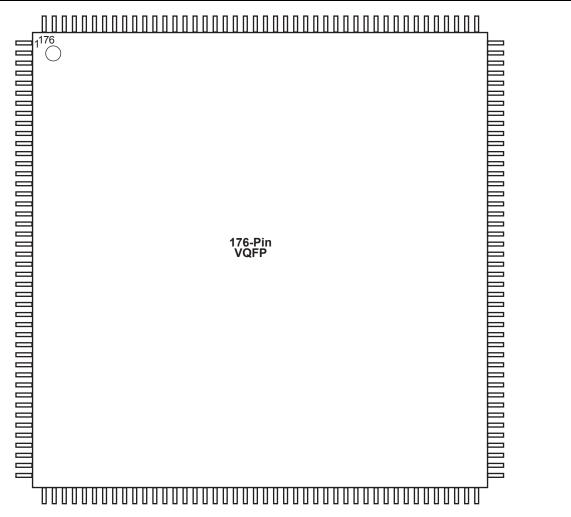
4-2 Revision 16



VQ128		
Pin Number	AGLP030 Function	
106	IO26RSB0	
107	IO25RSB0	
108	IO23RSB0	
109	IO22RSB0	
110	IO21RSB0	
111	IO19RSB0	
112	IO18RSB0	
113	VCC	
114	IO17RSB0	
115	IO16RSB0	
116	IO14RSB0	
117	IO13RSB0	
118	IO12RSB0	
119	IO10RSB0	
120	IO09RSB0	
121	VCCIB0	
122	GND	
123	IO07RSB0	
124	IO05RSB0	
125	IO03RSB0	
126	IO02RSB0	
127	IO01RSB0	
128	IO00RSB0	



VQ176



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.

4-4 Revision 16



VQ176		
	AGLP060	
Pin Number	Function	
1	GAA2/IO156RSB3	
2	IO155RSB3	
3	GAB2/IO154RSB3	
4	IO153RSB3	
5	GAC2/IO152RSB3	
6	GND	
7	VCCIB3	
8	IO149RSB3	
9	IO147RSB3	
10	IO145RSB3	
11	IO144RSB3	
12	IO143RSB3	
13	VCC	
14	IO141RSB3	
15	GFC1/IO140RSB3	
16	GFB1/IO138RSB3	
17	GFB0/IO137RSB3	
18	VCOMPLF	
19	GFA1/IO136RSB3	
20	VCCPLF	
21	GFA0/IO135RSB3	
22	GND	
23	VCCIB3	
24	GFA2/IO134RSB3	
25	GFB2/IO133RSB3	
26	GFC2/IO132RSB3	
27	IO131RSB3	
28	IO130RSB3	
29	IO129RSB3	
30	IO127RSB3	
31	IO126RSB3	
32	IO125RSB3	
33	IO123RSB3	
34	IO122RSB3	
35	IO121RSB3	

VQ176			
AGLP060			
Pin Number	Function		
36	IO119RSB3		
37	GND		
38	VCCIB3		
39	GEC1/IO116RSB3		
40	GEB1/IO114RSB3		
41	GEC0/IO115RSB3		
42	GEB0/IO113RSB3		
43	GEA1/IO112RSB3		
44	GEA0/IO111RSB3		
45	GEA2/IO110RSB2		
46	NC		
47	FF/GEB2/IO109R SB2		
48	GEC2/IO108RSB2		
49	IO106RSB2		
50	IO107RSB2		
51	IO104RSB2		
52	IO105RSB2		
53	IO102RSB2		
54	IO103RSB2		
55	GND		
56	VCCIB2		
57	IO101RSB2		
58	IO100RSB2		
59	IO99RSB2		
60	IO98RSB2		
61	IO97RSB2		
62	IO96RSB2		
63	IO95RSB2		
64	IO94RSB2		
65	IO93RSB2		
66	VCC		
67	IO92RSB2		
68	IO91RSB2		
69	IO90RSB2		

VQ176		
Pin Number	AGLP060 Function	
70	IO89RSB2	
71	IO88RSB2	
72	IO87RSB2	
73	IO86RSB2	
74	IO85RSB2	
75	IO84RSB2	
76	GND	
77	VCCIB2	
78	IO83RSB2	
79	IO82RSB2	
80	GDC2/IO80RSB2	
81	IO81RSB2	
82	GDA2/IO78RSB2	
83	GDB2/IO79RSB2	
84	NC	
85	NC	
86	TCK	
87	TDI	
88	TMS	
89	VPUMP	
90	TDO	
91	TRST	
92	VJTAG	
93	GDA1/IO76RSB1	
94	GDC0/IO73RSB1	
95	GDB1/IO74RSB1	
96	GDC1/IO72RSB1	
97	VCCIB1	
98	GND	
99	IO70RSB1	
100	IO69RSB1	
101	IO67RSB1	
102	IO66RSB1	
103	IO65RSB1	
104	IO63RSB1	



VQ176					
Pin Number	AGLP060 Function				
105	IO62RSB1				
106	IO61RSB1				
107	GCC2/IO60RSB1				
108	GCB2/IO59RSB1				
109	GCA2/IO58RSB1				
110	GCA0/IO57RSB1				
111	GCA1/IO56RSB1				
112	VCCIB1				
113	GND				
114	GCB0/IO55RSB1				
115	GCB1/IO54RSB1				
116	GCC0/IO53RSB1				
117	GCC1/IO52RSB1				
118	IO51RSB1				
119	IO50RSB1				
120	VCC				
121	IO48RSB1				
122	IO47RSB1				
123	IO45RSB1				
124	IO44RSB1				
125	IO43RSB1				
126	VCCIB1				
127	GND				
128	GBC2/IO40RSB1				
129	IO39RSB1				
130	GBB2/IO38RSB1				
131	IO37RSB1				
132	GBA2/IO36RSB1				
133	GBA1/IO35RSB0				
134	NC				
135	GBA0/IO34RSB0				
136	NC				
137	GBB1/IO33RSB0				
138	NC				
139	GBC1/IO31RSB0				

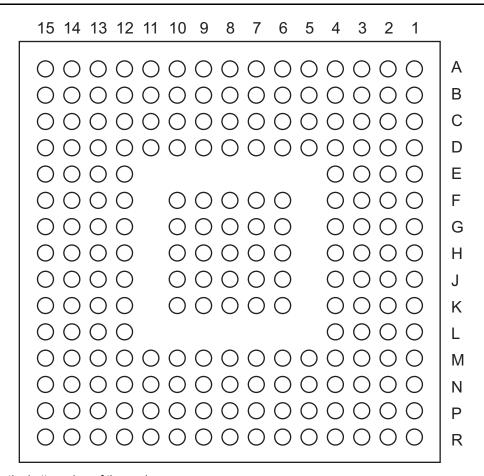
VQ176					
Pin Number	AGLP060 Function				
140	GBB0/IO32RSB0				
141	GBC0/IO30RSB0				
142	IO29RSB0				
143	IO28RSB0				
144	IO27RSB0				
145	VCCIB0				
146	GND				
147	IO26RSB0				
148	IO25RSB0				
149	IO24RSB0				
150	IO23RSB0				
151	IO22RSB0				
152	IO21RSB0				
153	IO20RSB0				
154	IO19RSB0				
155	IO18RSB0				
156	VCC				
157	IO17RSB0				
158	IO16RSB0				
159	IO15RSB0				
160	IO14RSB0				
161	IO13RSB0				
162	IO12RSB0				
163	IO11RSB0				
164	IO10RSB0				
165	IO09RSB0				
166	VCCIB0				
167	GND				
168	IO07RSB0				
169	IO08RSB0				
170	GAC1/IO05RSB0				
171	IO06RSB0				
172	GAB1/IO03RSB0				
173	GAC0/IO04RSB0				
174	GAB0/IO02RSB0				

VQ176				
Pin Number	AGLP060 Function			
175	GAA1/IO01RSB0			
176	GAA0/IO00RSB0			

4-6 Revision 16



CS201



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx.



CS201		CS201		CS201	
Pin Number	AGLP030 Function	Pin Number	AGLP030 Function	Pin Number	AGLP030 Function
A1	NC	C6	IO12RSB0	F3	IO119RSB3
A2	IO04RSB0	C7	IO23RSB0	F4	IO111RSB3
A3	IO06RSB0	C8	IO19RSB0	F6	GND
A4	IO09RSB0	C9	IO28RSB0	F7	VCC
A5	IO11RSB0	C10	IO32RSB0	F8	VCCIB0
A6	IO13RSB0	C11	IO35RSB0	F9	VCCIB0
A7	IO17RSB0	C12	NC	F10	VCCIB0
A8	IO18RSB0	C13	GND	F12	NC
A9	IO24RSB0	C14	IO41RSB1	F13	NC
A10	IO26RSB0	C15	IO37RSB1	F14	IO40RSB1
A11	IO27RSB0	D1	IO117RSB3	F15	IO38RSB1
A12	IO31RSB0	D2	IO118RSB3	G1	NC
A13	NC	D3	NC	G2	IO112RSB3
A14	NC	D4	GND	G3	IO110RSB3
A15	NC	D5	IO01RSB0	G4	IO109RSB3
B1	NC	D6	IO03RSB0	G6	VCCIB3
B2	NC	D7	IO10RSB0	G7	GND
В3	IO08RSB0	D8	IO21RSB0	G8	VCC
B4	IO05RSB0	D9	IO25RSB0	G9	GND
B5	IO07RSB0	D10	IO30RSB0	G10	GND
B6	IO15RSB0	D11	IO33RSB0	G12	NC
В7	IO14RSB0	D12	GND	G13	NC
B8	IO16RSB0	D13	NC	G14	IO42RSB1
В9	IO20RSB0	D14	IO36RSB1	G15	IO44RSB1
B10	IO22RSB0	D15	IO39RSB1	H1	NC
B11	IO34RSB0	E1	IO115RSB3	H2	GEB0/IO106RSB3
B12	IO29RSB0	E2	IO114RSB3	H3	GEC0/IO108RSB3
B13	NC	E3	NC	H4	NC
B14	NC	E4	NC	H6	VCCIB3
B15	NC	E12	NC	H7	GND
C1	NC	E13	NC	H8	VCC
C2	NC	E14	GDC0/IO46RSB1	H9	GND
C3	GND	E15	GDB0/IO48RSB1	H10	VCCIB1
C4	IO00RSB0	F1	IO113RSB3	H12	IO54RSB1
C5	IO02RSB0	F2	IO116RSB3	H13	GDA0/IO47RSB1

4-8 Revision 16



CS201		
Pin Number	AGLP030 Function	
H14	IO45RSB1	
H15	IO43RSB1	
J1	GEA0/IO107RSB3	
J2	IO105RSB3	
J3	IO104RSB3	
J4	IO102RSB3	
J6	VCCIB3	
J7	GND	
J8	VCC	
J9	GND	
J10	VCCIB1	
J12	NC	
J13	NC	
J14	IO52RSB1	
J15	IO50RSB1	
K1	IO103RSB3	
K2	IO101RSB3	
K3	IO99RSB3	
K4	IO100RSB3	
K6	GND	
K7	VCCIB2	
K8	VCCIB2	
K9	VCCIB2	
K10	VCCIB1	
K12	NC	
K13	IO57RSB1	
K14	IO49RSB1	
K15	IO53RSB1	
L1	IO96RSB3	
L2	IO98RSB3	
L3	IO95RSB3	
L4	IO94RSB3	
L12	NC	
L13	NC	
L14	IO51RSB1	

CS201			
Pin Number	AGLP030 Function		
L15	IO58RSB1		
M1	IO93RSB3		
M2	IO92RSB3		
M3	IO97RSB3		
M4	GND		
M5	NC		
M6	IO79RSB2		
M7	IO77RSB2		
M8	IO72RSB2		
M9	IO70RSB2		
M10	IO61RSB2		
M11	IO59RSB2		
M12	GND		
M13	NC		
M14	IO55RSB1		
M15	IO56RSB1		
N1	NC		
N2	NC		
N3	GND		
N4	NC		
N5	IO88RSB2		
N6	IO81RSB2		
N7	IO75RSB2		
N8	IO68RSB2		
N9	IO66RSB2		
N10	IO65RSB2		
N11	IO71RSB2		
N12	IO63RSB2		
N13	GND		
N14	TDO		
N15	VJTAG		
P1	NC		
P2	NC		
P3	NC		
P4	NC		

CS201		
Pin Number	AGLP030 Function	
P5	IO87RSB2	
P6	IO86RSB2	
P7	IO84RSB2	
P8	IO80RSB2	
P9	IO74RSB2	
P10	IO73RSB2	
P11	IO76RSB2	
P12	IO67RSB2	
P13	IO64RSB2	
P14	VPUMP	
P15	TRST	
R1	NC	
R2	NC	
R3	IO91RSB2	
R4	FF/IO90RSB2	
R5	IO89RSB2	
R6	IO83RSB2	
R7	IO82RSB2	
R8	IO85RSB2	
R9	IO78RSB2	
R10	IO69RSB2	
R11	IO62RSB2	
R12	IO60RSB2	
R13	TMS	
R14	TDI	
R15	TCK	



	CS201		CS201		S201
Pin Number	AGLP060 Function	Pin Number	AGLP060 Function	Pin Number	AGLP060 Function
A1	IO150RSB3	C6	IO07RSB0	F3	IO145RSB3
A2	GAA0/IO00RSB0	C7	IO16RSB0	F4	IO147RSB3
A3	GAC0/IO04RSB0	C8	IO21RSB0	F6	GND
A4	IO08RSB0	C9	IO28RSB0	F7	VCC
A5	IO11RSB0	C10	GBB1/IO33RSB0	F8	VCCIB0
A6	IO15RSB0	C11	GBA1/IO35RSB0	F9	VCCIB0
A7	IO17RSB0	C12	GBB2/IO38RSB1	F10	VCCIB0
A8	IO18RSB0	C13	GND	F12	IO47RSB1
A9	IO22RSB0	C14	IO48RSB1	F13	IO45RSB1
A10	IO26RSB0	C15	IO39RSB1	F14	GCC1/IO52RSB1
A11	IO29RSB0	D1	IO146RSB3	F15	GCA1/IO56RSB1
A12	GBC1/IO31RSB0	D2	IO144RSB3	G1*	VCOMPLF
A13	GBA2/IO36RSB1	D3	IO148RSB3	G2	GFB0/IO137RSB3
A14	IO41RSB1	D4	GND	G3	GFC0/IO139RSB3
A15	NC	D5	GAB0/IO02RSB0	G4	IO143RSB3
B1	IO151RSB3	D6	GAC1/IO05RSB0	G6	VCCIB3
B2	GAB2/IO154RSB3	D7	IO14RSB0	G7	GND
В3	IO06RSB0	D8	IO19RSB0	G8	VCC
B4	IO09RSB0	D9	GBC0/IO30RSB0	G9	GND
B5	IO13RSB0	D10	GBB0/IO32RSB0	G10	GND
В6	IO10RSB0	D11	GBA0/IO34RSB0	G12	IO50RSB1
B7	IO12RSB0	D12	GND	G13	GCB1/IO54RSB1
В8	IO20RSB0	D13	GBC2/IO40RSB1	G14	GCC2/IO60RSB1
В9	IO23RSB0	D14	IO51RSB1	G15	GCA2/IO58RSB1
B10	IO25RSB0	D15	IO44RSB1	H1*	VCCPLF
B11	IO24RSB0	E1	IO142RSB3	H2	GFA1/IO136RSB3
B12	IO27RSB0	E2	IO149RSB3	Н3	GFB1/IO138RSB3
B13	IO37RSB1	E3	IO153RSB3	H4	NC
B14	IO46RSB1	E4	GAC2/IO152RSB3	H6	VCCIB3
B15	IO42RSB1	E12	IO43RSB1	H7	GND
C1	IO155RSB3	E13	IO49RSB1	H8	VCC
C2	GAA2/IO156RSB3	E14	GCC0/IO53RSB1	H9	GND
C3	GND	E15	GCB0/IO55RSB1	H10	VCCIB1
C4	GAA1/IO01RSB0	F1	IO141RSB3	H12	GCB2/IO59RSB1
C5	GAB1/IO03RSB0	F2	GFC1/IO140RSB3	H13	GCA0/IO57RSB1

Note: *Pin numbers G1 and H1 must be connected to ground because a PLL is not supported for AGLP060-CS/G201.

4-10 Revision 16



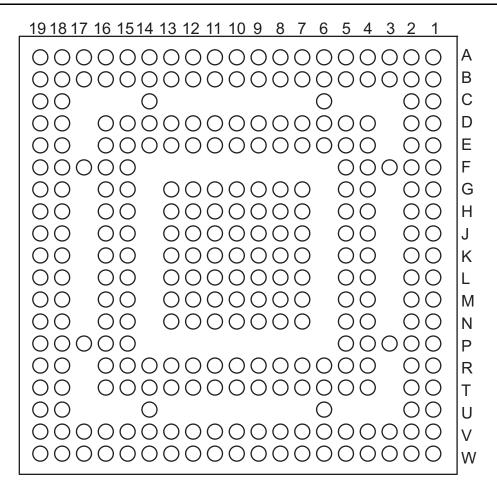
CS201		
AGLP060		
Pin Number	Function	
H14	IO64RSB1	
H15	IO62RSB1	
J1	GFA2/IO134RSB3	
J2	GFA0/IO135RSB3	
J3	GFB2/IO133RSB3	
J4	IO131RSB3	
J6	VCCIB3	
J7	GND	
J8	VCC	
J9	GND	
J10	VCCIB1	
J12	IO61RSB1	
J13	IO63RSB1	
J14	IO68RSB1	
J15	IO66RSB1	
K1	IO130RSB3	
K2	GFC2/IO132RSB3	
K3	IO127RSB3	
K4	IO129RSB3	
K6	GND	
K7	VCCIB2	
K8	VCCIB2	
K9	VCCIB2	
K10	VCCIB1	
K12	IO65RSB1	
K13	IO67RSB1	
K14	IO69RSB1	
K15	IO70RSB1	
L1	IO126RSB3	
L2	IO128RSB3	
L3	IO121RSB3	
L4	IO123RSB3	
L12	GDB1/IO74RSB1	
L13	GDC1/IO72RSB1	
L14	IO71RSB1	

CS201		
Pin Number	AGLP060 Function	
L15	GDC0/IO73RSB1	
M1	IO122RSB3	
M2	IO124RSB3	
M3	IO119RSB3	
M4	GND	
M5	IO125RSB3	
M6	IO98RSB2	
M7	IO96RSB2	
M8	IO91RSB2	
M9	IO89RSB2	
M10	IO82RSB2	
M11	GDA2/IO78RSB2	
M12	GND	
M13	GDA1/IO76RSB1	
M14	GDA0/IO77RSB1	
M15	GDB0/IO75RSB1	
N1	IO117RSB3	
N2	IO120RSB3	
N3	GND	
N4	GEB1/IO114RSB3	
N5	IO107RSB2	
N6	IO100RSB2	
N7	IO94RSB2	
N8	IO87RSB2	
N9	IO85RSB2	
N10	GDC2/IO80RSB2	
N11	IO90RSB2	
N12	IO84RSB2	
N13	GND	
N14	TDO	
N15	VJTAG	
P1	GEC0/IO115RSB3	
P2	GEC1/IO116RSB3	
P3	GEA0/IO111RSB3	
P4	GEA1/IO112RSB3	

2000		
CS201		
AGLP060 Function		
IO106RSB2		
IO105RSB2		
IO103RSB2		
IO99RSB2		
IO93RSB2		
IO92RSB2		
IO95RSB2		
IO86RSB2		
IO83RSB2		
VPUMP		
TRST		
IO118RSB3		
GEB0/IO113RSB3		
GEA2/IO110RSB2		
FF/GEB2/IO109RS B2		
GEC2/IO108RSB2		
IO102RSB2		
IO101RSB2		
IO104RSB2		
IO97RSB2		
IO88RSB2		
IO81RSB2		
GDB2/IO79RSB2		
TMS		
TDI		
TCK		



CS281



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at http://www.microsemi.com/soc/products/solutions/package/docs.aspx

4-12 Revision 16



CS281		
Pin Number	AGLP125 Function	
A1	GND	
A2	GAB0/IO02RSB0	
A3	GAC1/IO05RSB0	
A4	IO09RSB0	
A5	IO13RSB0	
A6	IO15RSB0	
A7	IO18RSB0	
A8	IO23RSB0	
A9	IO25RSB0	
A10	VCCIB0	
A11	IO33RSB0	
A12	IO41RSB0	
A13	IO43RSB0	
A14	IO46RSB0	
A15	IO55RSB0	
A16	IO56RSB0	
A17	GBC1/IO58RSB0	
A18	GBA0/IO61RSB0	
A19	GND	
B1	GAA2/IO211RSB3	
B2	VCCIB0	
В3	GAB1/IO03RSB0	
B4	GAC0/IO04RSB0	
B5	IO11RSB0	
B6	GND	
В7	IO21RSB0	
B8	IO22RSB0	
В9	IO28RSB0	
B10	IO32RSB0	
B11	IO36RSB0	
B12	IO39RSB0	
B13	IO42RSB0	
B14	GND	
B15	IO52RSB0	
B16	GBC0/IO57RSB0	
B17	GBA1/IO62RSB0	

CS281		
Pin Number	AGLP125 Function	
B18	VCCIB1	
B19	IO64RSB1	
C1	GAB2/IO209RSB3	
C2	IO210RSB3	
C6	IO12RSB0	
C14	IO47RSB0	
C18	IO54RSB0	
C19	GBB2/IO65RSB1	
D1	IO206RSB3	
D2	IO208RSB3	
D4	GAA0/IO00RSB0	
D5	GAA1/IO01RSB0	
D6	IO10RSB0	
D7	IO17RSB0	
D8	IO24RSB0	
D9	IO27RSB0	
D10	GND	
D11	IO31RSB0	
D12	IO40RSB0	
D13	IO49RSB0	
D14	IO45RSB0	
D15	GBB0/IO59RSB0	
D16	GBA2/IO63RSB1	
D18	GBC2/IO67RSB1	
D19	IO66RSB1	
E1	IO203RSB3	
E2	IO205RSB3	
E4	IO07RSB0	
E5	IO06RSB0	
E6	IO14RSB0	
E7	IO20RSB0	
E8	IO29RSB0	
E9	IO34RSB0	
E10	IO30RSB0	
E11	IO37RSB0	
E12	IO38RSB0	

CS281		
Pin Number AGLP125 Function		
E13	IO48RSB0	
E14	GBB1/IO60RSB0	
E15	IO53RSB0	
E16	IO69RSB1	
E18	IO68RSB1	
E19	IO71RSB1	
F1	IO198RSB3	
F2	GND	
F3	IO201RSB3	
F4	IO204RSB3	
F5	IO16RSB0	
F15	IO50RSB0	
F16	IO74RSB1	
F17	IO72RSB1	
F18	GND	
F19	IO73RSB1	
G1	IO195RSB3	
G2	IO200RSB3	
G4	IO202RSB3	
G5	IO08RSB0	
G7	GAC2/IO207RSB3	
G8	VCCIB0	
G9	IO26RSB0	
G10	IO35RSB0	
G11	IO44RSB0	
G12	VCCIB0	
G13	IO51RSB0	
G15	IO70RSB1	
G16	IO75RSB1	
G18	GCC0/IO80RSB1	
G19	GCB1/IO81RSB1	
H1	GFB0/IO191RSB3	
H2	IO196RSB3	
H4	GFC1/IO194RSB3	
H5	GFB1/IO192RSB3	
H7	VCCIB3	



CS281		
Pin Number	AGLP125 Function	
H8	VCC	
H9	VCCIB0	
H10	VCC	
H11	VCCIB0	
H12	VCC	
H13	VCCIB1	
H15	IO77RSB1	
H16	GCB0/IO82RSB1	
H18	GCA1/IO83RSB1	
H19	GCA2/IO85RSB1	
J1	VCOMPLF	
J2	GFA0/IO189RSB3	
J4	VCCPLF	
J5	GFC0/IO193RSB3	
J7	GFA2/IO188RSB3	
J8	VCCIB3	
J9	GND	
J10	GND	
J11	GND	
J12	VCCIB1	
J13	GCC1/IO79RSB1	
J15	GCA0/IO84RSB1	
J16	GCB2/IO86RSB1	
J18	IO76RSB1	
J19	IO78RSB1	
K1	VCCIB3	
K2	GFA1/IO190RSB3	
K4	GND	
K5	IO19RSB0	
K7	IO197RSB3	
K8	VCC	
K9	GND	
K10	GND	
K11	GND	
K12	VCC	
K13	GCC2/IO87RSB1	

CS281		
Pin Number	AGLP125 Function	
K15	IO89RSB1	
K16	GND	
K18	IO88RSB1	
K19	VCCIB1	
L1	GFB2/IO187RSB3	
L2	IO185RSB3	
L4	GFC2/IO186RSB3	
L5	IO184RSB3	
L7	IO199RSB3	
L8	VCCIB3	
L9	GND	
L10	GND	
L11	GND	
L12	VCCIB1	
L13	IO95RSB1	
L15	IO91RSB1	
L16	NC	
L18	IO90RSB1	
L19	NC	
M1	IO180RSB3	
M2	IO179RSB3	
M4	IO181RSB3	
M5	IO183RSB3	
M7	VCCIB3	
M8	VCC	
M9	VCCIB2	
M10	VCC	
M11	VCCIB2	
M12	VCC	
M13	VCCIB1	
M15	IO122RSB2	
M16	IO93RSB1	
M18	IO92RSB1	
M19	NC	
N1	IO178RSB3	
N2	IO175RSB3	
	101101000	

CS281				
Pin Number	AGLP125 Function			
N4	IO182RSB3			
N5	IO161RSB2			
N7	GEA2/IO164RSB2			
N8	VCCIB2			
N9	IO137RSB2			
N10	IO135RSB2			
N11	IO131RSB2			
N12	VCCIB2			
N13	VPUMP			
N15	IO117RSB2			
N16	IO96RSB1			
N18	IO98RSB1			
N19	IO94RSB1			
P1	IO174RSB3			
P2	GND			
P3	IO176RSB3			
P4	IO177RSB3			
P5	GEA0/IO165RSB3			
P15	IO111RSB2			
P16	IO108RSB2			
P17	GDC1/IO99RSB1			
P18	GND			
P19	IO97RSB1			
R1	IO173RSB3			
R2	IO172RSB3			
R4	GEC1/IO170RSB3			
R5	GEB1/IO168RSB3			
R6	IO154RSB2			
R7	IO149RSB2			
R8	IO146RSB2			
R9	IO138RSB2			
R10	IO134RSB2			
R11	IO132RSB2			
R12	IO130RSB2			
R13	IO118RSB2			
R14	IO112RSB2			

4-14 Revision 16

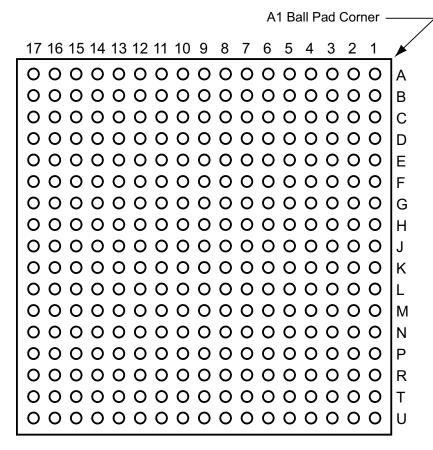


	CS281			
Pin Number AGLP125 Function				
R15	IO109RSB2			
R16	GDA1/IO103RSB1			
R18	GDB0/IO102RSB1			
R19	GDC0/IO100RSB1			
T1	IO171RSB3			
T2	GEC0/IO169RSB3			
T4	GEB0/IO167RSB3			
T5	IO157RSB2			
T6	IO158RSB2			
T7	IO148RSB2			
T8	IO145RSB2			
T9	IO143RSB2			
T10	GND			
T11	IO129RSB2			
T12	IO126RSB2			
T13	IO125RSB2			
T14	IO116RSB2			
T15	GDC2/IO107RSB2			
T16	TMS			
T18	VJTAG			
T19	GDB1/IO101RSB1			
U1	IO160RSB2			
U2	GEA1/IO166RSB3			
U6	IO151RSB2			
U14	IO121RSB2			
U18	TRST			
U19	GDA0/IO104RSB1			
V1	IO159RSB2			
V2	VCCIB3			
V3	GEC2/IO162RSB2			
V4	IO156RSB2			
V5	IO153RSB2			
V6	GND			
V7	IO144RSB2			
V8	IO141RSB2			
V9	IO140RSB2			

CS281				
Pin Number	AGLP125 Function			
V10	IO133RSB2			
V11	IO127RSB2			
V12	IO123RSB2			
V13	IO120RSB2			
V14	GND			
V15	IO113RSB2			
V16	GDA2/IO105RSB2			
V17	TDI			
V18	VCCIB2			
V19	TDO			
W1	GND			
W2	FF/GEB2/IO163RSB 2			
W3	IO155RSB2			
W4	IO152RSB2			
W5	IO150RSB2			
W6	IO147RSB2			
W7	IO142RSB2			
W8	IO139RSB2			
W9	IO136RSB2			
W10	VCCIB2			
W11	IO128RSB2			
W12	IO124RSB2			
W13	IO119RSB2			
W14	IO115RSB2			
W15	IO114RSB2			
W16	IO110RSB2			
W17	GDB2/IO106RSB2			
W18	TCK			
W19	GND			



CS289



Note: This is the bottom view of the package.

Note

For Package Manufacturing and Environmental information, visit the Resource Center at $\label{eq:http://www.microsemi.com/soc/products/solutions/package/docs.aspx .}$

4-16 Revision 16



CS289				
Pin Number	AGLP030 Function			
A1	IO03RSB0			
A2	NC			
А3	NC			
A4	GND			
A5	IO10RSB0			
A6	IO14RSB0			
A7	IO16RSB0			
A8	IO18RSB0			
A9	GND			
A10	IO23RSB0			
A11	IO27RSB0			
A12	NC			
A13	NC			
A14	GND			
A15	NC			
A16	NC			
A17	IO30RSB0			
B1	IO01RSB0			
B2	GND			
В3	NC			
B4	NC			
B5	IO07RSB0			
B6	NC			
В7	VCCIB0			
В8	IO17RSB0			
B9	IO19RSB0			
B10	IO24RSB0			
B11	IO28RSB0			
B12	VCCIB0			
B13	NC			
B14	NC			
B15	NC			
B16	IO31RSB0			
B17	GND			
C1	NC			
C2	IO00RSB0			
C3	IO04RSB0			
C3 IO04RSB0				

(CS289			
Pin Number	AGLP030 Function			
C4	NC			
C5	VCCIB0			
C6	IO09RSB0			
C7	IO13RSB0			
C8	IO15RSB0			
C9	IO21RSB0			
C10	GND			
C11	IO29RSB0			
C12	NC			
C13	NC			
C14	NC			
C15	GND			
C16	IO34RSB0			
C17	NC			
D1	NC			
D2	IO119RSB3			
D3	GND			
D4	IO02RSB0			
D5	NC			
D6	NC			
D7	NC			
D8	GND			
D9	IO20RSB0			
D10	IO25RSB0			
D11	NC			
D12	NC			
D13	GND			
D14	IO32RSB0			
D15	IO35RSB0			
D16	NC			
D17	NC			
E1	VCCIB3			
E2	IO114RSB3			
E3	IO115RSB3			
E4	IO118RSB3			
E5	IO05RSB0			
E6	NC			

•	CS289			
Pin Number	AGLP030 Function			
E7	IO06RSB0			
E8				
E9	IO11RSB0			
	IO22RSB0			
E10	IO26RSB0			
E11	VCCIB0			
E12 E13	NC IO33DSD0			
	IO33RSB0			
E14	IO36RSB1			
E15	IO38RSB1			
E16	VCCIB1			
E17	NC			
F1	IO111RSB3			
F2	NC			
F3	IO116RSB3			
F4	VCCIB3			
F5	IO117RSB3			
F6	NC			
F7	NC			
F8	IO08RSB0			
F9	IO12RSB0			
F10	NC			
F11	NC			
F12	NC			
F13	NC			
F14	GND			
F15	NC			
F16	IO37RSB1			
F17	IO41RSB1			
G1	IO110RSB3			
G2	GND			
G3	IO113RSB3			
G4	NC			
G5	NC			
G6	NC			
G7	GND			
G8	GND			
G9 VCC				



CS289				
	AGLP030			
Pin Number	Function			
G10	GND			
G11	GND			
G12	IO40RSB1			
G13	NC			
G14	IO39RSB1			
G15	IO44RSB1			
G16	NC			
G17	GND			
H1	NC			
H2	GEC0/IO108RSB3			
H3	NC			
H4	IO112RSB3			
H5	NC			
H6	IO109RSB3			
H7	GND			
H8	GND			
H9	GND			
H10	GND			
H11	GND			
H12	NC			
H13	NC			
H14	IO45RSB1			
H15	VCCIB1			
H16	GDB0/IO48RSB1			
H17	IO42RSB1			
J1	NC			
J2	GEA0/IO107RSB3			
J3	VCCIB3			
J4	IO105RSB3			
J5	NC			
J6	NC			
J7	VCC			
J8	GND			
J9	GND			
J10	GND			
J11	VCC			
J12	IO50RSB1			

CS289				
Pin Number	AGLP030 Function			
J13	IO43RSB1			
J14	IO51RSB1			
J15	IO52RSB1			
J16	GDC0/IO46RSB1			
J17	GDA0/IO47RSB1			
K1	GND			
K2	GEB0/IO106RSB3			
K3	IO102RSB3			
K4	IO104RSB3			
K5	IO99RSB3			
K6	NC			
K7	GND			
K8	GND			
K9	GND			
K10	GND			
K11	GND			
K12	NC			
K13	NC			
K14	NC			
K15	IO53RSB1			
K16	GND			
K17	IO49RSB1			
L1	IO103RSB3			
L2	IO101RSB3			
L3	NC			
L4	GND			
L5	NC			
L6	NC			
L7	GND			
L8	GND			
L9	VCC			
L10	GND			
L11	GND			
L12	IO58RSB1			
L13	IO54RSB1			
L14	VCCIB1			
L15 NC				

(CS289			
Pin Number	AGLP030 Function			
L16	NC			
L17	NC			
M1	NC			
M2	VCCIB3			
M3	IO100RSB3			
M4	IO98RSB3			
M5	IO93RSB3			
M6	IO97RSB3			
M7	NC			
M8	NC			
M9	IO71RSB2			
M10	NC			
M11	IO63RSB2			
M12	NC			
M13	IO57RSB1			
M14	NC			
M15	NC			
M16	NC			
M17	VCCIB1			
N1	NC			
N2	NC			
N3	IO95RSB3			
N4	IO96RSB3			
N5	GND			
N6	NC			
N7	IO85RSB2			
N8	IO79RSB2			
N9	IO77RSB2			
N10	VCCIB2			
N11	NC			
N12	NC			
N13	IO59RSB2			
N14	NC			
N15	GND			
N16	IO56RSB1			
N17	IO55RSB1			
P1 IO94RSB3				

4-18 Revision 16



(CS289			
AGLP030				
Pin Number	Function			
P2	NC			
P3	GND			
P4	NC			
P5	NC			
P6	IO87RSB2			
P7	IO80RSB2			
P8	GND			
P9	IO72RSB2			
P10	IO67RSB2			
P11	IO61RSB2			
P12	NC			
P13	VCCIB2			
P14	NC			
P15	IO60RSB2			
P16	IO62RSB2			
P17	VJTAG			
R1	GND			
R2	IO91RSB2			
R3	NC			
R4	NC			
R5	NC			
R6	VCCIB2			
R7	IO83RSB2			
R8	IO78RSB2			
R9	IO74RSB2			
R10	IO70RSB2			
R11	GND			
R12	NC			
R13	NC			
R14	NC			
R15	NC			
R16	TMS			
R17	TRST			
T1	IO92RSB3			
T2	IO89RSB2			
T3	NC			
T4	GND			

(CS289			
Pin Number	AGLP030 Function			
T5	NC			
T6	IO84RSB2			
T7	IO81RSB2			
Т8	IO76RSB2			
Т9	VCCIB2			
T10	IO69RSB2			
T11	IO65RSB2			
T12	IO64RSB2			
T13	NC			
T14	GND			
T15	NC			
T16	TDI			
T17	TDO			
U1	FF/IO90RSB2			
U2	GND			
U3	NC			
U4	IO88RSB2			
U5	IO86RSB2			
U6	IO82RSB2			
U7	GND			
U8	IO75RSB2			
U9	IO73RSB2			
U10	IO68RSB2			
U11	IO66RSB2			
U12	GND			
U13	NC			
U14	NC			
U15	NC			
U16	TCK			
U17 VPUMP				



CS289		CS289		CS289	
Pin Number	AGLP060 Function	Pin Number	AGLP060 Function	Pin Number	AGLP060 Function
A1	GAB1/IO03RSB0	C5	VCCIB0	E9	IO22RSB0
A2	NC	C6	IO09RSB0	E10	IO26RSB0
A3	NC	C7	IO13RSB0	E11	VCCIB0
A4	GND	C8	IO15RSB0	E12	NC
A5	IO10RSB0	C9	IO21RSB0	E13	GBB1/IO33RSB0
A6	IO14RSB0	C10	GND	E14	GBA2/IO36RSB1
A7	IO16RSB0	C11	IO29RSB0	E15	GBB2/IO38RSB1
A8	IO18RSB0	C12	NC	E16	VCCIB1
A9	GND	C13	NC	E17	IO44RSB1
A10	IO23RSB0	C14	NC	F1	GFC1/IO140RSB3
A11	IO27RSB0	C15	GND	F2	IO142RSB3
A12	NC	C16	GBA0/IO34RSB0	F3	IO149RSB3
A13	NC	C17	IO39RSB1	F4	VCCIB3
A14	GND	D1	IO150RSB3	F5	GAB2/IO154RSB3
A15	NC	D2	IO151RSB3	F6	IO153RSB3
A16	NC	D3	GND	F7	NC
A17	GBC0/IO30RSB0	D4	GAB0/IO02RSB0	F8	IO08RSB0
B1	GAA1/IO01RSB0	D5	NC	F9	IO12RSB0
B2	GND	D6	NC	F10	NC
В3	NC	D7	NC	F11	NC
B4	NC	D8	GND	F12	NC
B5	IO07RSB0	D9	IO20RSB0	F13	GBC2/IO40RSB1
В6	NC	D10	IO25RSB0	F14	GND
B7	VCCIB0	D11	NC	F15	IO43RSB1
B8	IO17RSB0	D12	NC	F16	IO46RSB1
B9	IO19RSB0	D13	GND	F17	IO45RSB1
B10	IO24RSB0	D14	GBB0/IO32RSB0	G1	GFC0/IO139RSB3
B11	IO28RSB0	D15	GBA1/IO35RSB0	G2	GND
B12	VCCIB0	D16	IO37RSB1	G3	IO144RSB3
B13	NC	D17	IO42RSB1	G4	IO145RSB3
B14	NC	E1	VCCIB3	G5	IO146RSB3
B15	NC	E2	IO147RSB3	G6	IO148RSB3
B16	GBC1/IO31RSB0	E3	GAC2/IO152RSB3	G7	GND
B17	GND	E4	GAA2/IO156RSB3	G8	GND
C1	IO155RSB3	E5	GAC1/IO05RSB0	G9	VCC
C2	GAA0/IO00RSB0	E6	NC	G10	GND
C3	GAC0/IO04RSB0	E7	IO06RSB0	G11	GND
C4	NC	E8	IO11RSB0	G12	IO48RSB1

4-20 Revision 16



CS289		CS289		CS289	
Pin Number	AGLP060 Function	Pin Number	AGLP060 Function	Pin Number	AGLP060 Function
G13	IO41RSB1	J17	GCA1/IO56RSB1	M4	IO122RSB3
G14	IO47RSB1	K1	GND	M5	GEB0/IO113RSB3
G15	IO49RSB1	K2	GFA0/IO135RSB3	M6	GEB1/IO114RSB3
G16	IO50RSB1	K3	GFB2/IO133RSB3	M7	NC
G17	GND	K4	IO128RSB3	M8	NC
H1	VCOMPLF	K5	IO123RSB3	M9	IO90RSB2
H2	GFB0/IO137RSB3	K6	IO125RSB3	M10	NC
H3	NC	K7	GND	M11	IO83RSB2
H4	IO141RSB3	K8	GND	M12	NC
H5	IO143RSB3	K9	GND	M13	GDA1/IO76RSB1
H6	GFB1/IO138RSB3	K10	GND	M14	GDA0/IO77RSB1
H7	GND	K11	GND	M15	IO71RSB1
H8	GND	K12	IO64RSB1	M16	IO69RSB1
H9	GND	K13	IO61RSB1	M17	VCCIB1
H10	GND	K14	IO66RSB1	N1	IO119RSB3
H11	GND	K15	IO65RSB1	N2	IO120RSB3
H12	GCC1/IO52RSB1	K16	GND	N3	GEC0/IO115RSB3
H13	IO51RSB1	K17	GCC2/IO60RSB1	N4	GEA0/IO111RSB3
H14	GCA0/IO57RSB1	L1	GFA2/IO134RSB3	N5	GND
H15	VCCIB1	L2	GFC2/IO132RSB3	N6	NC
H16	GCA2/IO58RSB1	L3	IO127RSB3	N7	IO104RSB2
H17	GCC0/IO53RSB1	L4	GND	N8	IO98RSB2
J1	VCCPLF	L5	IO121RSB3	N9	IO96RSB2
J2	GFA1/IO136RSB3	L6	GEC1/IO116RSB3	N10	VCCIB2
J3	VCCIB3	L7	GND	N11	NC
J4	IO131RSB3	L8	GND	N12	NC
J5	IO130RSB3	L9	VCC	N13	GDB2/IO79RSB2
J6	IO129RSB3	L10	GND	N14	NC
J7	VCC	L11	GND	N15	GND
J8	GND	L12	GDC1/IO72RSB1	N16	GDB0/IO75RSB1
J9	GND	L13	GDB1/IO74RSB1	N17	GDC0/IO73RSB1
J10	GND	L14	VCCIB1	P1	IO118RSB3
J11	VCC	L15	IO70RSB1	P2	IO117RSB3
J12	GCB2/IO59RSB1	L16	IO68RSB1	P3	GND
J13	GCB1/IO54RSB1	L17	IO67RSB1	P4	NC
J14	IO62RSB1	M1	IO126RSB3	P5	NC
J15	IO63RSB1	M2	VCCIB3	P6	IO106RSB2
J16	GCB0/IO55RSB1	M3	IO124RSB3	P7	IO99RSB2



00000			
CS289			
Pin Number	AGLP060 Function		
P8	GND		
P9	IO91RSB2		
P10	IO86RSB2		
P11	IO81RSB2		
P12	NC		
P13	VCCIB2		
P14	NC		
P15	GDA2/IO78RSB2		
P16	GDC2/IO80RSB2		
P17	VJTAG		
R1	GND		
R2	GEA2/IO110RSB2		
R3	NC		
R4	NC		
R5	NC		
R6	VCCIB2		
R7	IO102RSB2		
R8	IO97RSB2		
R9	IO93RSB2		
R10	IO89RSB2		
R11	GND		
R12	NC		
R13	NC		
R14	NC		
R15	NC		
R16	TMS		
R17	TRST		
T1	GEA1/IO112RSB3		
T2	GEC2/IO108RSB2		
T3	NC		
T4	GND		
T5	NC		
T6	IO103RSB2		
T7	IO100RSB2		
T8	IO95RSB2		
T9	VCCIB2		
T10 IO88RSB2			
T11 IO84RSB2			

CS289				
Pin Number	AGLP060 Function			
T12	IO82RSB2			
T13	NC			
T14	GND			
T15	NC			
T16	TDI			
T17	TDO			
U1	FF/GEB2/IO109RS B2			
U2	GND			
U3	NC			
U4	IO107RSB2			
U5	IO105RSB2			
U6	IO101RSB2			
U7	GND			
U8	IO94RSB2			
U9	IO92RSB2			
U10	IO87RSB2			
U11	IO85RSB2			
U12	GND			
U13	NC			
U14	NC			
U15	NC			
U16	TCK			
U17	VPUMP			

4-22 Revision 16



CS289				
Pin Number AGLP125 Function				
A1	GAB1/IO03RSB0			
A2	IO11RSB0			
A3	IO08RSB0			
A4	GND			
A5	IO19RSB0			
A6	IO24RSB0			
A7	IO26RSB0			
A8	IO30RSB0			
A9	GND			
A10	IO35RSB0			
A11	IO38RSB0			
A12	IO40RSB0			
A13	IO42RSB0			
A14	GND			
A15	IO48RSB0			
A16	IO54RSB0			
A17	GBC0/IO57RSB0			
B1	GAA1/IO01RSB0			
B2	GND			
В3	IO06RSB0			
B4	IO13RSB0			
B5	IO15RSB0			
B6	IO21RSB0			
В7	VCCIB0			
B8	IO28RSB0			
B9	IO31RSB0			
B10	IO37RSB0			
B11	IO39RSB0			
B12	VCCIB0			
B13	IO44RSB0			
B14	IO46RSB0			
B15	IO49RSB0			
B16	GBC1/IO58RSB0			
B17	GND			
C1	IO210RSB3			
C2	GAA0/IO00RSB0			
C3	GAC0/IO04RSB0			
C4	IO09RSB0			
	1			

CS289 Pin Number AGLP125 Function C5 VCCIB0 C6 IO17RSB0 C7 IO23RSB0 C8 IO27RSB0 C9 IO33RSB0 C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3 D2 IO205RSB3
C5 VCCIB0 C6 IO17RSB0 C7 IO23RSB0 C8 IO27RSB0 C9 IO33RSB0 C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C6 IO17RSB0 C7 IO23RSB0 C8 IO27RSB0 C9 IO33RSB0 C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C7 IO23RSB0 C8 IO27RSB0 C9 IO33RSB0 C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C8 IO27RSB0 C9 IO33RSB0 C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C9 IO33RSB0 C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C10 GND C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C11 IO43RSB0 C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C12 IO45RSB0 C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C13 IO50RSB0 C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C14 IO52RSB0 C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C15 GND C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C16 GBA0/IO61RSB0 C17 IO68RSB1 D1 IO204RSB3
C17 IO68RSB1 D1 IO204RSB3
D1 IO204RSB3
D2 IO20EDSB3
DZ IOZUJNOBO
D3 GND
D4 GAB0/IO02RSB0
D5 IO07RSB0
D6 IO10RSB0
D7 IO18RSB0
D8 GND
D9 IO34RSB0
D10 IO41RSB0
D11 IO47RSB0
D12 IO55RSB0
D13 GND
D14 GBB0/IO59RSB0
D15 GBA1/IO62RSB0
D16 IO66RSB1
D17 IO70RSB1
E1 VCCIB3
E2 IO200RSB3
E3 GAC2/IO207RSB3
E4 GAA2/IO211RSB3
E5 GAC1/IO05RSB0
E6 IO12RSB0
E7 IO16RSB0
E8 IO22RSB0

CS289			
Pin Number	AGLP125 Function		
E9	IO32RSB0		
E10	IO36RSB0		
E11	VCCIB0		
E12	IO56RSB0		
E13	GBB1/IO60RSB0		
E14	GBA2/IO63RSB1		
E15	GBB2/IO65RSB1		
E16	VCCIB1		
E17	IO73RSB1		
F1	GFC1/IO194RSB3		
F2	IO196RSB3		
F3	IO202RSB3		
F4	VCCIB3		
F5	GAB2/IO209RSB3		
F6	IO208RSB3		
F7	IO14RSB0		
F8	IO20RSB0		
F9	IO25RSB0		
F10	IO29RSB0		
F11	IO51RSB0		
F12	IO53RSB0		
F13	GBC2/IO67RSB1		
F14	GND		
F15	IO75RSB1		
F16	IO71RSB1		
F17	IO77RSB1		
G1	GFC0/IO193RSB3		
G2	GND		
G3	IO198RSB3		
G4	IO203RSB3		
G5	IO201RSB3		
G6	IO206RSB3		
G7	GND		
G8	GND		
G9	VCC		
G10	GND		
G11	GND		
G12	IO72RSB1		
<u> </u>	I.		



CS289			
Pin Number AGLP125 Function			
G13	IO64RSB1		
G14	IO69RSB1		
G15	IO78RSB1		
G16	IO76RSB1		
G17	GND		
H1	VCOMPLF		
H2	GFB0/IO191RSB3		
H3	IO195RSB3		
H4	IO197RSB3		
H5	IO199RSB3		
H6	GFB1/IO192RSB3		
H7	GND		
H8	GND		
H9	GND		
H10	GND		
H11	GND		
H12	GCC1/IO79RSB1		
H13	IO74RSB1		
H14	GCA0/IO84RSB1		
H15	VCCIB1		
H16	GCA2/IO85RSB1		
H17	GCC0/IO80RSB1		
J1	VCCPLF		
J2	GFA1/IO190RSB3		
J3	VCCIB3		
J4	IO185RSB3		
J5	IO183RSB3		
J6	IO181RSB3		
J7	VCC		
J8	GND		
J9	GND		
J10	GND		
J11	VCC		
J12	GCB2/IO86RSB1		
J13	GCB1/IO81RSB1		
J14	IO90RSB1		
J15	IO89RSB1		
J16	GCB0/IO82RSB1		
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CS289				
Pin Number AGLP125 Functio				
J17	GCA1/IO83RSB1			
K1	GND			
K2	GFA0/IO189RSB3			
K3	GFB2/IO187RSB3			
K4	IO179RSB3			
K5	IO175RSB3			
K6	IO177RSB3			
K7	GND			
K8	GND			
K9	GND			
K10	GND			
K11	GND			
K12	IO88RSB1			
K13	IO94RSB1			
K14	IO95RSB1			
K15	IO93RSB1			
K16	GND			
K17	GCC2/IO87RSB1			
L1	GFA2/IO188RSB3			
L2	GFC2/IO186RSB3			
L3	IO182RSB3			
L4	GND			
L5	IO173RSB3			
L6	GEC1/IO170RSB3			
L7	GND			
L8	GND			
L9	VCC			
L10	GND			
L11	GND			
L12	GDC1/IO99RSB1			
L13	GDB1/IO101RSB1			
L14	VCCIB1			
L15	IO98RSB1			
L16	IO92RSB1			
L17	IO91RSB1			
M1	IO184RSB3			
M2	VCCIB3			
M3 IO176RSB3				

CS289			
Pin Number	AGLP125 Function		
M4	IO172RSB3		
M5	GEB0/IO167RSB3		
M6	GEB1/IO168RSB3		
M7	IO159RSB2		
M8	IO161RSB2		
M9	IO135RSB2		
M10	IO128RSB2		
M11	IO121RSB2		
M12	IO113RSB2		
M13	GDA1/IO103RSB1		
M14	GDA0/IO104RSB1		
M15	IO97RSB1		
M16	IO96RSB1		
M17	VCCIB1		
N1	IO180RSB3		
N2	IO178RSB3		
N3	GEC0/IO169RSB3		
N4	GEA0/IO165RSB3		
N5	GND		
N6	IO156RSB2		
N7	IO148RSB2		
N8	IO144RSB2		
N9	IO137RSB2		
N10	VCCIB2		
N11	IO119RSB2		
N12	IO111RSB2		
N13	GDB2/IO106RSB2		
N14	IO109RSB2		
N15	GND		
N16	GDB0/IO102RSB1		
N17	GDC0/IO100RSB1		
P1	IO174RSB3		
P2	IO171RSB3		
P3	GND		
P4	IO160RSB2		
P5	IO157RSB2		
P6	IO154RSB2		
P7	IO152RSB2		

4-24 Revision 16



CS289			
Pin Number	AGLP125 Function		
P8	GND		
P9	IO132RSB2		
P10	IO125RSB2		
P11	IO126RSB2		
P12	IO12BRSB2		
P13	VCCIB2		
P14	IO108RSB2		
P15	GDA2/IO105RSB2		
P16	GDC2/IO107RSB2		
P17	VJTAG		
R1	GND		
R2	GEA2/IO164RSB2		
R3	IO158RSB2		
R4	IO155RSB2		
R5	IO150RSB2		
R6	VCCIB2		
R7	IO145RSB2		
R8	IO141RSB2		
R9	IO134RSB2		
R10	IO130RSB2		
R11	GND		
R12	IO118RSB2		
R13	IO116RSB2		
R14	IO114RSB2		
R15	IO110RSB2		
R16	TMS		
R17	TRST		
T1	GEA1/IO166RSB3		
T2	GEC2/IO162RSB2		
Т3	IO153RSB2		
T4	GND		
T5	IO147RSB2		
T6	IO143RSB2		
T7	IO140RSB2		
T8	IO139RSB2		
T9	VCCIB2		
T10	IO131RSB2		
T11	IO127RSB2		

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CS289				
Pin Number	AGLP125 Function			
T12	IO124RSB2			
T13	IO122RSB2			
T14	GND			
T15	IO115RSB2			
T16	TDI			
T17	TDO			
U1	FF/GEB2/IO163RS B2			
U2	GND			
U3	IO151RSB2			
U4	IO149RSB2			
U5	IO146RSB2			
U6	IO142RSB2			
U7	GND			
U8	IO138RSB2			
U9	IO136RSB2			
U10	IO133RSB2			
U11	IO129RSB2			
U12	GND			
U13	IO123RSB2			
U14	IO120RSB2			
U15	IO117RSB2			
U16	TCK			
U17	VPUMP			



5 - Datasheet Information

List of Changes

The following table lists critical changes that were made in each revision of the IGLOO PLUS datasheet.

Revision	Changes	Page
Revision 16 (December 2012)	The "IGLOO PLUS Ordering Information" section has been updated to mention "Y" as "Blank" mentioning "Device Does Not Include License to Implement IP Based on the Cryptography Research, Inc. (CRI) Patent Portfolio" (SAR 43175).	III
	The note in Table 2-90 • IGLOO PLUS CCC/PLL Specification and Table 2-91 • IGLOO PLUS CCC/PLL Specification referring the reader to SmartGen was revised to refer instead to the online help associated with the core (SAR 42566).	2-61, 2-62
	Live at Power-Up (LAPU) has been replaced with 'Instant On'.	NA
Revision 15 (October 2012)	Values updated for IGLOO PLUS V2 or V5 Devices, 1.5 V Core Supply Voltage in Table 2-15 • Different Components Contributing to Dynamic Power Consumption in IGLOO PLUS Devices and for IGLOO PLUS V2 Devices, 1.2 V Core Supply Voltage in Table 2-17 • Different Components Contributing to Dynamic Power Consumption in IGLOO PLUS Devices (SAR 31988). Also added a new Note to the two tables.	2-10, 2-11
	Libero Integrated Design Environment (IDE) was changed to Libero System-on-Chip (SoC) throughout the document (SAR 40277).	N/A
Revision 14 (September 2012)	The "Security" section was modified to clarify that Microsemi does not support readback of programmed data.	1-2
Revision 13 (June 2012)	Figure 2-30 • FIFO Read and Figure 2-31 • FIFO Write have been added (SAR 34843).	2-73
	Updated the terminology used in Timing Characteristics in the following tables: Table 2-96 • FIFO and Table 2-97 • FIFO (SAR 38236).	2-76
	The following sentence was removed from the "VMVx I/O Supply Voltage (quiet)" section in the "Pin Descriptions and Packaging" section: "Within the package, the VMV plane is decoupled from the simultaneous switching noise originating from the output buffer VCCI domain" and replaced with "Within the package, the VMV plane biases the input stage of the I/Os in the I/O banks" (SAR 38320). The datasheet mentions that "VMV pins must be connected to the corresponding VCCI pins" for an ESD enhancement.	3-1
Revision 12 (March 2012)	The "In-System Programming (ISP) and Security" section and "Security" section were revised to clarify that although no existing security measures can give an absolute guarantee, Microsemi FPGAs implement the best security available in the industry (SAR 34664).	I, 1-2
	The Y security option and Licensed DPA Logo were added to the "IGLOO PLUS Ordering Information" section. The trademarked Licensed DPA Logo identifies that a product is covered by a DPA counter-measures license from Cryptography Research (SAR 34724).	III
	The "Specifying I/O States During Programming" section is new (SAR 34695).	1-7
	The following sentence was removed from the "Advanced Architecture" section:	1-3
	"In addition, extensive on-chip programming circuitry allows for rapid, single-voltage (3.3 V) programming of IGLOO PLUS devices via an IEEE 1532 JTAG interface" (SAR 34684).	



Revision	Changes	Page
Revision 12 (continued)	The reference to guidelines for global spines and VersaTile rows, given in the "Global Clock Contribution—PCLOCK" section, was corrected to the "Spine Architecture" section of the Global Resources chapter in the <i>IGLOO PLUS FPGA Fabric User's Guide</i> (SAR 34733).	2-12
	$t_{\mbox{\scriptsize DOUT}}$ was corrected to $t_{\mbox{\scriptsize DIN}}$ in Figure 2-4 • Input Buffer Timing Model and Delays (example) (SAR 37107).	2-16
	The AC Loading figures in the "Single-Ended I/O Characteristics" section were updated to match tables in the "Summary of I/O Timing Characteristics – Default I/O Software Settings" section (SAR 34887).	2-27
	Minimum pulse width High and Low values were added to the tables in the "Global Tree Timing Characteristics" section. The maximum frequency for global clock parameter was removed from these tables because a frequency on the global is only an indication of what the global network can do. There are other limiters such as the SRAM, I/Os, and PLL. SmartTime software should be used to determine the design frequency (SAR 36963).	2-58
	Table 2-90 • IGLOO PLUS CCC/PLL Specification and Table 2-91 • IGLOO PLUS CCC/PLL Specification were updated. A note was added to both tables indicating that when the CCC/PLL core is generated by Microsemi core generator software, not all delay values of the specified delay increments are available (SAR 34820).	2-61, 2-62
	The value for serial clock was missing from these tables and has been restored. The value and units for input cycle-to-cycle jitter were incorrect and have been restored. The note to Table 2-90 • IGLOO PLUS CCC/PLL Specification giving specifications for which measurements done was corrected from VCC/VCCPLL = 1.14 V to VCC/VCCPLL = 1.425 V. The Delay Range in Block: Programmable Delay 2 value in Table 2-91 • IGLOO PLUS CCC/PLL Specification was corrected from 0.025 to 0.863 (SAR 37058).	
	Figure 2-28 • Write Access after Read onto Same Address was deleted. Reference was made to a new application note, <i>Simultaneous Read-Write Operations in Dual-Port SRAM for Flash-Based cSoCs and FPGAs</i> , which covers these cases in detail (SAR 34868).	2-65,
	The port names in the SRAM "Timing Waveforms", SRAM "Timing Characteristics" tables, Figure 2-32 • FIFO Reset, and the FIFO "Timing Characteristics" tables were revised to ensure consistency with the software names (SAR 35748).	2-68, 2-74, 2-76
	The "Pin Descriptions and Packaging" chapter has been added (SAR 34769).	3-1
	Package names used in the "Package Pin Assignments" section were revised to match standards given in <i>Package Mechanical Drawings</i> (SAR 34769).	4-1
Revision 11 (July 2010)	The versioning system for datasheets has been changed. Datasheets are assigned a revision number that increments each time the datasheet is revised. The "IGLOO PLUS Device Status" table indicates the status for each device in the family.	N/A
	The "Reprogrammable Flash Technology" section was revised to add "250 MHz (1.5 V systems) and 160 MHz (1.2 V systems) System Performance."	I
	The "I/Os with Advanced I/O Standards" section was revised to add definitions for hot-swap and cold-sparing.	1-6
	Conditional statements regarding hot insertion were removed from the description of VI in Table 2-1 • Absolute Maximum Ratings, since all IGLOO PLUS devices are hot insertion enabled.	2-1

5-2 Revision 16



Revision	Changes	Page
Revision 11 (continued)	Table 2-2 • Recommended Operating Conditions1,2 was revised. 1.2 V DC wide range supply voltage and 3.3 V wide range supply voltage (SAR 26270) were added for VCCI. VJTAG DC Voltage was revised (SAR 24052). The value range for VPUMP programming voltage for operation was changed from "0 to 3.45" to "0 to 3.6" (SAR 25220).	2-2
	Table 2-6 • Temperature and Voltage Derating Factors for Timing Delays (normalized to TJ = 70°C, VCC = 1.425 V) and Table 2-7 • Temperature and Voltage Derating Factors for Timing Delays (normalized to TJ = 70°C, VCC = 1.14 V) were revised.	2-6, 2-7
	Table 2-8 • Power Supply State per Mode is new.	2-7
	The tables in the "Quiescent Supply Current" section were updated (SARs 24882 and 24112). Some of the table notes were changed or deleted.	2-7
	VIH maximum values in tables were updated as needed to 3.6 V (SARs 20990, 79370).	N/A
	The values in the following tables were updated. 3.3 V LVCMOS and 1.2 V LVCMOS wide range were added to the tables where applicable.	
	Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings	2-9
	Table 2-14 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings1	2-9
	Table 2-21 • Summary of Maximum and Minimum DC Input and Output Levels Applicable to Commercial and Industrial Conditions—Software Default Settings	2-19 2-20
	Table 2-22 • Summary of Maximum and Minimum DC Input Levels	2-21
	Table 2-23 • Summary of AC Measuring Points Table 2-25 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade, Commercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V	2-22
	Table 2-26 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade Commercial-Case Conditions: TJ = 70° C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V	2-23
	Table 2-28 • I/O Output Buffer Maximum Resistances 1	2-24
	A table note was added to Table 2-16 • Different Components Contributing to the	2-11,
	Static Power Consumption in IGLOO PLUS Devices and Table 2-18 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices stating the value for PDC4 is the minimum contribution of the PLL when operating at lowest frequency.	2-12
	Table 2-29 • I/O Weak Pull-Up/Pull-Down Resistances was revised, including addition of 3.3 V and 1.2 V LVCMOS wide range.	2-25
	The notes defining $R_{\text{WEAK PULL-UP-MAX}}$ and $R_{\text{WEAK PULLDOWN-MAX}}$ were revised (SAR 21348).	
	Table 2-30 • I/O Short Currents IOSH/IOSL was revised to include data for 3.3 V and 1.2 V LVCMOS wide range (SAR 79353 and SAR 79366).	2-25
	Table 2-31 • Duration of Short Circuit Event before Failure was revised to change the maximum temperature from 110°C to 100°C, with an example of six months instead of three months (SAR 26259).	2-26



Revision	Changes	Page
Revision 11 (continued)	The tables in the "Single-Ended I/O Characteristics" section were updated. Notes clarifying IIL and IIH were added.	2-27
	Tables for 3.3 V LVCMOS and 1.2 V LVCMOS wide range were added (SAR 79370, SAR 79353, and SAR 79366).	
	Notes in the wide range tables state that the minimum drive strength for any LVCMOS 3.3 V (or LVCMOS 1.2 V) software configuration when run in wide range is $\pm 100~\mu A$. Drive strength displayed in the software is supported for normal range only. For a detailed I/V curve, refer to the IBIS models (SAR 25700).	
	The following sentence was deleted from the "2.5 V LVCMOS" section: It uses a 5 V-tolerant input buffer and push-pull output buffer (SAR 24916).	2-32
	The tables in the "Input Register" section, "Output Register" section, and "Output Enable Register" section were updated. The tables in the "VersaTile Characteristics" section were updated.	2-45 through 2-56
	The following tables were updated in the "Global Tree Timing Characteristics" section:	2-58
	Table 2-85 • AGLP060 Global Resource (1.5 V)	
	Table 2-86 • AGLP125 Global Resource (1.5 V)	
	Table 2-88 • AGLP060 Global Resource (1.2 V)	
	Table 2-90 • IGLOO PLUS CCC/PLL Specification and Table 2-91 • IGLOO PLUS CCC/PLL Specification were revised (SAR 79388). VCO output jitter and maximum peak-to-peak jitter data were changed. Three notes were added to the table in connection with these changes.	2-61
	Figure 2-28 • Write Access after Write onto Same Address and Figure 2-29 • Write Access after Read onto Same Address were deleted.	N/A
	The tables in the "SRAM", "FIFO" and "Embedded FlashROM Characteristics" sections were updated.	2-68, 2-78

5-4 Revision 16



Revision	Changes	Page
Revision 10 (Apr 2009) Product Brief v1.5 DC and Switching Characteristics Advance v0.5	The –F speed grade is no longer offered for IGLOO PLUS devices. References to it have been removed from the document. The speed grade column and note regarding –F speed grade were removed from "IGLOO PLUS Ordering Information". The "Speed Grade and Temperature Grade Matrix" section was removed.	III, IV
Revision 9 (Feb 2009) Product Brief v1.4	The "Advanced I/O" section was revised to add two bullets regarding support of wide range power supply voltage.	I
	The "I/Os with Advanced I/O Standards" section was revised to add 3.0 V wide range to the list of supported voltages. The "Wide Range I/O Support" section is new.	1-7
Revision 8 (Jan 2009) Packaging v1.5	The "CS201" pin table was revised to add a note regarding pins G1 and H1.	4-8
Revision 7 (Dec 2008) Product Brief v1.3	A note was added to IGLOO PLUS Devices: "AGLP060 in CS201 does not support the PLL."	I
	Table 2 • IGLOO PLUS FPGAs Package Size Dimensions was updated to change the nominal size of VQ176 from 100 to 400 mm ² .	II
Revision 6 (Oct 2008)	Data was revised significantly in the following tables:	2-22,
DC and Switching Characteristics Advance v0.4	Table 2-25 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade, Commercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.425 V, Worst-Case VCCI = 3.0 V	2-33
	Table 2-26 • Summary of I/O Timing Characteristics—Software Default Settings, STD Speed Grade Commercial-Case Conditions: TJ = 70°C, Worst-Case VCC = 1.14 V, Worst-Case VCCI = 3.0 V	
	Table 2-50 • 2.5 LVCMOS Low Slew – Applies to 1.2 V DC Core Voltage	
	Table 2-51 • 2.5 V LVCMOS High Slew – Applies to 1.2 V DC Core Voltage	
Revision 5 (Aug 2008) Product Brief v1.2	The VQ128 and VQ176 packages were added to Table 1 • IGLOO PLUS Product Family, the "I/Os Per Package 1" table, Table 2 • IGLOO PLUS FPGAs Package Size Dimensions, "IGLOO PLUS Ordering Information", and the "Temperature Grade Offerings" table.	I to IV
Packaging v1.4	The "VQ128" package drawing and pin table are new.	4-2
	The "VQ176" package drawing and pin table are new.	4-5
Revision 4 (Jul 2008) Product Brief v1.1 DC and Switching Characteristics Advance v0.3	As a result of the Libero IDE v8.4 release, Actel now offers a wide range of core voltage support. The document was updated to change 1.2 V / 1.5 V to 1.2 V to 1.5 V.	N/A
Revision 3 (Jun 2008) DC and Switching Characteristics Advance v0.2	Tables have been updated to reflect default values in the software. The default I/O capacitance is 5 pF. Tables have been updated to include the LVCMOS 1.2 V I/O set.	N/A
	Table note 3 was updated in Table 2-2 • Recommended Operating Conditions1,2 to add the sentence, "VCCI should be at the same voltage within a given I/O bank." References to table notes 5, 6, 7, and 8 were added. Reference to table note 3 was removed from VPUMP Operation and placed next to VCC.	2-2
	Table 2-4 • Overshoot and Undershoot Limits 1 was revised to remove "as measured on quiet I/Os" from the title. Table note 2 was revised to remove "estimated SSO density over cycles." Table note 3 was deleted.	2-3



Revision	Changes	Page
Revision 3 (continued)	The table note for Table 2-9 • Quiescent Supply Current (IDD) Characteristics, IGLOO PLUS Flash*Freeze Mode* to remove the sentence stating that values do not include I/O static contribution.	2-7
	The table note for Table 2-10 • Quiescent Supply Current (IDD) Characteristics, IGLOO PLUS Sleep Mode* was updated to remove VJTAG and VCCI and the statement that values do not include I/O static contribution.	2-7
	The table note for Table 2-11 • Quiescent Supply Current (IDD) Characteristics, IGLOO PLUS Shutdown Mode was updated to remove the statement that values do not include I/O static contribution.	2-8
	Note 2 of Table 2-12 • Quiescent Supply Current (IDD), No IGLOO PLUS Flash*Freeze Mode 1 was updated to include VCCPLL. Table note 4 was deleted.	2-8
	Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings and Table 2-14 • Summary of I/O Output Buffer Power (per pin) – Default I/O Software Settings1 were updated to remove static power. The table notes were updated to reflect that power was measured on VCC _I . Table note 2 was added to Table 2-13 • Summary of I/O Input Buffer Power (per pin) – Default I/O Software Settings.	2-9, 2-9
	Table 2-16 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices and Table 2-18 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices were updated to change the definition for P_{DC5} from bank static power to bank quiescent power. Table subtitles were added for Table 2-16 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices, Table 2-17 • Different Components Contributing to Dynamic Power Consumption in IGLOO PLUS Devices, and Table 2-18 • Different Components Contributing to the Static Power Consumption in IGLOO PLUS Devices.	2-11, 2-12
	The "Total Static Power Consumption—PSTAT" section was revised.	2-12
1	Table 2-32 • Schmitt Trigger Input Hysteresis is new.	2-26
Packaging v1.3	The "CS281" package drawing is new.	4-13
1	The "CS281" table for the AGLP125 device is new.	4-13
Revision 3 (continued)	The "CS289" package drawing was incorrect. The graphic was showing the CS281 mechanical drawing and not the CS289 mechanical drawing. This has now been corrected.	4-17
Revision 2 (Jun 2008) Packaging v1.2	The "CS289" table for the AGLP030 device is new.	4-17
Revision 1 (Jun 2008)	The "CS289" table for the AGLP060 device is new.	4-20
Packaging v1.1	The "CS289" table for the AGLP125 device is new.	4-23

5-6 Revision 16



Datasheet Categories

Categories

In order to provide the latest information to designers, some datasheet parameters are published before data has been fully characterized from silicon devices. The data provided for a given device, as highlighted in the "IGLOO PLUS Device" table on page II, is designated as either "Product Brief," "Advance," "Preliminary," or "Production." The definitions of these categories are as follows:

Product Brief

The product brief is a summarized version of a datasheet (advance or production) and contains general product information. This document gives an overview of specific device and family information.

Advance

This version contains initial estimated information based on simulation, other products, devices, or speed grades. This information can be used as estimates, but not for production. This label only applies to the DC and Switching Characteristics chapter of the datasheet and will only be used when the data has not been fully characterized.

Preliminary

The datasheet contains information based on simulation and/or initial characterization. The information is believed to be correct, but changes are possible.

Production

This version contains information that is considered to be final.

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